

# Intel® Core™2 Duo Mobile Processor, Mobile Intel® 965 Express Chipset Family and ICH8M I/O Controller Hub

Schematics

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*December 2006*

*Revision 1.5*

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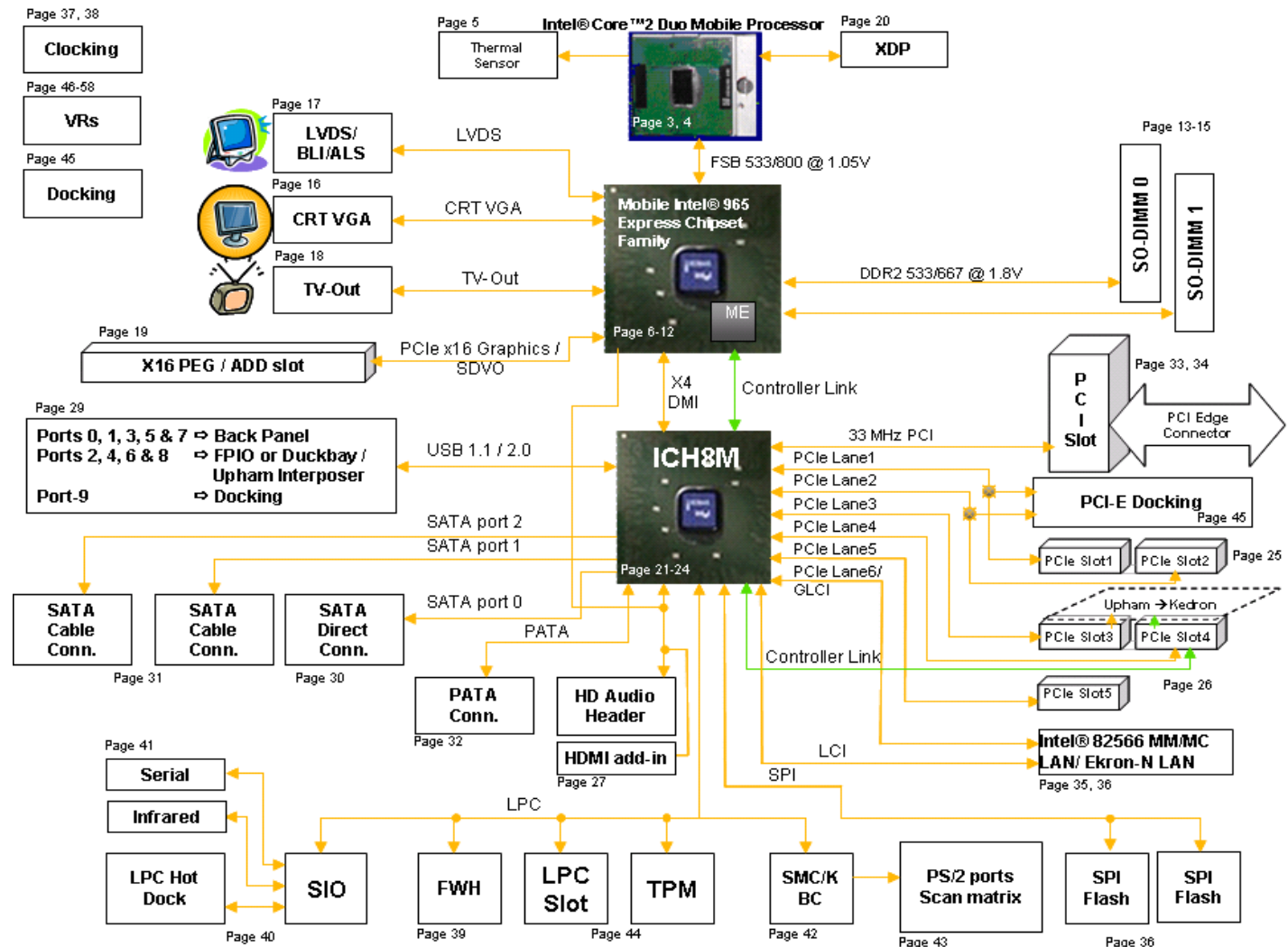
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## Customer Reference Board

Rev 1.5

### Table of Contents

Page	Description
1a	This Page
1b	Revision History
2	NOTES
3	Intel® Core™2 Duo Mobile Processor (1 of 2)
4	Intel® Core™2 Duo Mobile Processor (2 of 2)
5	CPU Thermal Sensor & Fan
6	Mobile Intel® 965 Express Chipset Family (1 OF 6)
7	Mobile Intel® 965 Express Chipset Family (2 OF 6)
8	Mobile Intel® 965 Express Chipset Family (3 OF 6)
9	Mobile Intel® 965 Express Chipset Family (4 OF 6)
10	Mobile Intel® 965 Express Chipset Family (5 OF 6)
11	Mobile Intel® 965 Express Chipset Family (6 OF 6)
12	Mobile Intel® 965 Express Chipset Family Strapping
13	DDR2 SODIMM 0
14	DDR2 SODIMM 1
15	DDR2 TERMINATION AND THERMAL SENSOR
16	CRT
17	LVDS
18	TV
19	PCI-E GRAPHICS
20	XDP
21	ICH8M (1 of 4)
22	ICH8M (2 of 4)
23	ICH8M (3 of 4)
24	ICH8M (4 of 4)
25	PCI-E Slots (1 & 2)
26	PCI-E Slots (3,4 & 5)
27	High Definition Audio
28	HDA Power Supply
29	USB 1.1/2.0
30	SATA (1 of 3)
31	SATA (2 and 3 of 3)
32	IDE
33	PCI Slot 3
34	PCI Edge Connector (Goldfinger)
35	Intel® 82566 MM/MC LAN & Ekron-N Option
36	LAN Docking and SPI
37	CK505
38	DB800 & Buffers
39	FWH and I/O Port Expander
40	SIO
41	Legacy Support
42	H8 2104 KBC
43	PS2
44	LPC Slot, TPM Header, and EMA
45	Docking
46	TPS51120 System Power
47	DDR VR
48	Crestline VR
49	Graphics Core VR
50	DDR2 VREF
51	System Charger VR
52	IMVP-6
53	IMVP-6 Core VR
54	CPU Decoupling
55	Start Up Sequence
56	DISCHARGE CIRCUITS
57	Sleep control
58	POWER SEQUENCING TIMING BLOCK DIAGRAM



<b>Matanzas</b>		Intel Confidential
Title TITLE PAGE		
Size A	Document Number NDA	Rev 1.5
Date:	Thursday, November 30, 2006	Sheet 1a of 58

# Rev 1.5 (Changes from Rev 1.301)

Note: Revision 1.5 of the CRB Schematics is based on Fab 3 of Matanzas boards.

Page:3  
-The PROCHOT signal pull up value changed from 75 Ohms to 1K Ohms,1%. This fixes the PROCHOT# failure when driven by thermal sensor on the CRB.

Page:7  
-Updated Crestline symbol to indicate LVDSB\_DATA\_3 and LVDSB\_DATA#3 pins to support Dual Channel 24-bit LVDS Support.

Page:10  
-Crestline CRT/TV QDAC Filter Change (Refer to WW44 Santa Rosa MOW)  
-Changed FB5T1 to R5U20 Resistor 100 ohms, 5%,1/16W  
-Changed no-stuff R5T5 with C5T20 1.0uF,20%

Page:13  
-Corrected net name RSVD-M\_A\_A14 to M\_A\_A14

Page:14  
-Corrected net name RSVD-M\_B\_A14 to M\_B\_A14

Page:17  
-LVDS Connector updated to indicate LVDSB\_DATA\_3 and LVDSB\_DATA#3 pins

Page:21  
-Added a note that ICH8M Internal VR should not be disabled.

Page:22  
-Added strapping configuration information for PCIe x2

Page:23  
-Removed the pull-up to +V3.3S circuit on CRB\_SV\_DET. Customer platforms should pull-up CRB\_SV\_DET (if used) to +V3.3A via 10k Ohm resistor.

Page 31:  
-Clarified SATA Port 1 impact with J7J2 No Shunt

Page:36  
-Auto Connect Battery Saver Energy Detect Circuit Update: R5A3 changed from 3.92KOhms to 1.87KOhms. This is an update to the recommendation in the WW44 Santa Rosa MOW.

Page:41  
If SPI Descriptor Lock is removed, a 1k Ohms resistor is required between pins 9 and 7 of J8F1 to avoid damage to I/Os.

Page:44  
-ME\_SMC\_ALERT# should be pulled-up to +V3.3A instead of +V3.3M. On the CRB,R6G17 is made no-stuff & the internal pull up on the H8 is enabled. Customer platforms need to pull this signal to +V3.3A.  
-Added note on ME\_SMC\_ALERT# assertion/de-assertion indication

Page:48  
-499 Ohms value of R5G10 causes +V1.05S to be +V1.09S. R5G10 changed from 499Ohms to 0Ohms.

Page:49  
-R3G13, R3G12, R3G11, R3G9, R3G10 stuff with 20K resistors  
-R3G14 stuff with 30K resistor  
-R2G16 value changed to 100K resistor  
-J2G1 - Removed jumper shunts. No shunts to be installed.  
-The pull up on GVR\_VID3 (R3G10) and GVR\_VR\_EN (R3G14) should be connected to +V3.3S instead of +V3.3  
-Modified sheet Graphics Controller symbol

Page:52 & 53  
-Modified sheet IMVP Controller and FET Symbols

Page:55  
-J3G1 Pin1 and 2 should be shorted for ME support in G3 state.  
-Corrected net name XDP\_DBRESET#\_R to XDP\_DBRESET#

Title		
Revision History		
Size A	Document Number NDA	Rev 1.5
Date:	Friday, December 08, 2006	Sheet 1b of 58

# SANTA ROSA CUSTOMER REFERENCE PLATFORM

## SCHEMATIC ANNOTATIONS AND BOARD INFORMATION

POWER PLANE	VOLTAGE	ACTIVE IN	DESCRIPTION
+VBATA	9V-12.5V	S0/M0, (S3-S5)/M1, (S3-S5)/M-off	Battery Rail in Mobile Power Mode
+VBAT	9V-12.5V	S0/M0, (S3-S5)/M1, (S3-S5)/M-off	Battery Rail in Mobile Power Mode
+VBATS	9V-12.5V	S0/M0	Battery Rail in Mobile Power Mode
+V12S	12V	S0/M0	Only on in DT Power Mode
-V12A	-12V	S0/M0, (S3-S5)/M1, (S3-S5)/M-off	Only on in DT Power Mode
-V12S	-12V	S0/M0	Only on in DT Power Mode
+V5A	5V	S0/M0, (S3-S5)/M1, (S3-S5)/M-off	
+V5	5V	S0/M0, S3/M1, S3/M-off	
+V5S	5V	S0/M0	
+V3.3A	3.3V	S0/M0, (S3-S5)/M1, (S3-S5)/M-off	
+V3.3M	3.3V	S0/M0, (S3-S5)/M1, S3/M-off w/WOL_EN	LAN
+V3.3M_CK505	3.3V	S0/M0, (S3-S5)/M1	clock, MCH
+V3.3	3.3V	S0/M0, S3/M1, S3/M-off	
+V3.3S	3.3V	S0/M0	
+V1.8	1.8V	S0/M0, (S3-S5)/M1, S3/M-off	DDR core
+V1.5S	1.5V	S0/M0	
+V1.25M	1.25V	S0/M0, (S3-S5)/M1	
+V1.25S	1.25V	S0/M0	
+V1.05M	1.05V	S0/M0, (S3-S5)/M1	
+V1.05S	1.05V	S0/M0	GMCH, ICH core, and FSB rail
+V0.9	0.9V	S0/M0, (S3-S5)/M1, S3/M-off	DDR command & control pull up.
+VCC_CORE	0.700V-1.77V	S0/M0	CPU core rail
+VCC_GFXCORE	0.7V-1.25V	S0/M0	GMCH Graphics core rail

Device	Address	Hex	Bus
Clock Generator	1101 001x	D2	SMB_I2C_M3
TBR00 Clock Buffer	1101 110x	DC	SMB_I2C_M3
SO-DIMM0	1010 000x	A0	SMB_I2C_M2
SO-DIMM1	1010 010x	A4	SMB_I2C_M2
SO-DIMM0 Thermal Sensor	0011 000x	30	SMB_I2C_M2
SO-DIMM1 Thermal Sensor	0011 010x	34	SMB_I2C_M2
DDR Thermal Sensor	0100 110x	4C	SMB_I2C_M2
I2C Bus Expander	0011 xxxx	3x	SMB_I2C
Ambient Light Sensor	0111 001x	72	ALS
EMA Display	0011 110x	3C	EMA
CPU Thermal Sensor	1001 100x	98	SMB_THRM
IMVFS Amb. Temp. Sensor	1001 101x	9A	SMB_THRM
Battery A	0001 011x	16	SMB_BS
Battery B	0001 111x	1E	SMB_BS
Board ID Port Expander	0011 000x	30	SMB_BS
Docking Port Expander	0011 001x	32	SMB_BS
Skin Temperature Sensor	1001 100x	98	SMB_BS
H8	TBD	TBD	SMB_MB
PCI-Slot3	TBD	TBD	SMB_I2C_A1
PCI-Gold Finger	TBD	TBD	SMB_I2C_A1
PCI-Express Slot1-5	TBD	TBD	SMB_I2C_A1
Docking	TBD	TBD	SMB_I2C_A1
PCIe x16 Slot (PEG)	TBD	TBD	SMB_I2C_S4
TPM Header	TBD	TBD	SMB_I2C_S4
ITP-XDP	TBD	TBD	SMB_I2C_S4

Buses labeled SMB\_I2C\_xx come out of ICH, via an I2C expander. The rest come out of EC.

Jumper	Default	Description	Page
J102	1-2	BSEL0	37
J105	1-2	BSEL1	37
J108	1-2	BSEL2	37
J201	1-2	GFX CORE	49
J201	3-4	GFX CORE	49
J201	5-6	GFX CORE	49
J201	7-8	GFX CORE	49
J201	11-12	GFX CORE	49
J211	1-X	Force Shutdown	55
J3B2	1-2, 3-4	CPU thermal sensor	5
J301	1-X	Power ON latch	55
J401	1-X	ME 03 to M1	55
J5H2	1-X	CMOS Clear	21
J6H2	1-2	CRB/SV Detect	23
J701	1-2	SIO Reset	40
J7J2	1-2	SATA Power Enable	31
J8B1	1-2	In-circuit SMC Programming	41
J8B2	1-2	In-circuit SMC Programming	41
J8B2	1-X	Boot BIOS Strap	22
J8F2	1-X	BIOS recovery	23
J9F1	1-2	KBC Enable	42
J9G2	1-2	Boot Block Programming	42
J9H1	1-X	Virtual Docking	42
J9H2	1-X	NMI	42
J9H3	1-X	KBC disable	42
J9H4	1-2	SMC MD0	42
J9H5	1-2	SATA device detect	41
J9H6	1-X	SMC MD2	32
J9H7	1-2	SMC MD1	42
J9H8	1-X	LID Position	42
J9H9	1-X	Virtual Battery	42

Switch	Default	Description	Page
SW9H1	1 - 2	Virtual Docking	42
SW9H2	1 - 2	Virtual Battery	42
SW9J1	1 - 2	LID Switch	42

SL No	NO_STUFF	STUFF
1	U6E2, U6E3, U6E4	
2	L5F1	
3	R5E5, R5F9, R5T16, R5U3, R5U11, R5U14, R5U21, R6V1	R5E4, R5T5, R5T8, R5T9, R5T10, R5T12, R5T17
4	C5E8, C5E9, C5E11, C5E12, C5E13, C5E14, C5E15, C5T12, C5T13, C5U1, C5U2, C5U3	C5E8, C5E9, C5T13, C5U3 with 0 Ohm 0402 size res IPN A93549-001
5	FBSF1, FBSF2, FBSF1	
6	J2G1(3 4), J2G1(5 6),	J2G1(1 2), J2G1(13 14)

Device	IDSEL #	REQ/GNT #	Interrupts
Slot 3	AD18	2 2	D, C, A, B
LAN	(AD24 internal)		

### Net Naming Conventions

Suffix	
# = Active Low Signal	
Prefix	
H = Host	
M = DDR Memory	
TP = Test Point (does not connect anywhere else)	

### LEDs and Switches

LED	Page	Reference
XTA Activity	21	CR5J1
VID0	41	CR1B1
VID1	41	CR1B2
VID2	41	CR1B3
VID3	41	CR1B4
VID4	41	CR1B5
VID5	41	CR1B6
VID6	41	CR1B7
Num Lock	42	CR9G1
Scroll Lock	42	CR9G2
Caps Lock	42	CR9G3
S3	57	CR3G2
M0/M1	57	CR4H1
S4	57	CR5H3
S5	57	CR5H4
S0	57	CR5H5
System Power Good	57	CR5J1

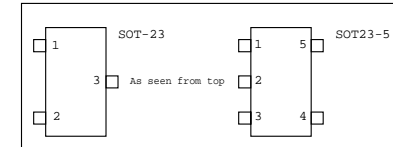
  

Switch	Page	Reference
Power Button	55	SW1C2
Reset Button	55	SW1C2
Net Detect	42	SW8E1
Virtual Docking	42	SW9H1
Virtual Battery	42	SW9H2
LID Switch	42	SW9J1

### Wake Events

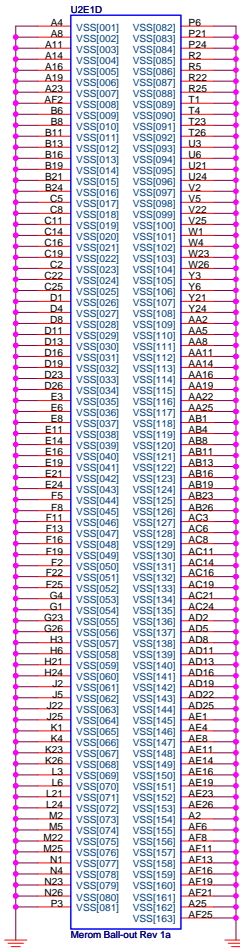
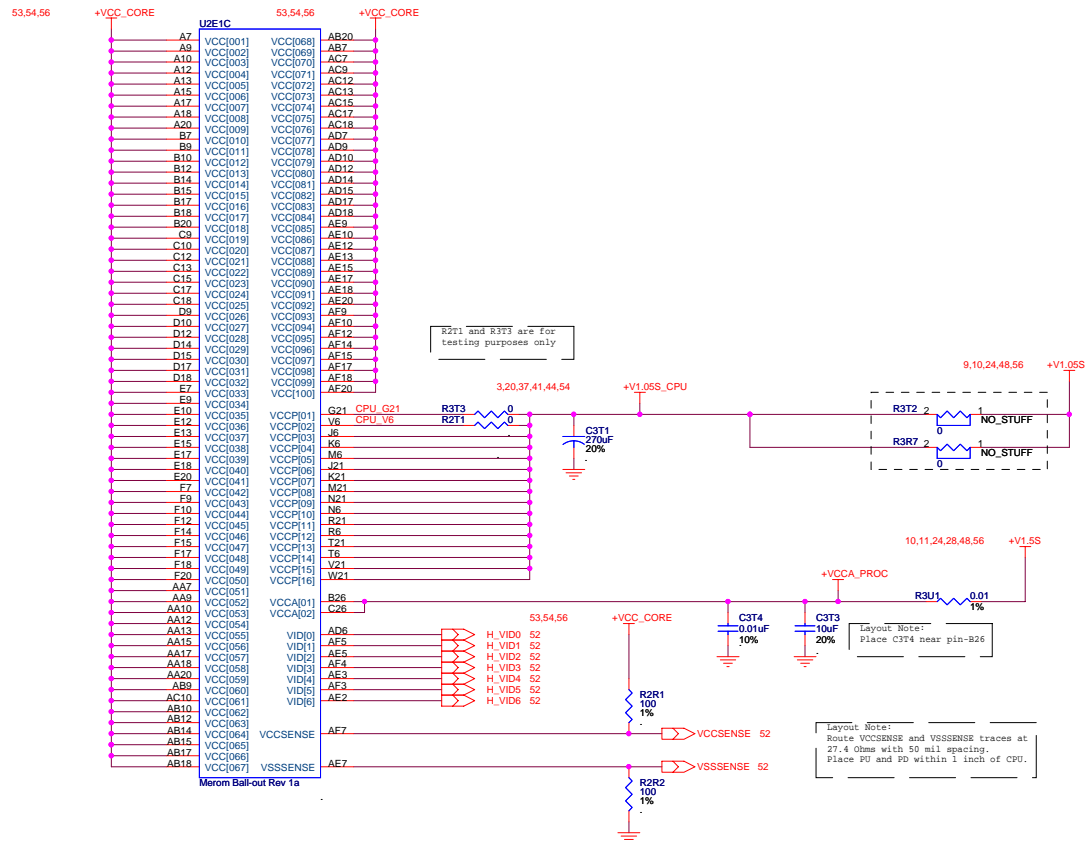
Wake Events	State Supported
RIF from serial port	S3
PM# from PCI, mini PCI slot/device, LPC slot/device	S3
PCI Express, mini PCI Express, Express-card wake event	S3
Wake on LAN	S3/M1
LID switch attached to SMC	S3
USB	S3
HDA wake on ring	S3
Smilink for AGLII	S3
Hot Key from Scan matrix keyboard	S3
PS/2 Keyboard/mouse	S3
PWRBTN#	S3
Netdetect	S3, S4, S5 / M1

### PCB Footprints



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NOTES		
<b>Size</b>	<b>Document Number</b>	<b>Rev</b>
A	NDA	1.5
<b>Date:</b>	Wednesday, December 06, 2006	<b>Sheet</b> 2 <b>of</b> 58



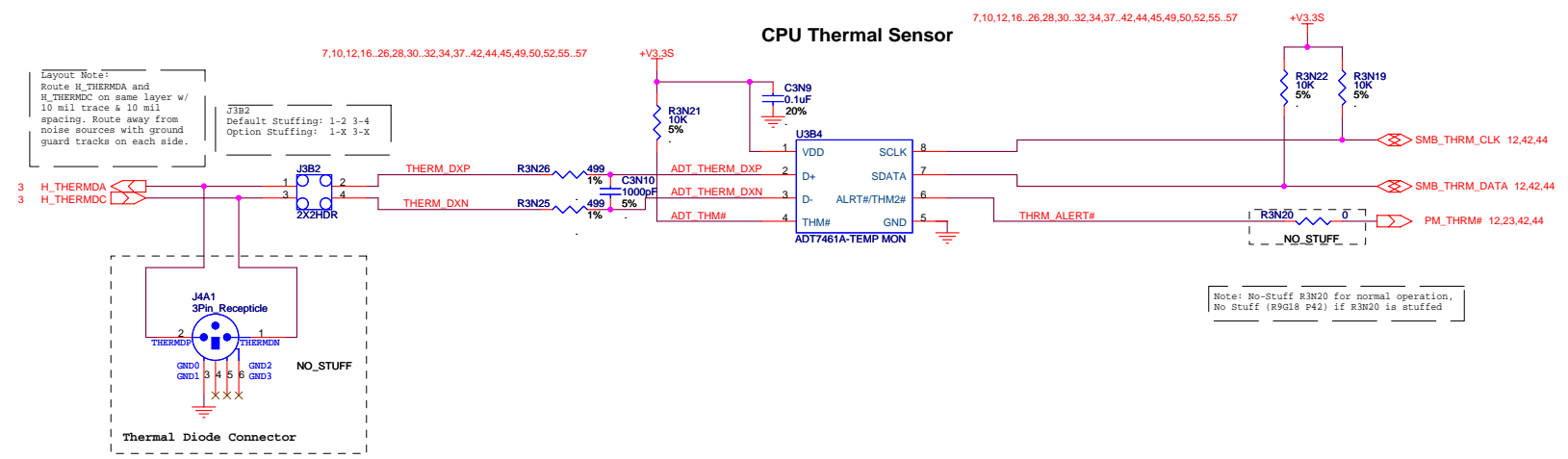


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Title			
Intel® Core™2 Duo Mobile Processor (2 of 2)			
Size	Document Number	Rev	
Custom	NDA	1.5	
Date:	Tuesday, November 21, 2006	Sheet	4 of 58

Layout Note:  
Route H\_THERMDA and H\_THERMDC on same layer w/ 10 mil trace & 10 mil spacing. Route away from noise sources with ground guard tracks on each side.

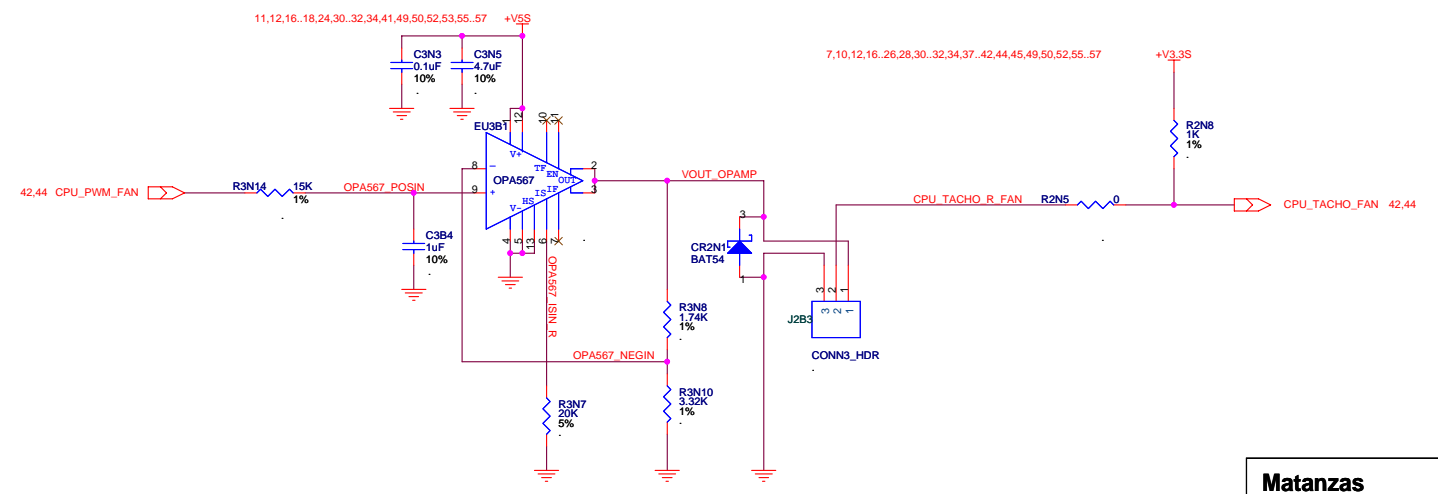
J3B2  
Default Stuffing: 1-2 3-4  
Option Stuffing: 1-X 3-X

### CPU Thermal Sensor



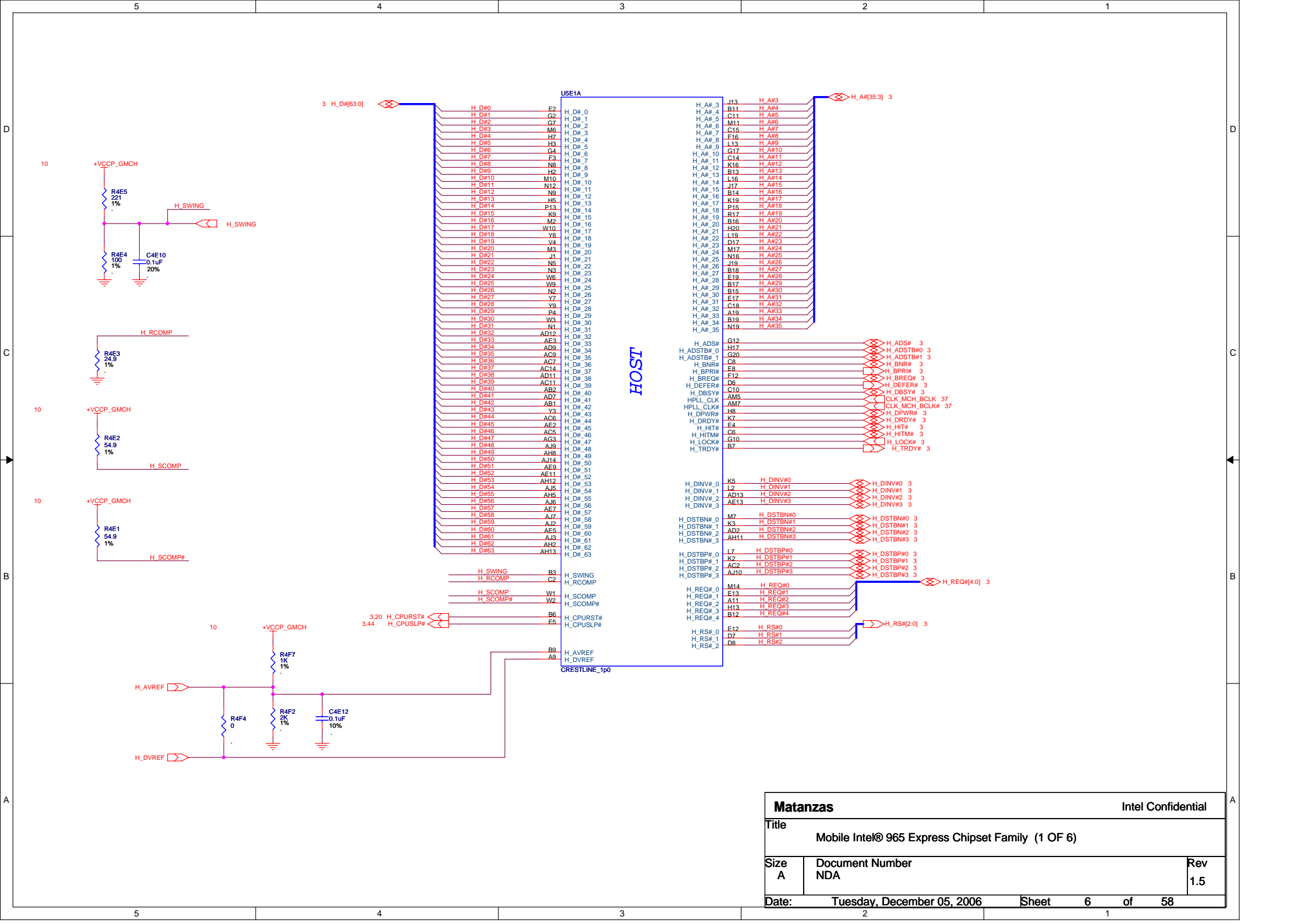
Note: No-Stuff R3N20 for normal operation.  
No Stuff (R9G18 P42) if R3N20 is stuffed.

### CPU Fan Power Control



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Title CPU Thermal Sensor & Fan		
Size A	Document Number NDA	Rev 1.5
Date:	Tuesday, December 05, 2006	Sheet 5 of 58

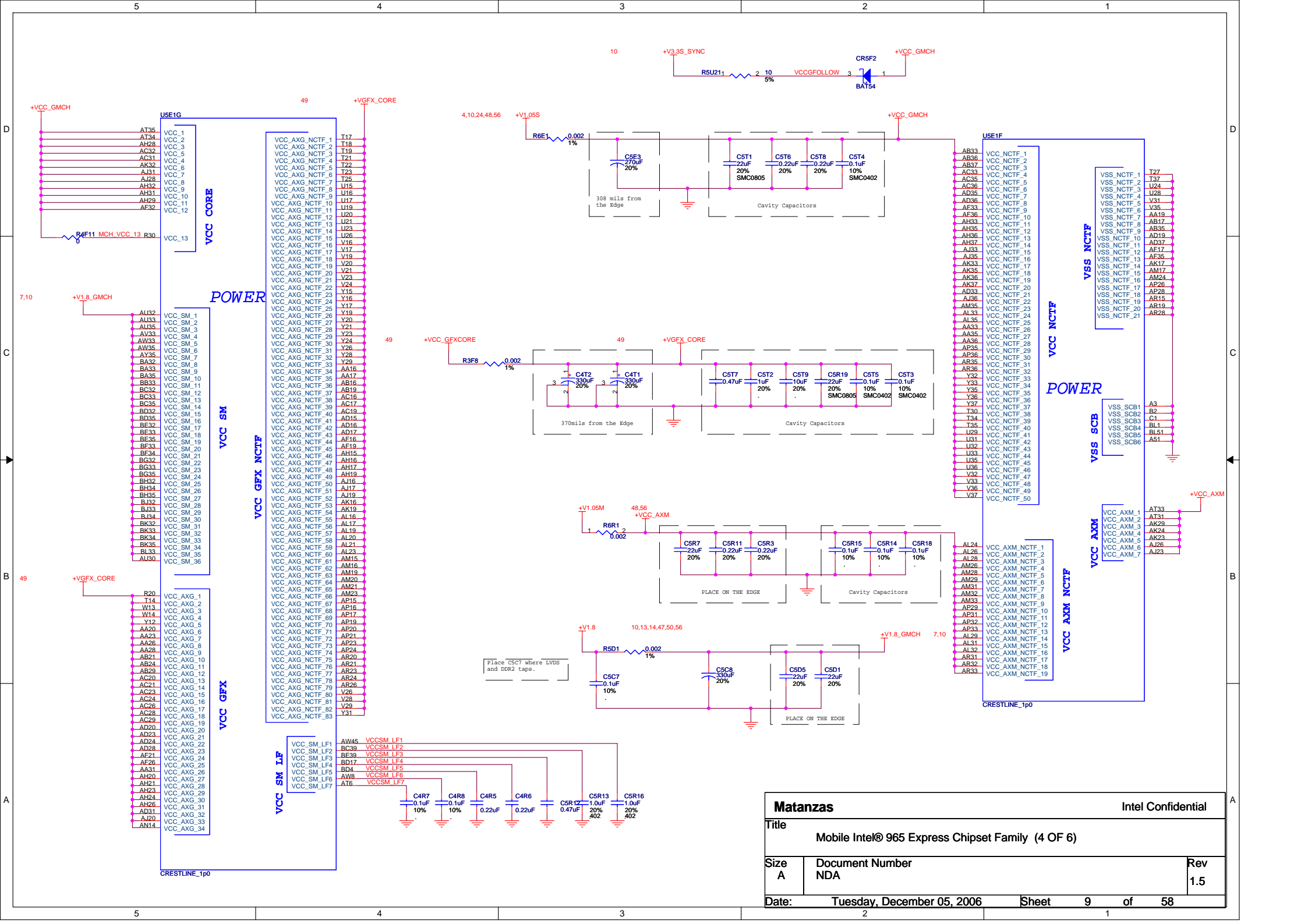




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Size A	Document Number NDA	Rev 1.5
Date:	Tuesday, December 05, 2006	Sheet 6 of 58







<b>Matanzas</b>		Intel Confidential
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Size A	Document Number NDA	Rev 1.5
Date:	Tuesday, December 05, 2006	Sheet 9 of 58

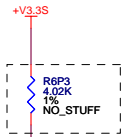




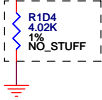
Layout Note:  
Location of all MCH\_CFG strap resistors  
needs to be close to trace to minimize stub

5,7,10,16..26,28,30..32,34,37..42,44,45,49,50,52,55..57

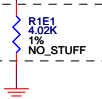
SDVO/PCIe Concurrent Operation	
MCH_CFG_20	Low = Only SDVO or PCIe x1 is operational (default) High = SDVO and PCIe x1 are operating simultaneously via the PEG port



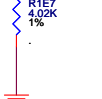
DMI X2 Select	
MCH_CFG_5	Low = DIMIX2 High = DIMIX4 (default)



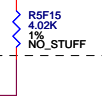
FSB Dynamic ODT	
MCH_CFG_16	Low = Dynamic ODT Disabled High = Dynamic ODT Enabled (default)



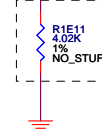
PCI Express Graphics Lane	
MCH_CFG_9	Low = Reverse Lane (default) High = Normal operation



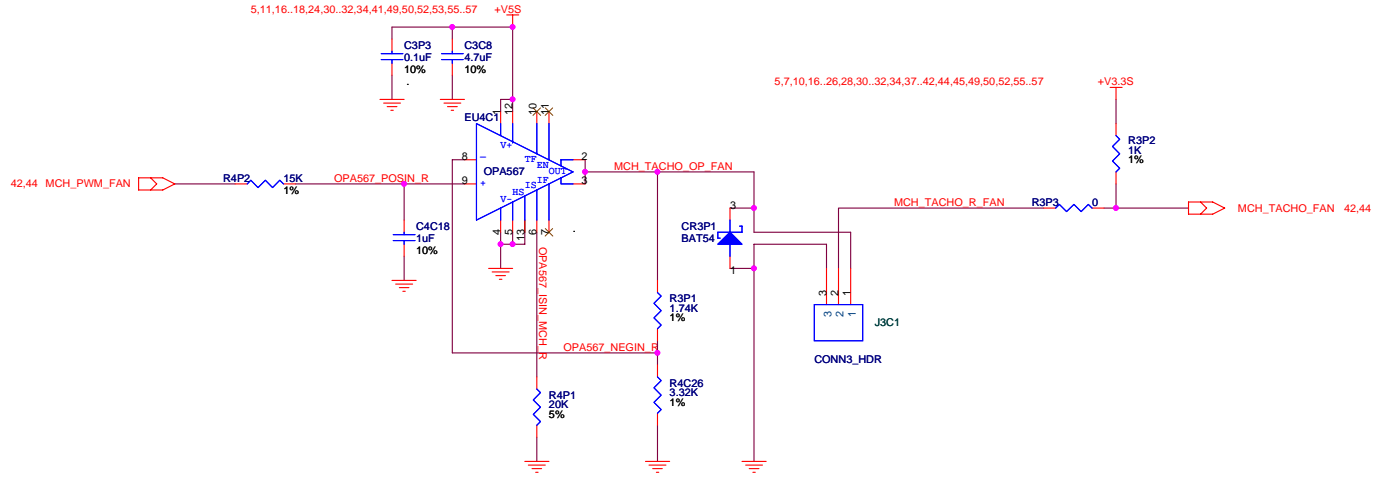
DMI Lane Reversal	
MCH_CFG_19	Low = Normal (default) High = Lanes Reversed



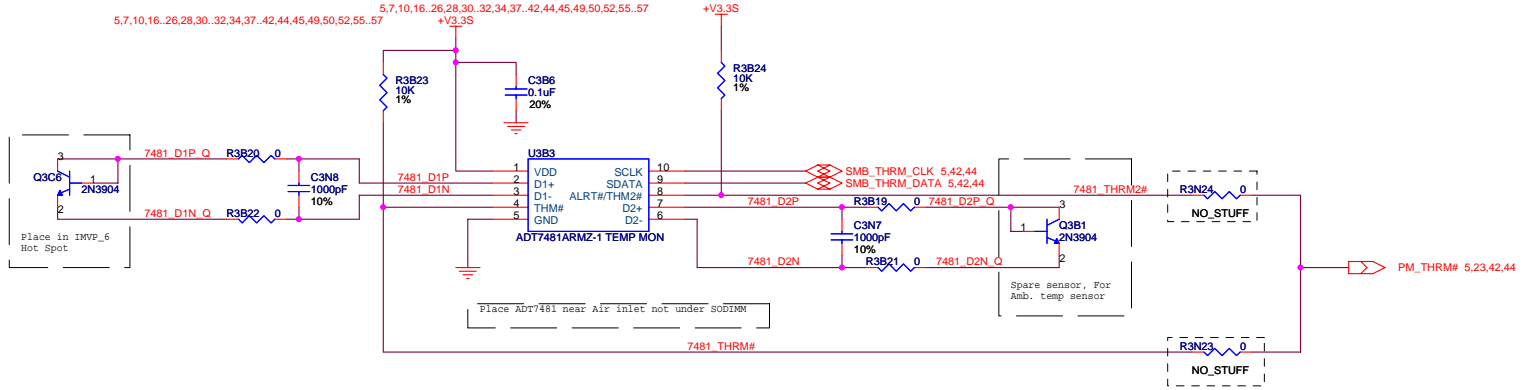
XOR / ALLZ / Clock Un-gating		
MCH_CFG_12	MCH_CFG_13	Configuration
0	0	Clock Gating Disabled
0	1	XOR Mode Enabled
1	0	All-Z Mode Enabled
1	1	Normal Operation (Default)



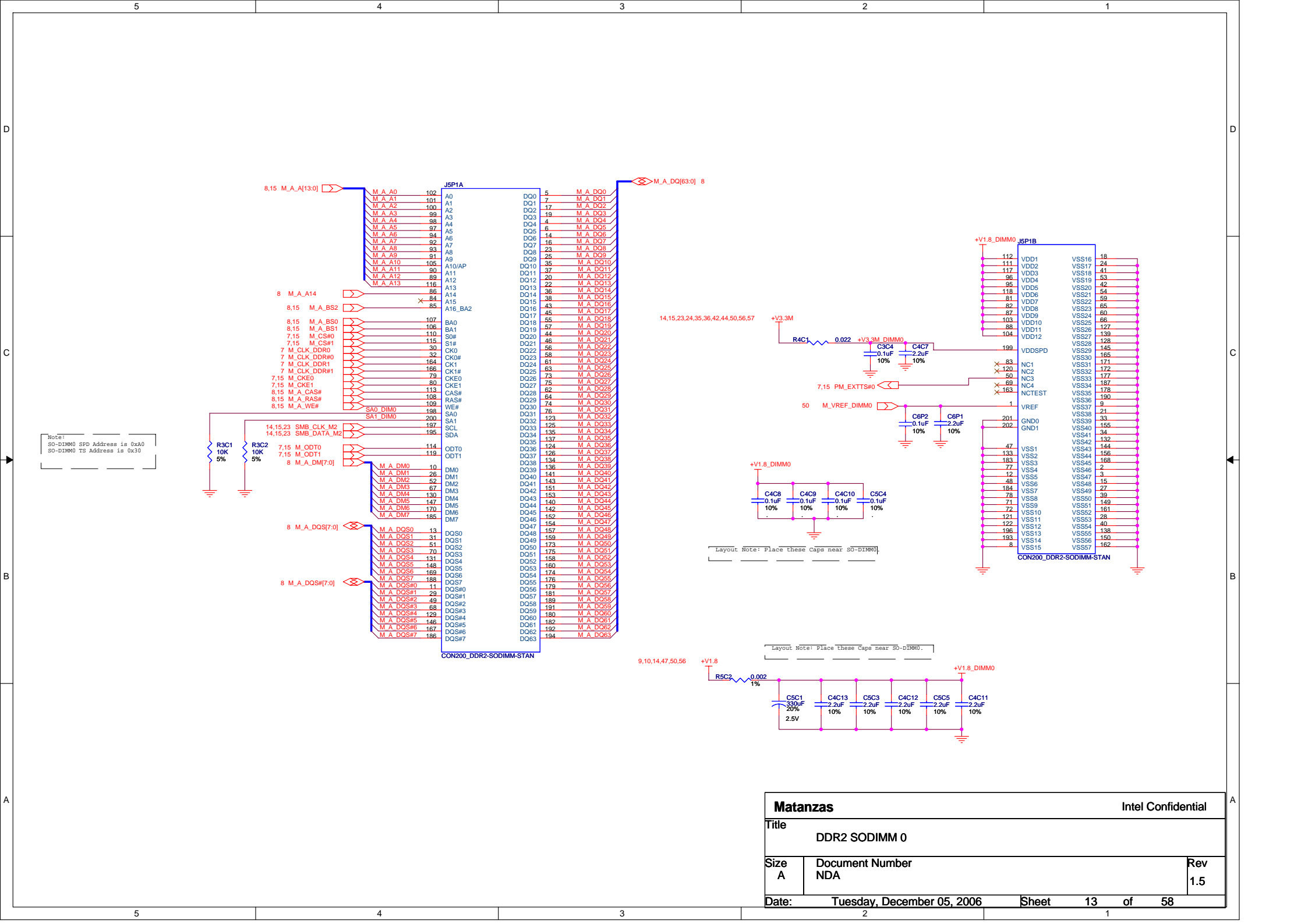
### GMCH Fan Power Control



### IMVP6 & Amb Thermal sensors



<b>Matanzas</b>		Intel Confidential
Title Mobile Intel® 965 Express Chipset Family STRAPPING		
Size A	Document Number NDA	Rev 1.5
Date: Tuesday, November 21, 2006	Sheet 12	of 58



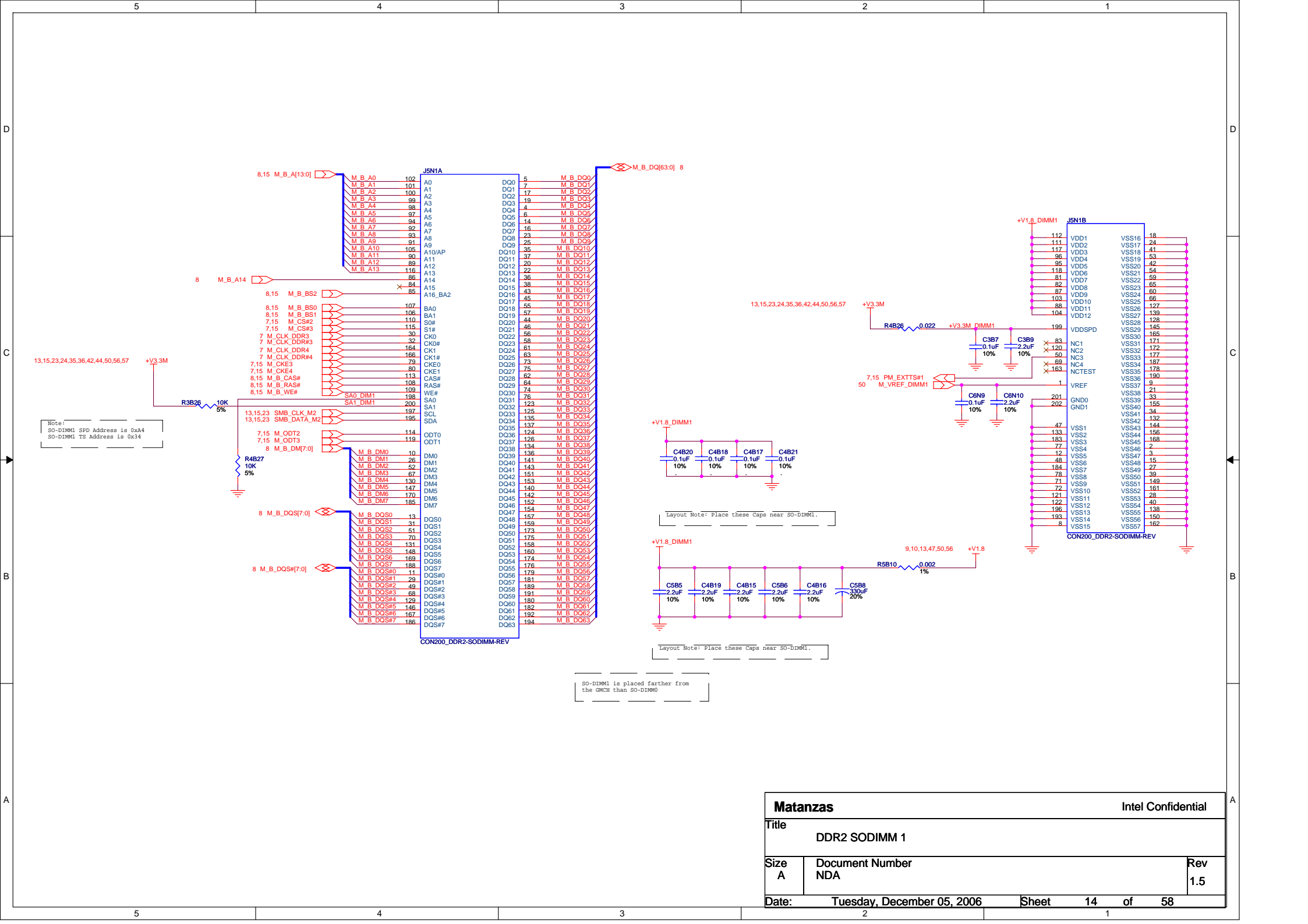
Note:  
 S0-DIMM0 SPD Address is 0xA0  
 S0-DIMM0 TS Address is 0x30

Layout Note: Place these Caps near S0-DIMM0.

Layout Note: Place these Caps near S0-DIMM0.

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<b>Title</b>			
DDR2 SODIMM 0			
<b>Size</b>	<b>Document Number</b>		<b>Rev</b>
A	NDA		1.5
<b>Date:</b>	Tuesday, December 05, 2006	<b>Sheet</b>	13 of 58





Note:  
 SO-DIMM1 SPD Address is 0xA4  
 SO-DIMM1 TS Address is 0x34

Layout Note: Place these Caps near SO-DIMM1.

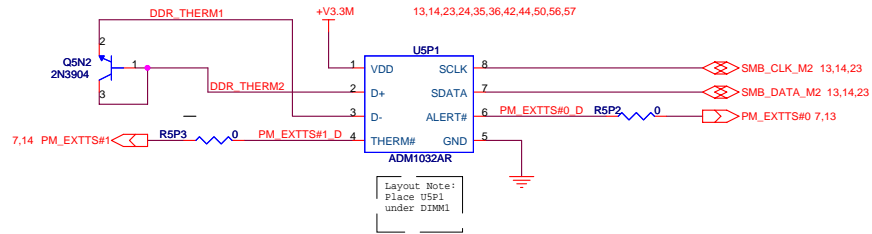
Layout Note: Place these Caps near SO-DIMM1.

SO-DIMM1 is placed farther from the GMCH than SO-DIMM0

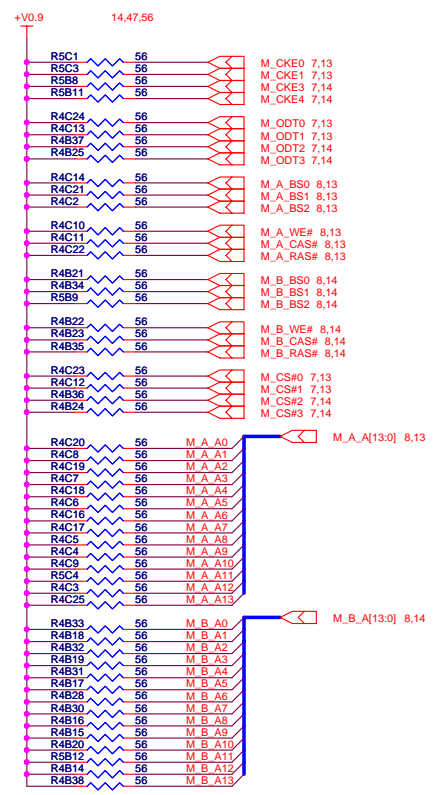
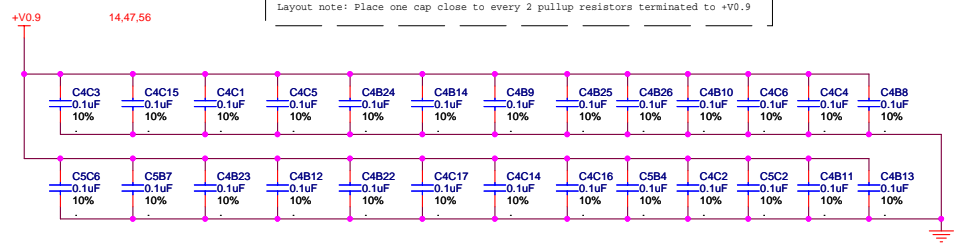
<b>Matanzas</b>		<b>Intel Confidential</b>	
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DDR2 SODIMM 1			
<b>Size</b>	<b>Document Number</b>		<b>Rev</b>
A	NDA		1.5
<b>Date:</b>	Tuesday, December 05, 2006	<b>Sheet</b>	14 of 58

Layout Note:  
Place Q5N2  
under DIMM0

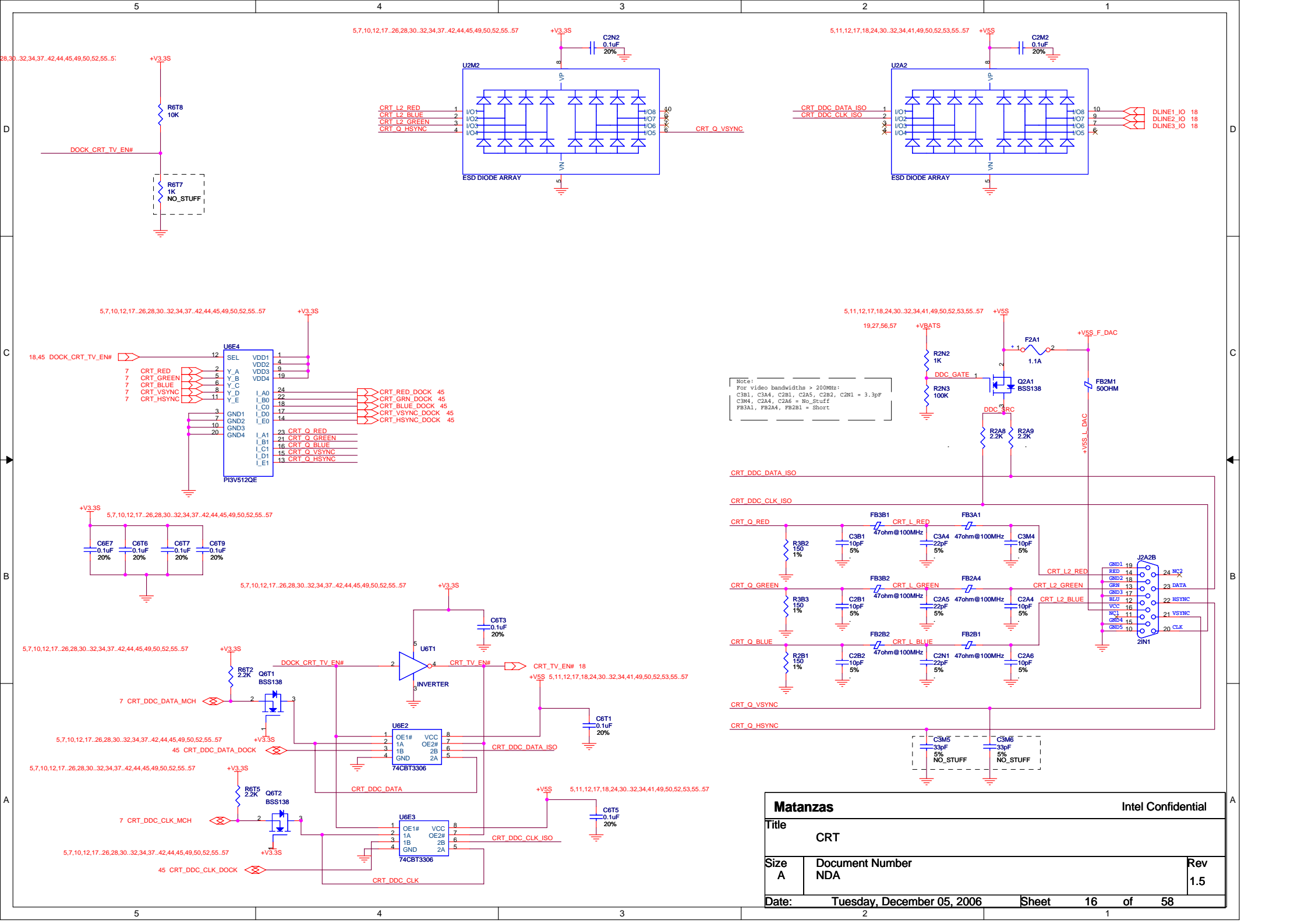
### On Board DDR2 Thermal Sensor



Layout note: Place one cap close to every 2 pullup resistors terminated to +V0.9

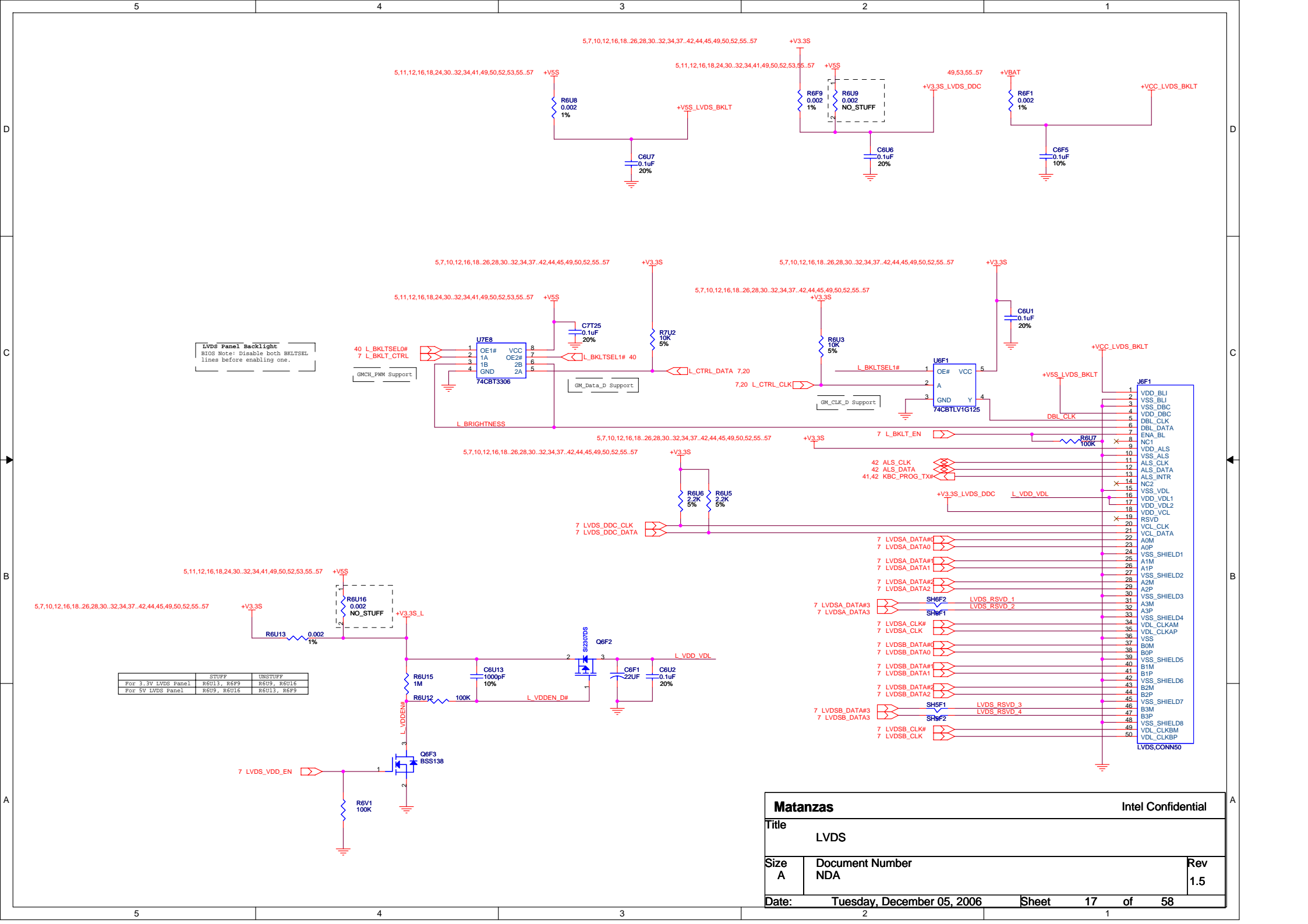


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Title DDR2 TERMINATION AND THERMAL SENSOR		
Size A	Document Number NDA	Rev 1.5
Date:	Tuesday, December 05, 2006	Sheet 15 of 58



Note:  
 For video bandwidths > 200MHz:  
 C3B1, C3A4, C2B1, C2A5, C2B2, C2N1 = 3.3pF  
 C3M4, C2A4, C2A6 = No\_Stuff  
 FB3A1, FB2A4, FB2B1 = Short

<b>Matanzas</b>		<b>Intel Confidential</b>	
Title CRT			
Size A	Document Number NDA		Rev 1.5
Date:	Tuesday, December 05, 2006	Sheet	16 of 58



**LVDS Panel Backlight**  
 BIOS Note: Disable Both BKLTSEL lines before enabling one.

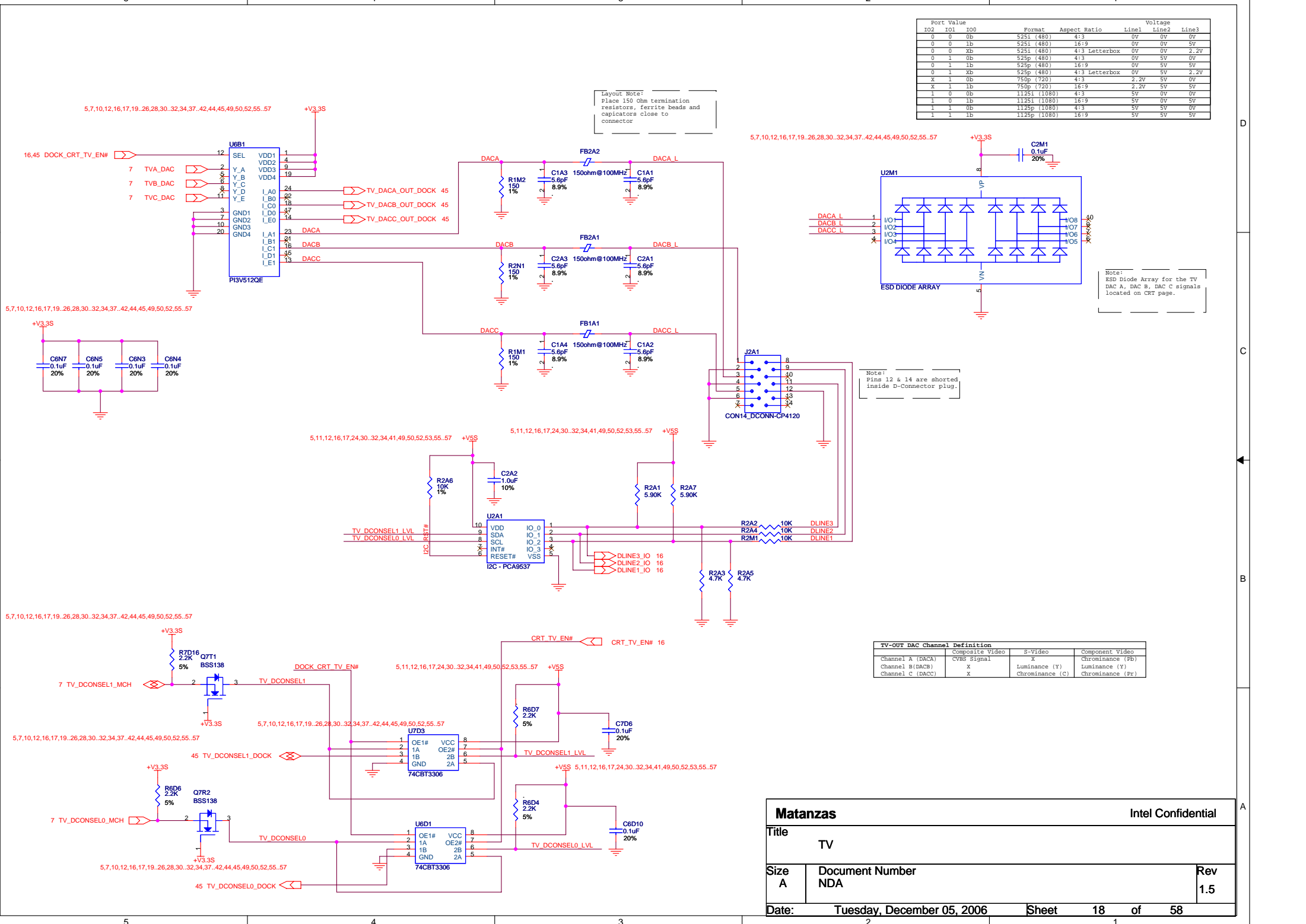
40 L\_BKLTSEL0#  
 7 L\_BKLT\_CTRL  
 GMCH\_PWM Support

GM\_Data\_D Support

GM\_CLK\_D Support

	STUFF	DNSSTUFF
For 3.3V LVDS Panel	R6U13, R6F9	R6U9, R6U16
For 5V LVDS Panel	R6U9, R6U16	R6U13, R6F9

<b>Matanzas</b>		<b>Intel Confidential</b>	
Title LVDS			
Size A	Document Number NDA		Rev 1.5
Date:	Tuesday, December 05, 2006	Sheet	17 of 58



Layout Note:  
Place 150 Ohm termination resistors, ferrite beads and capacitors close to connector

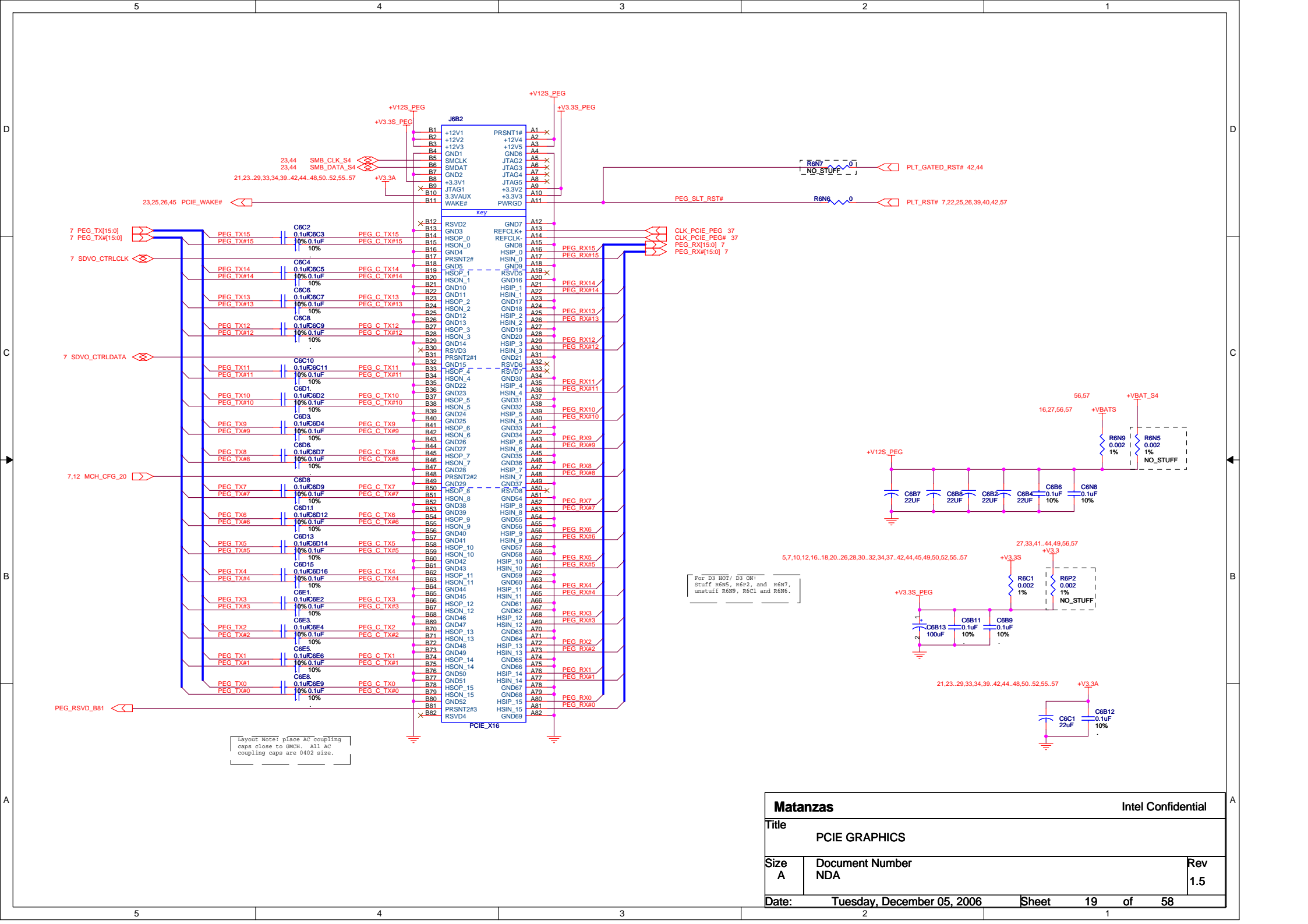
Port Value	IO2	IO1	IO0	Format	Aspect Ratio	Line1	Line2	Line3
0	0	0b		525i (480)	4:3	0V	0V	0V
0	0	1b		525i (480)	16:9	0V	0V	5V
0	0	Xb		525i (480)	4:3 Letterbox	0V	0V	2.2V
0	1	0b		525p (480)	4:3	0V	5V	0V
0	1	1b		525p (480)	16:9	0V	5V	5V
0	1	Xb		525p (480)	4:3 Letterbox	0V	5V	2.2V
X	1	0b		750p (720)	4:3	2.2V	5V	0V
X	1	1b		750p (720)	16:9	2.2V	5V	5V
1	0	0b		1125i (1080)	4:3	5V	0V	0V
1	0	1b		1125i (1080)	16:9	5V	0V	5V
1	1	0b		1125p (1080)	4:3	5V	5V	0V
1	1	1b		1125p (1080)	16:9	5V	5V	5V

Note:  
ESD Diode Array for the TV DAC A, DAC B, DAC C signals located on CRT page.

Note:  
Pins 12 & 14 are shorted inside D-Connector plug.

TV-OUT DAC Channel Definition	Composite Video	S-Video	Component Video
Channel A (DACA)	CVBS Signal	X	Chromance (Cb)
Channel B (DACB)	X	Luminance (Y)	Luminance (Y)
Channel C (DACC)	X	Chromance (C)	Chromance (Pr)

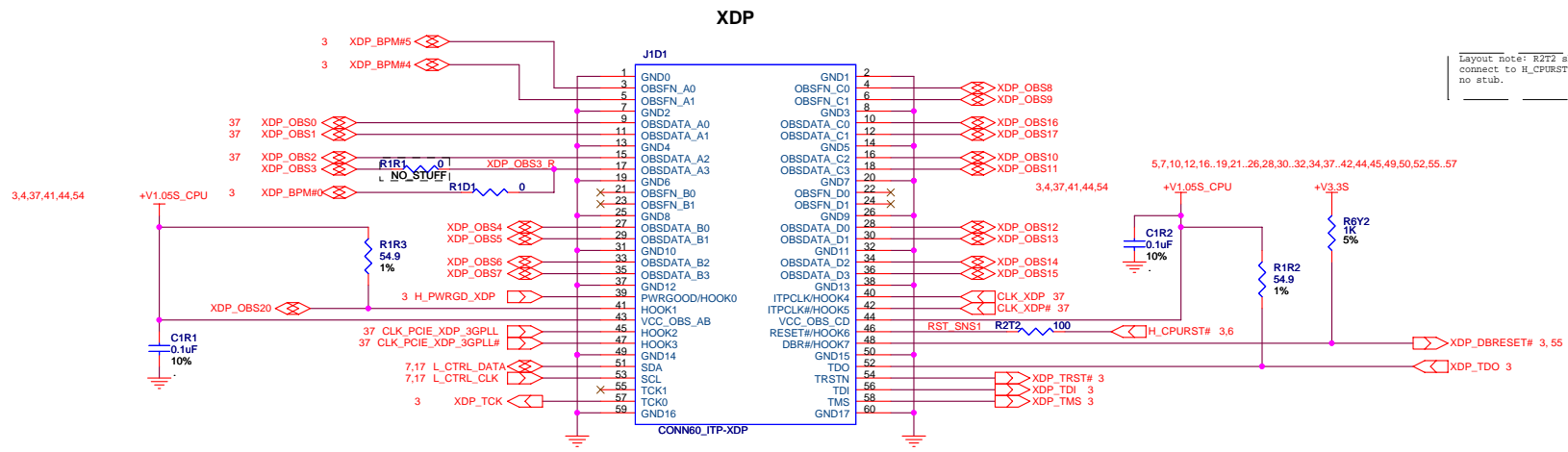
<b>Matanzas</b>		<b>Intel Confidential</b>	
Title TV			
Size A	Document Number NDA		Rev 1.5
Date:	Tuesday, December 05, 2006	Sheet	18 of 58



For D3 HOT/ D3 ON:  
 Stuff R6N5, R6P2, and R6N7,  
 unstuff R6N9, R6C1 and R6N6.

Layout Note: place AC coupling  
 caps close to GMCH. All AC  
 coupling caps are 0402 size.

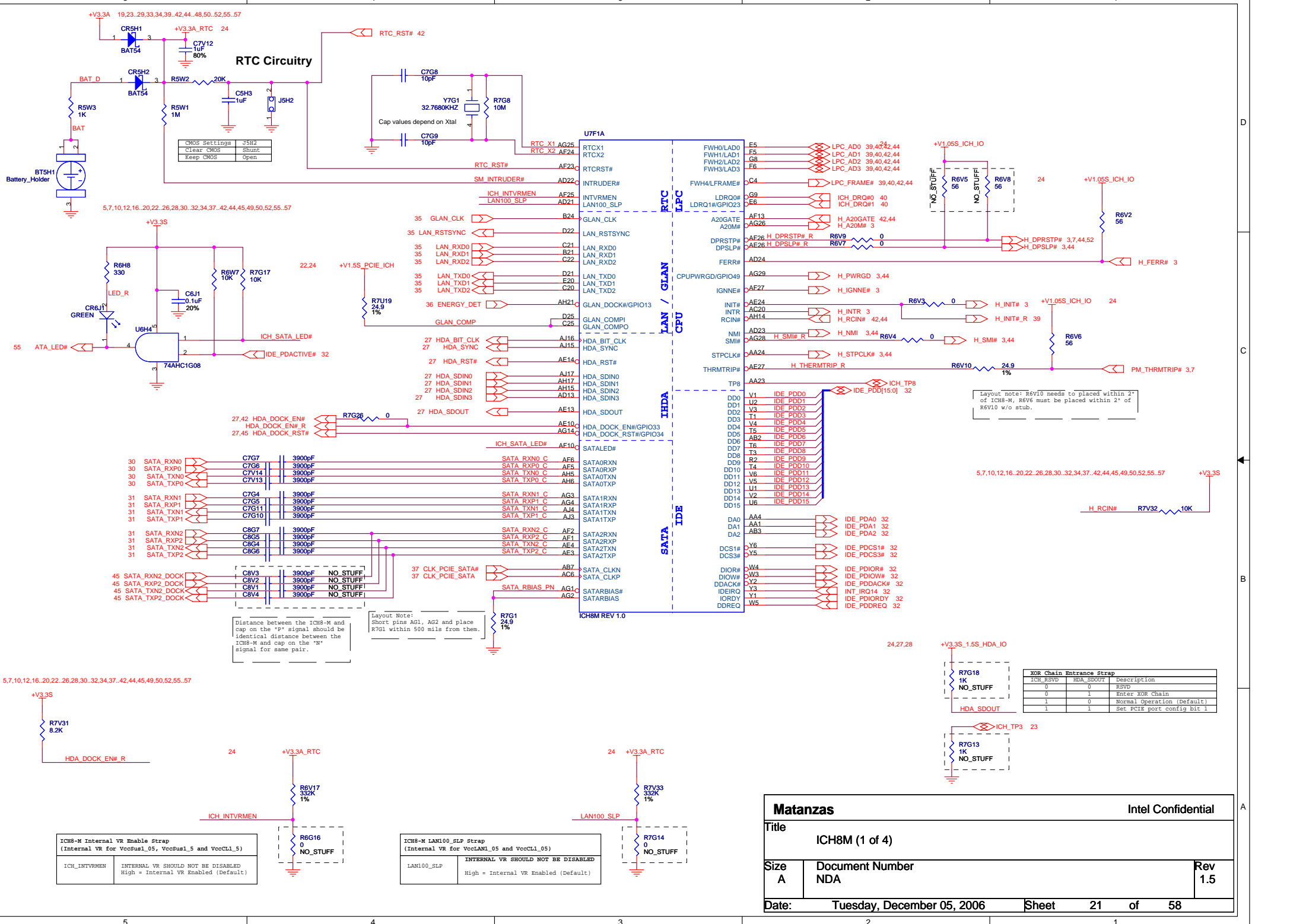
<b>Matanzas</b>		<b>Intel Confidential</b>	
Title PCIE GRAPHICS			
Size A	Document Number NDA		Rev 1.5
Date:	Tuesday, December 05, 2006	Sheet	19 of 58



Layout Note: R2T2 should connect to H\_CPURST# with no stub.

CAD Note:  
Place the XDP connector on the primary side of the CRB and place all components near the connector.

<b>Matanzas</b>		Intel Confidential
Title XDP		
Size A	Document Number NDA	Rev 1.5
Date:	Tuesday, December 05, 2006	Sheet 20 of 58



CMOS Setting#	J5I2
Clear CMOS	Shunt
Keep CMOS	Open

Layout note: R6V10 needs to be placed within 2" of ICH8-M. R6V6 must be placed within 2" of R6V10 w/o stub.

ICR_RSVD	HDA_SDOUT	Description
0	0	RSVD
0	1	Enter XOR Chain
1	0	Normal Operation (Default)
1	1	Set PCIe port config bit 1

ICH8-M Internal VR Enable Strap (Internal VR for VccSus1_05, VccSus1_5 and VccCL1_5)	
ICH_INTVRMEN	INTERNAL VR SHOULD NOT BE DISABLED High = Internal VR Enabled (Default)

ICH8-M LAN100_SLP Strap (Internal VR for VccLAN1_05 and VccCL1_05)	
LAN100_SLP	INTERNAL VR SHOULD NOT BE DISABLED High = Internal VR Enabled (Default)

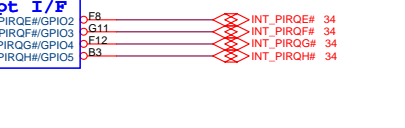
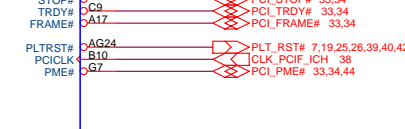
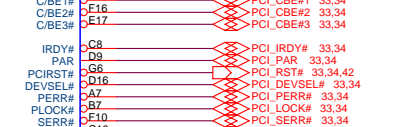
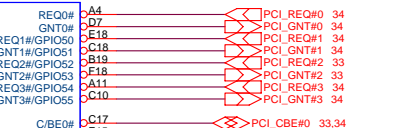
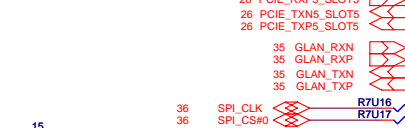
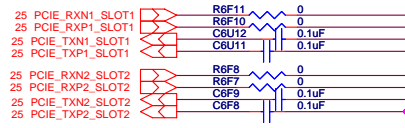
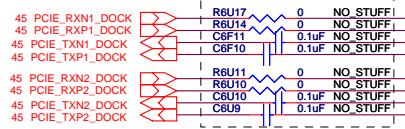
**Matanzas** Intel Confidential

Title: ICH8M (1 of 4)

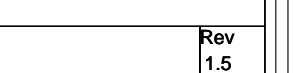
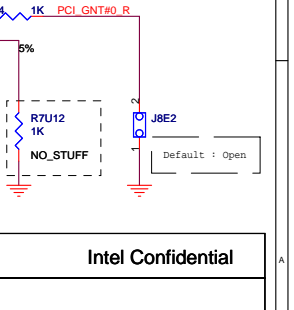
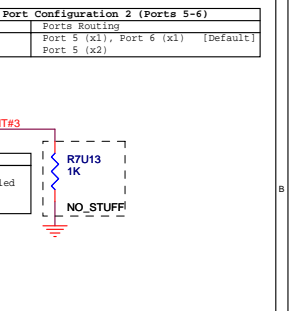
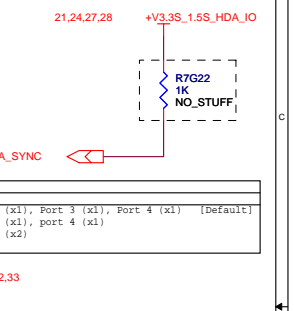
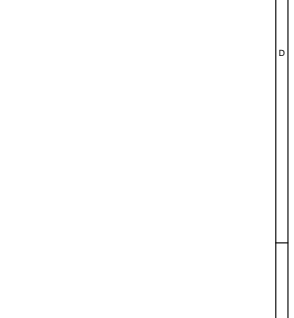
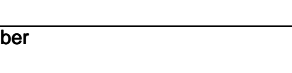
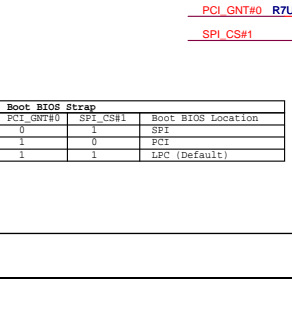
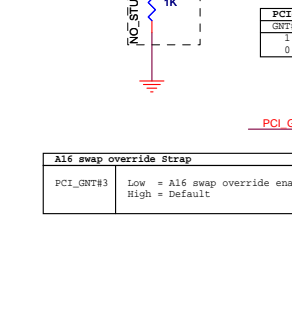
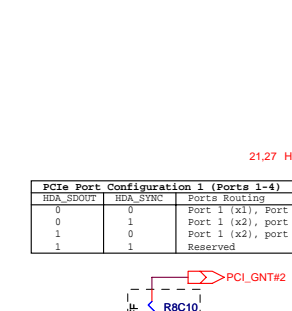
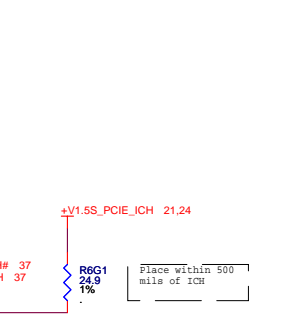
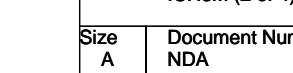
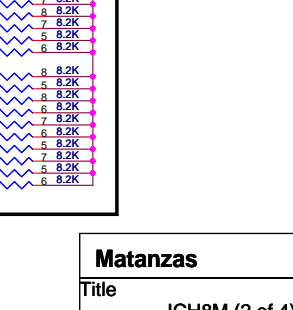
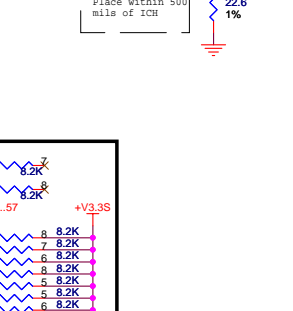
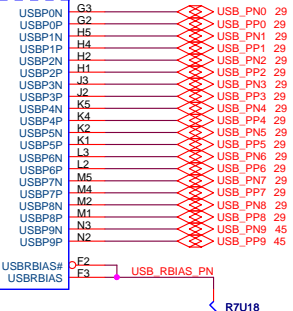
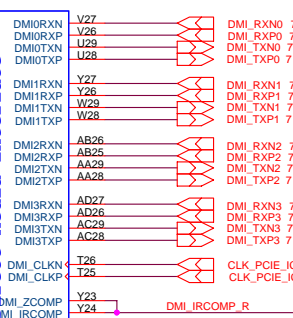
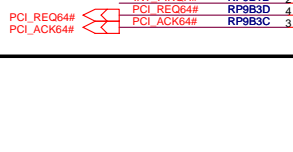
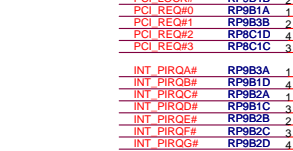
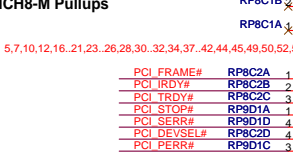
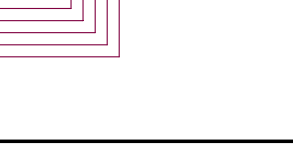
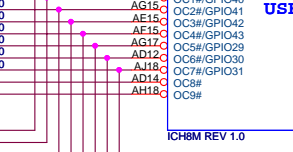
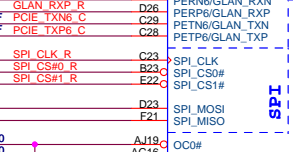
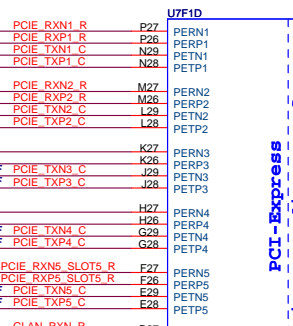
Size A	Document Number NDA	Rev 1.5
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Date: Tuesday, December 05, 2006 Sheet 21 of 58





Layout note:  
 1. PCIe A0 coupling caps need to be within 250 mils of the driver.  
 2. Place the strapping resistors/capacitors without any stub

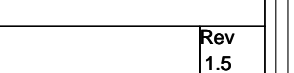
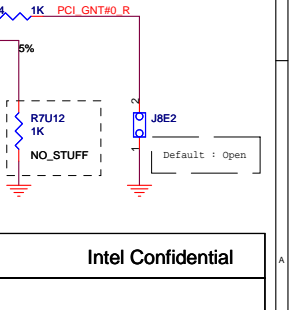
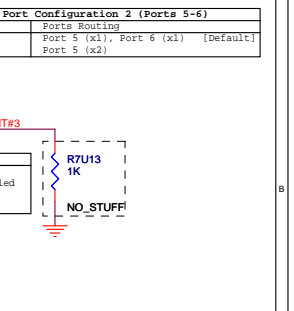
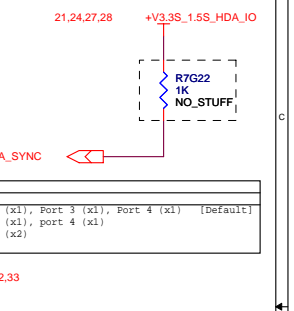
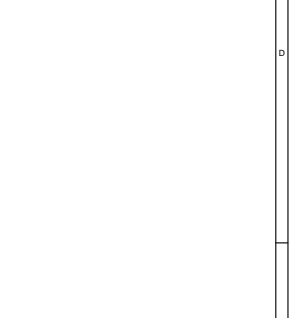
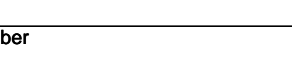
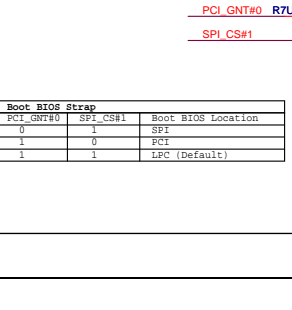
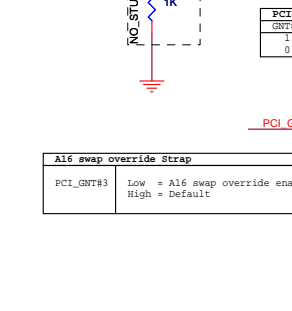
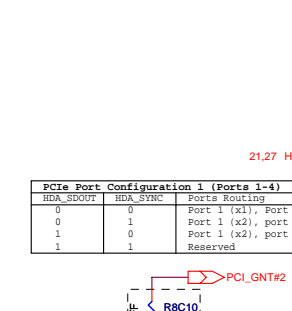
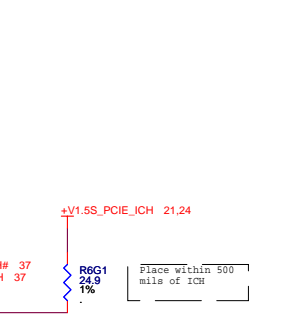
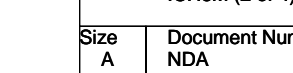
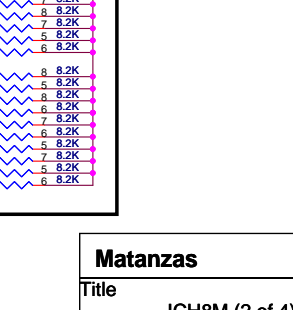
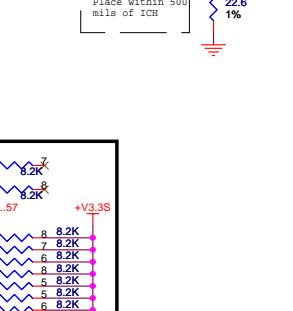
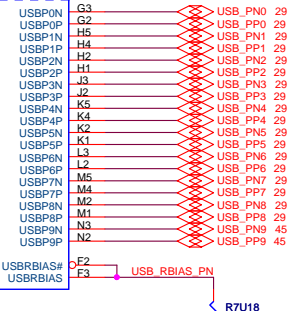
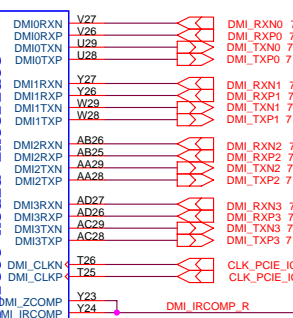
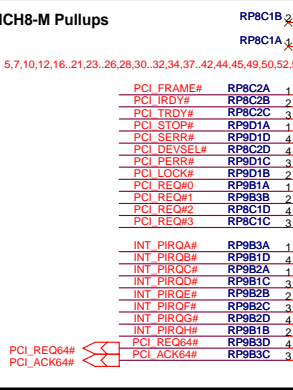
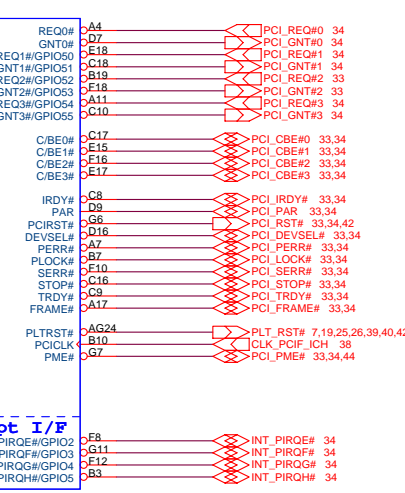


5,7,10,12,16,21,23,26,28,30,32,34,37,42,44,45,49,50,52,55,57

42,44,45 BUF\_PLT\_RST#

33,34 PCI\_AD[31:0]

33 INT\_PIRQA#  
 33,34 INT\_PIRQB#  
 33 INT\_PIRQC#  
 33 INT\_PIRQD#



HDA_SDOUF	HDA_SYNC	Ports Routing
0	0	Port 1 (x1), Port 2 (x1), Port 3 (x1), Port 4 (x1) [Default]
0	1	Port 1 (x2), Port 3 (x1), Port 4 (x1)
1	0	Port 1 (x2), Port 3 (x2)
1	1	Reserved

GNTH#	Ports Routing
1	Port 5 (x1), Port 6 (x1) [Default]
0	Port 5 (x2)

PCI_GNT#3	SPI_CS#1	Boot BIOS Location
0	1	SPI
1	0	PCI
1	1	LPC (Default)

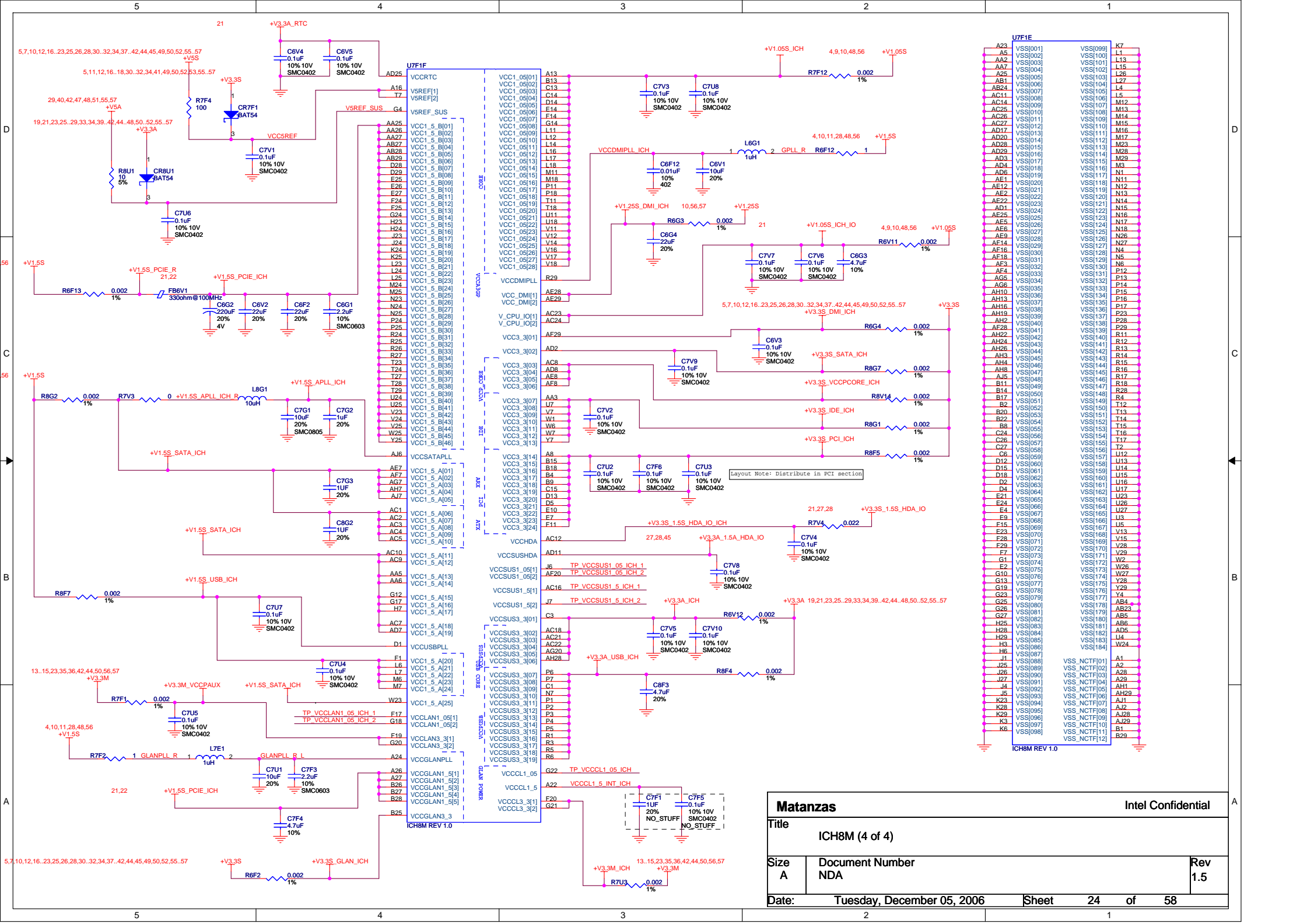
**Matanzas** Intel Confidential

Title: **ICH8M (2 of 4)**

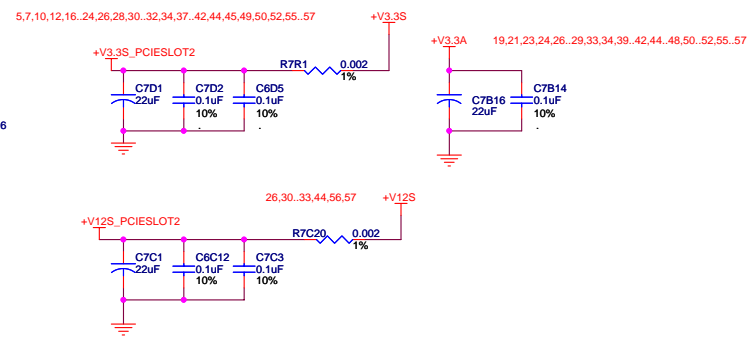
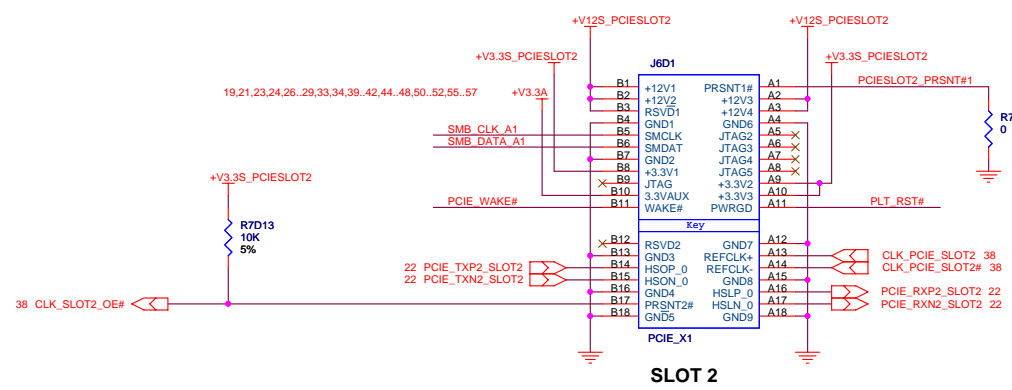
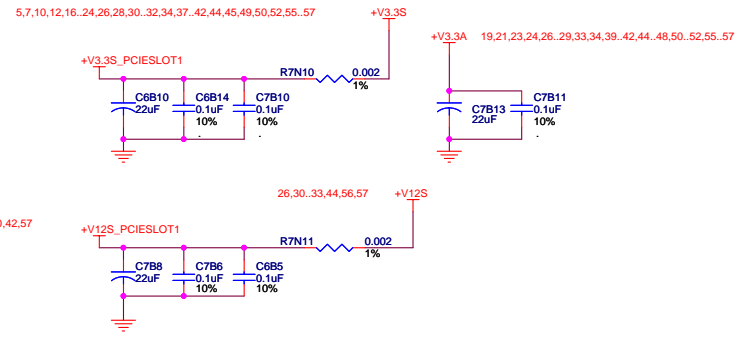
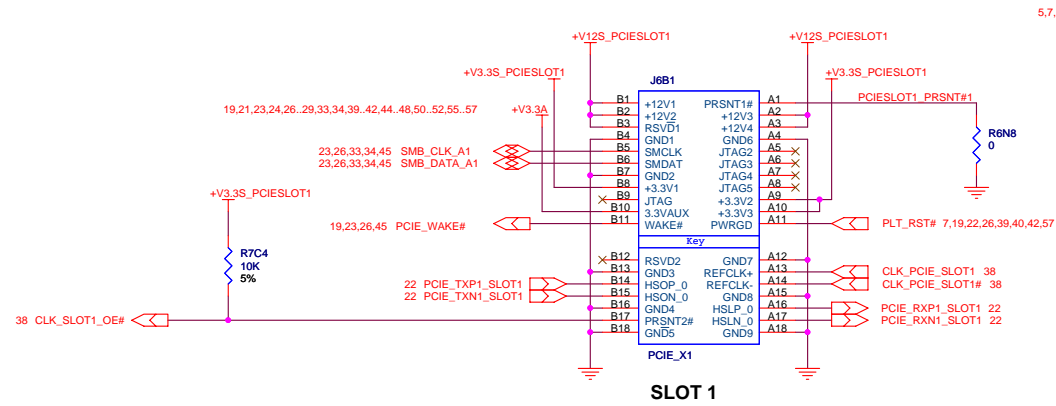
Size A	Document Number NDA	Rev 1.5
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Date: **Tuesday, December 05, 2006** Sheet **22** of **58**

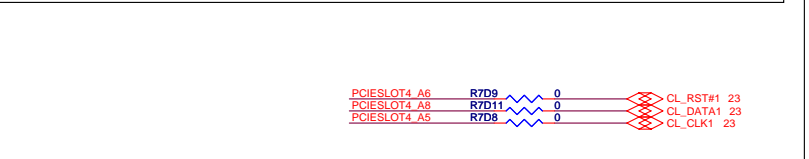
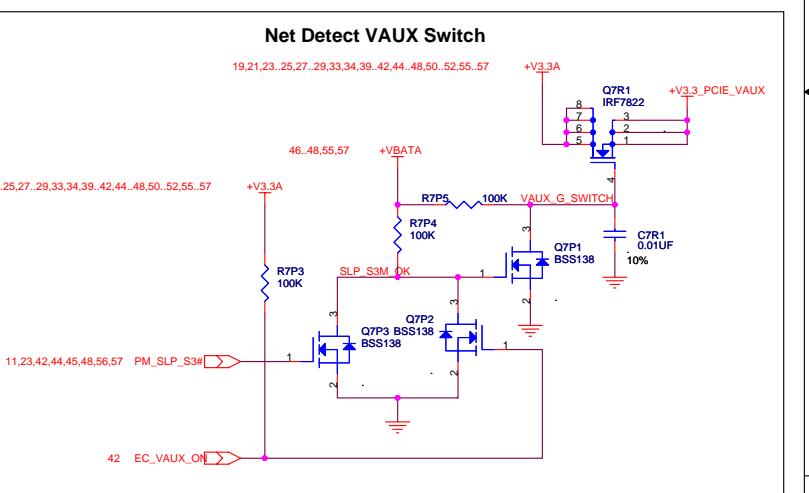
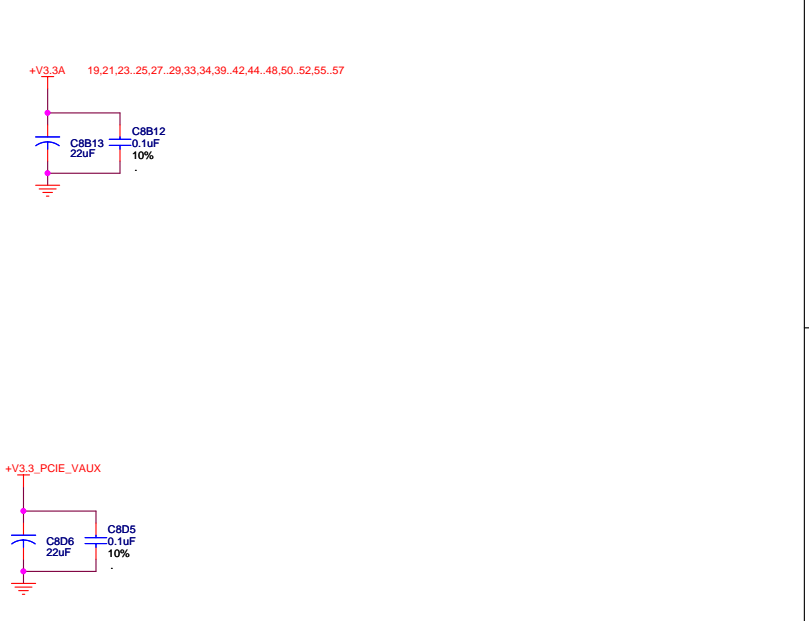
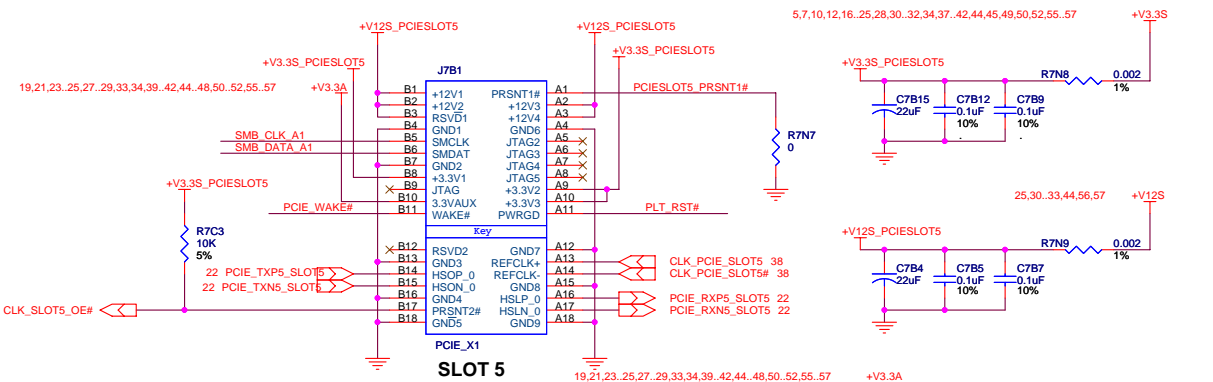
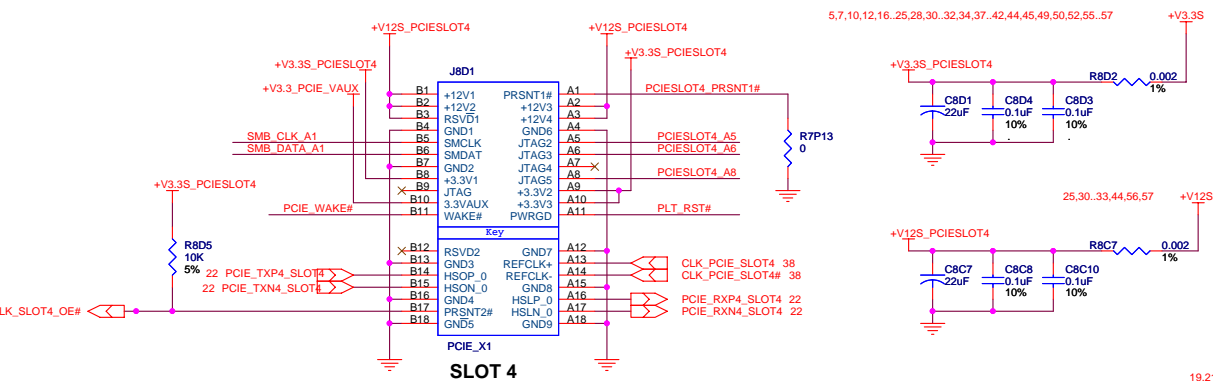
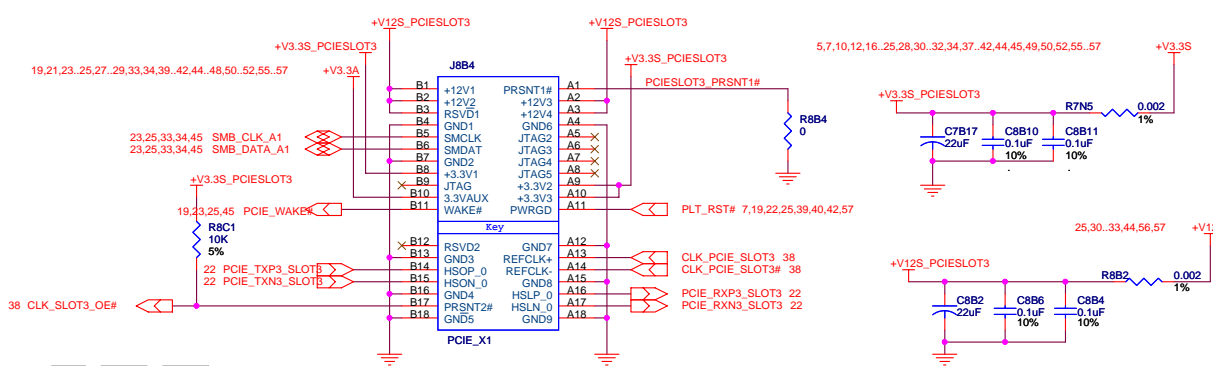




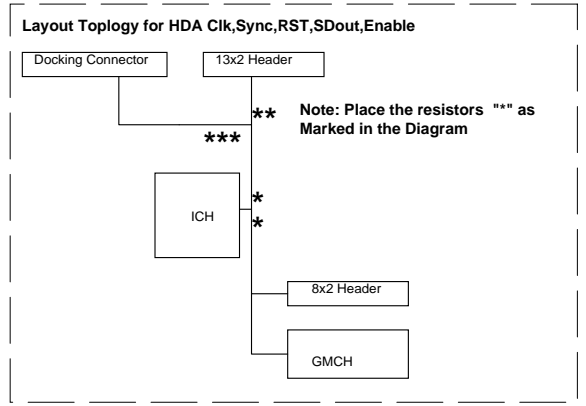
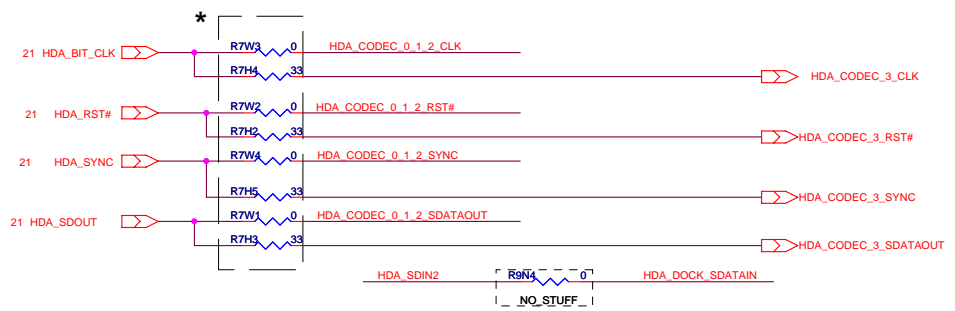
<b>Matanzas</b>		<b>Intel Confidential</b>	
Title: ICH8M (4 of 4)			
Size A	Document Number NDA		Rev 1.5
Date:	Tuesday, December 05, 2006	Sheet 24	of 58



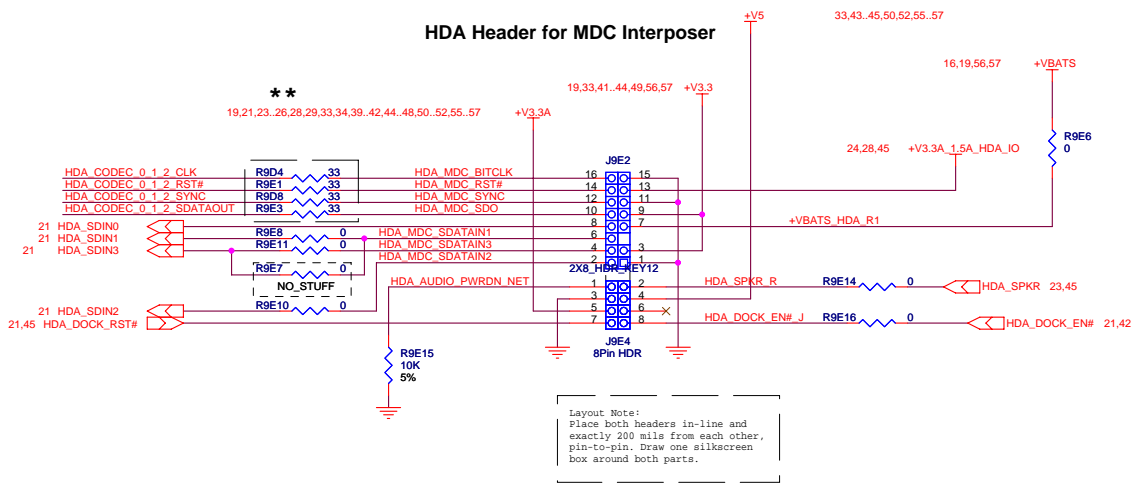
<b>Matanzas</b>		Intel Confidential
Title PCI-E Slots (1 & 2)		
Size	Document Number NDA	Rev 1.5
Date:	Tuesday, November 21, 2006	Sheet 25 of 58



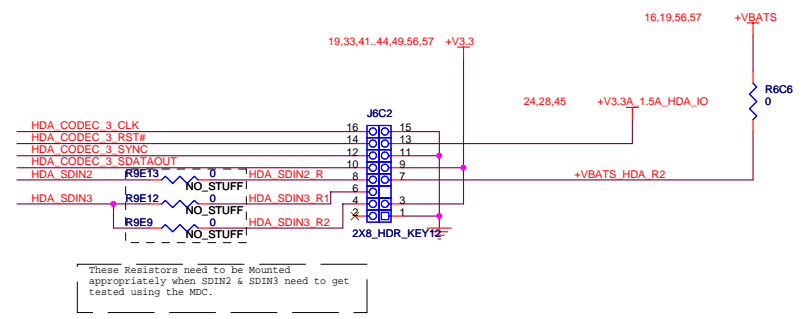
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<b>Title</b> PCI-E Slots (3,4 & 5)			
<b>Size</b>	<b>Document Number</b> NDA		<b>Rev</b> 1.5
<b>Date:</b> Tuesday, November 21, 2006	<b>Sheet</b> 26	<b>of</b> 58	



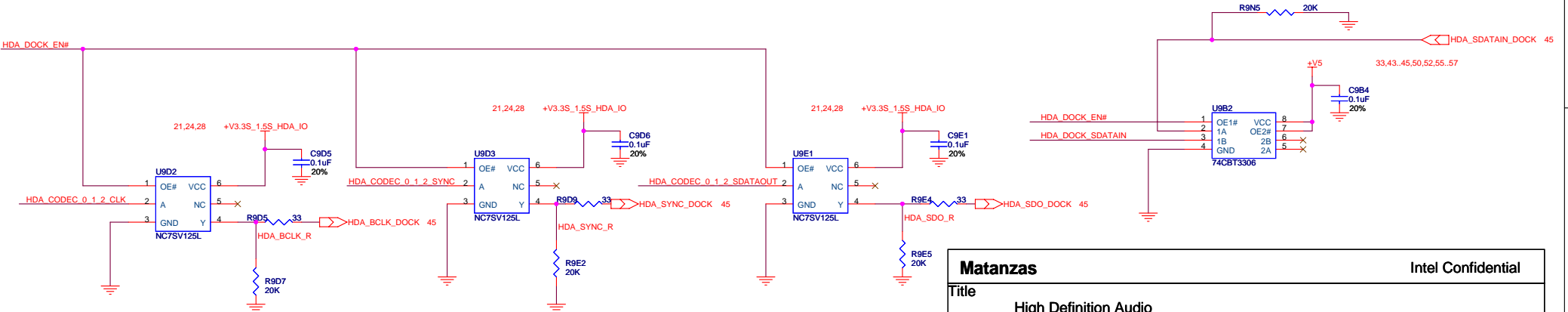
**HDA Header for MDC Interposer**



**HDA Header for External HDMI Support**

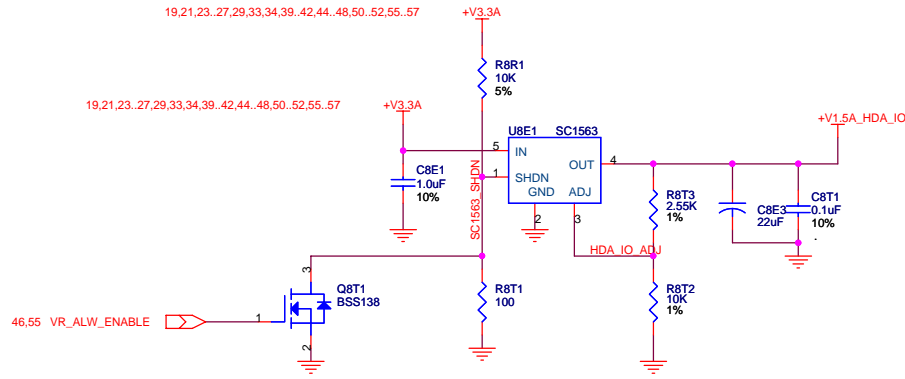


**HDA Docking Circuit**

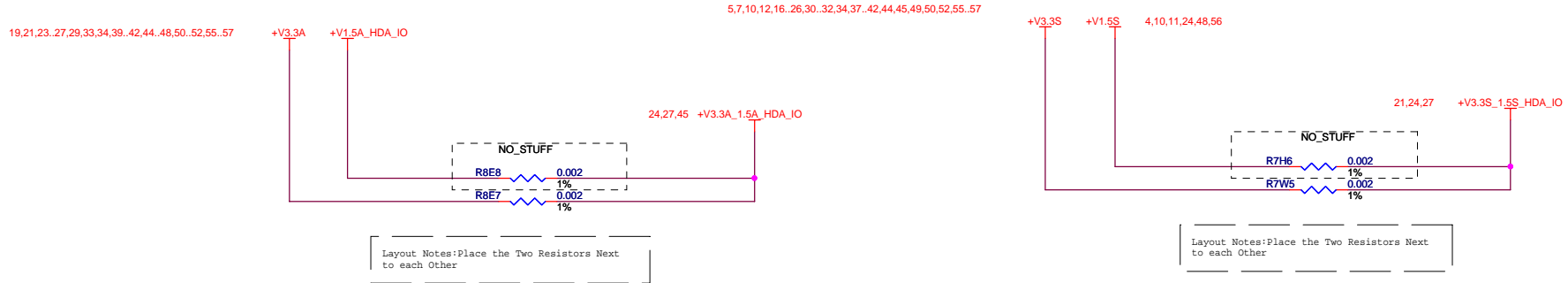


<b>Matanzas</b>		<b>Intel Confidential</b>	
Title High Definition Audio			
Size A	Document Number NDA	Rev 1.5	
Date:	Tuesday, December 05, 2006	Sheet	27 of 58

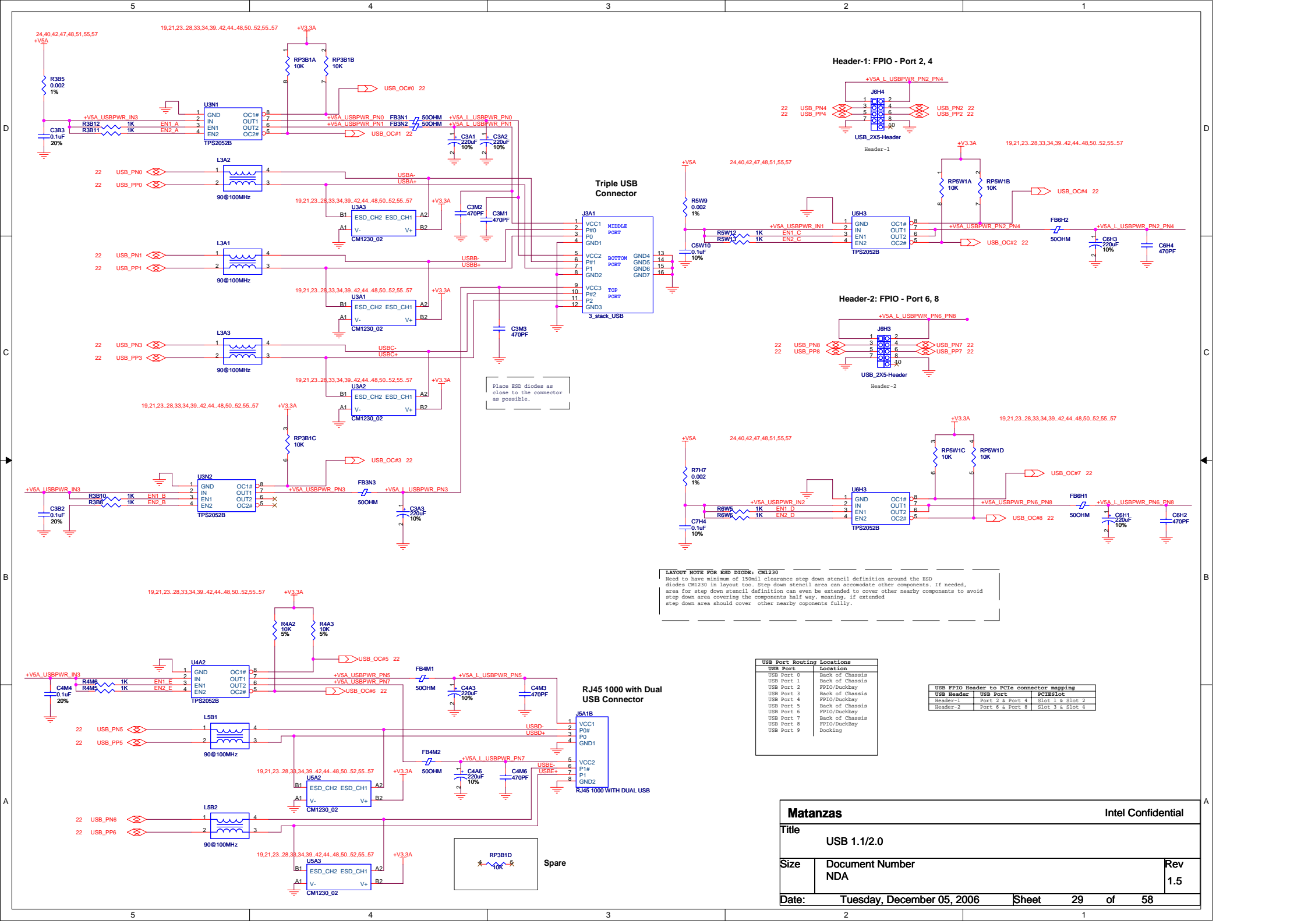
### Power Supply for High Definiton Audio



### Selection of I/O Voltage for the High Definition Audio



<b>Matanzas</b>		Intel Confidential
Title HDA Power Supply		
Size A	Document Number NDA	Rev 1.5
Date:	Tuesday, November 21, 2006	Sheet 28 of 58



Header-1: FPIO - Port 2, 4

Header-2: FPIO - Port 6, 8

Triple USB Connector

RJ45 1000 with Dual USB Connector

Place ESD diodes as close to the connector as possible.

**LAYOUT NOTE FOR ESD DIODES: CM1230**  
 Need to have minimum of 150mil clearance step down stencil definition around the ESD diodes CM1230 in layout too. Step down stencil area can accommodate other components. If needed, area for step down stencil definition can even be extended to cover other nearby components to avoid step down area covering the components half way, meaning, if extended step down area should cover other nearby components fully.

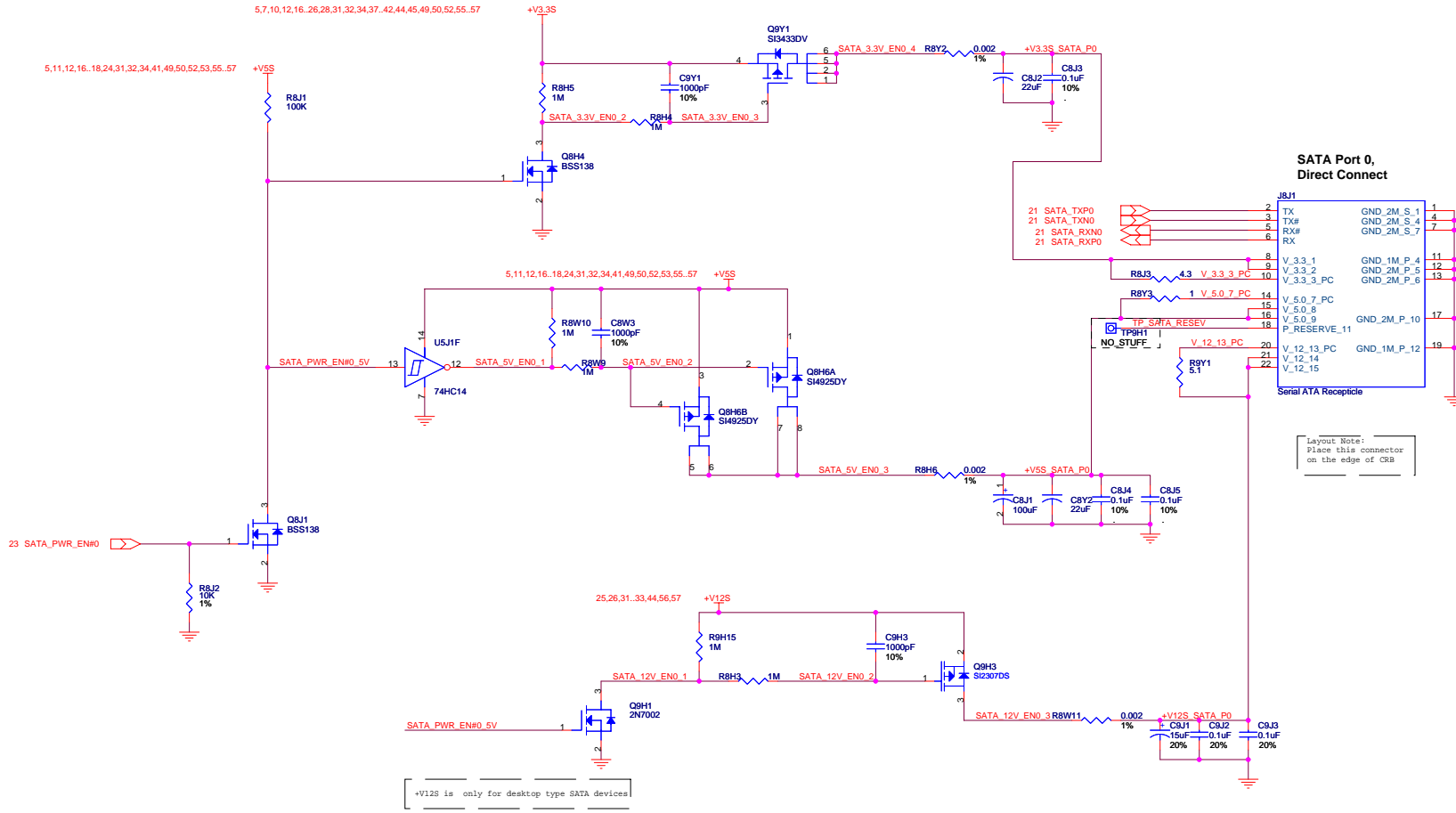
USB Port	Location
USB Port 0	Back of Chassis
USB Port 1	Back of Chassis
USB Port 2	FPIO/Duckbay
USB Port 3	Back of Chassis
USB Port 4	FPIO/Duckbay
USB Port 5	Back of Chassis
USB Port 6	FPIO/Duckbay
USB Port 7	Back of Chassis
USB Port 8	FPIO/Duckbay
USB Port 9	Docking

USB Header	USB Port	PCIe Slot
Header-1	Port 2 & Port 4	Slot 1 & Slot 2
Header-2	Port 6 & Port 8	Slot 3 & Slot 4

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<b>Title</b>			
USB 1.1/2.0			
<b>Size</b>		<b>Document Number</b>	
NDA		NDA	
<b>Date:</b>		<b>Rev</b>	
Tuesday, December 05, 2006		1.5	
<b>Sheet</b>		<b>of</b>	
29		58	

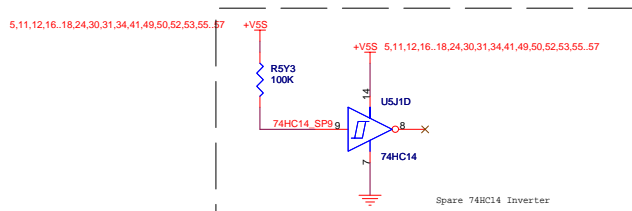
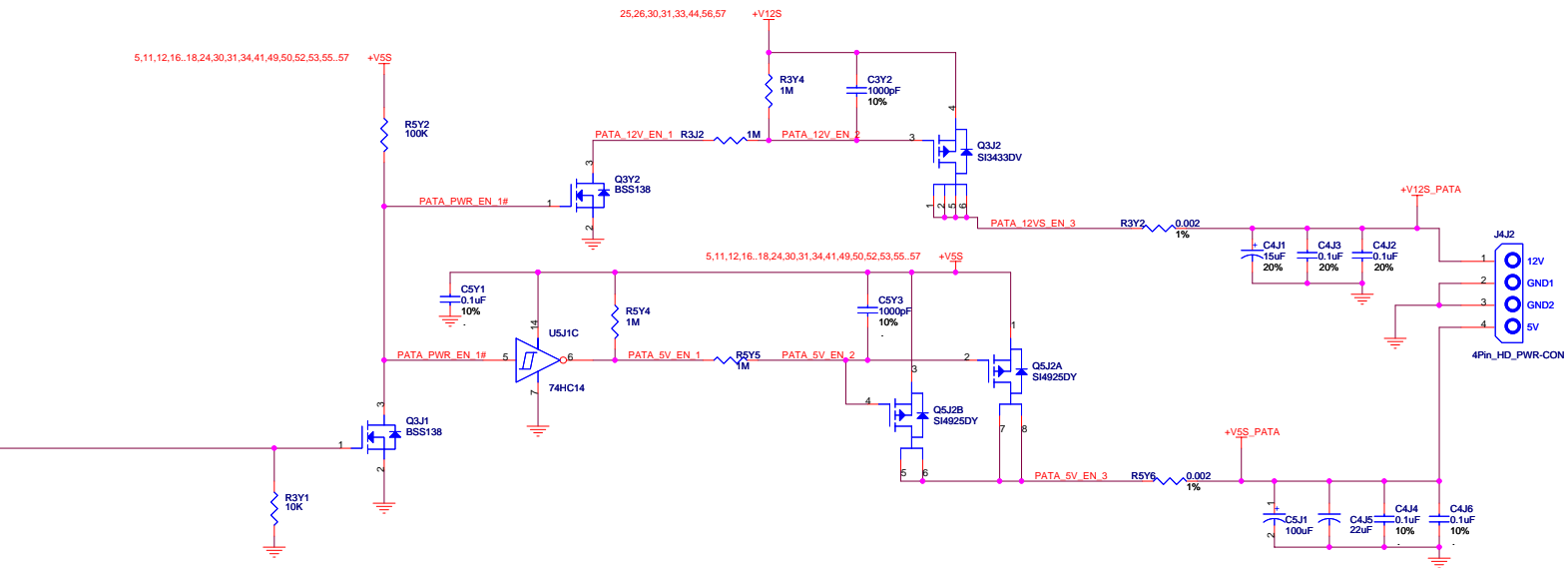
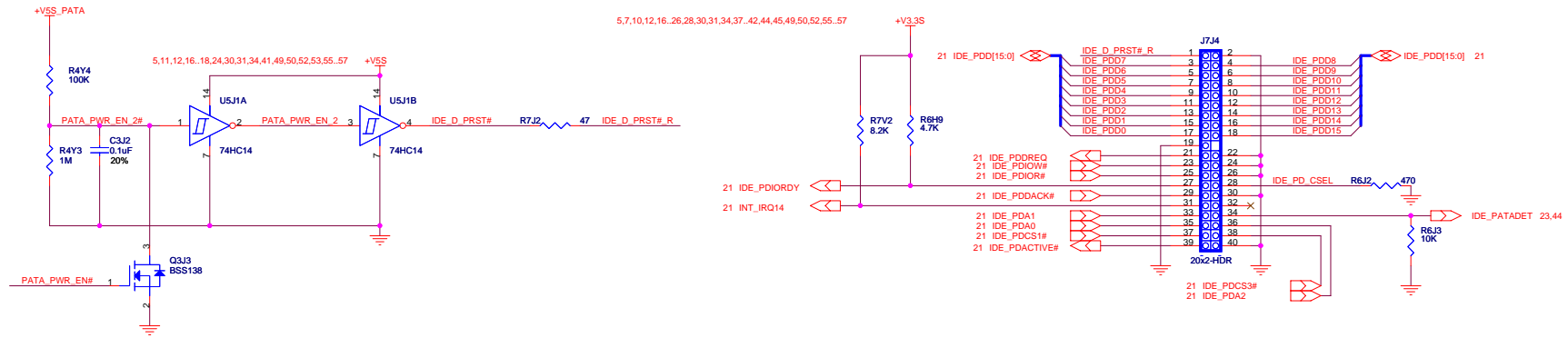


SATA Port-0, Direct Connect



<b>Matanzas</b>		Intel Confidential
Title <b>SATA (1 of 3)</b>		
Size	Document Number NDA	Rev 1.5
Date:	Tuesday, December 05, 2006	Sheet 30 of 58





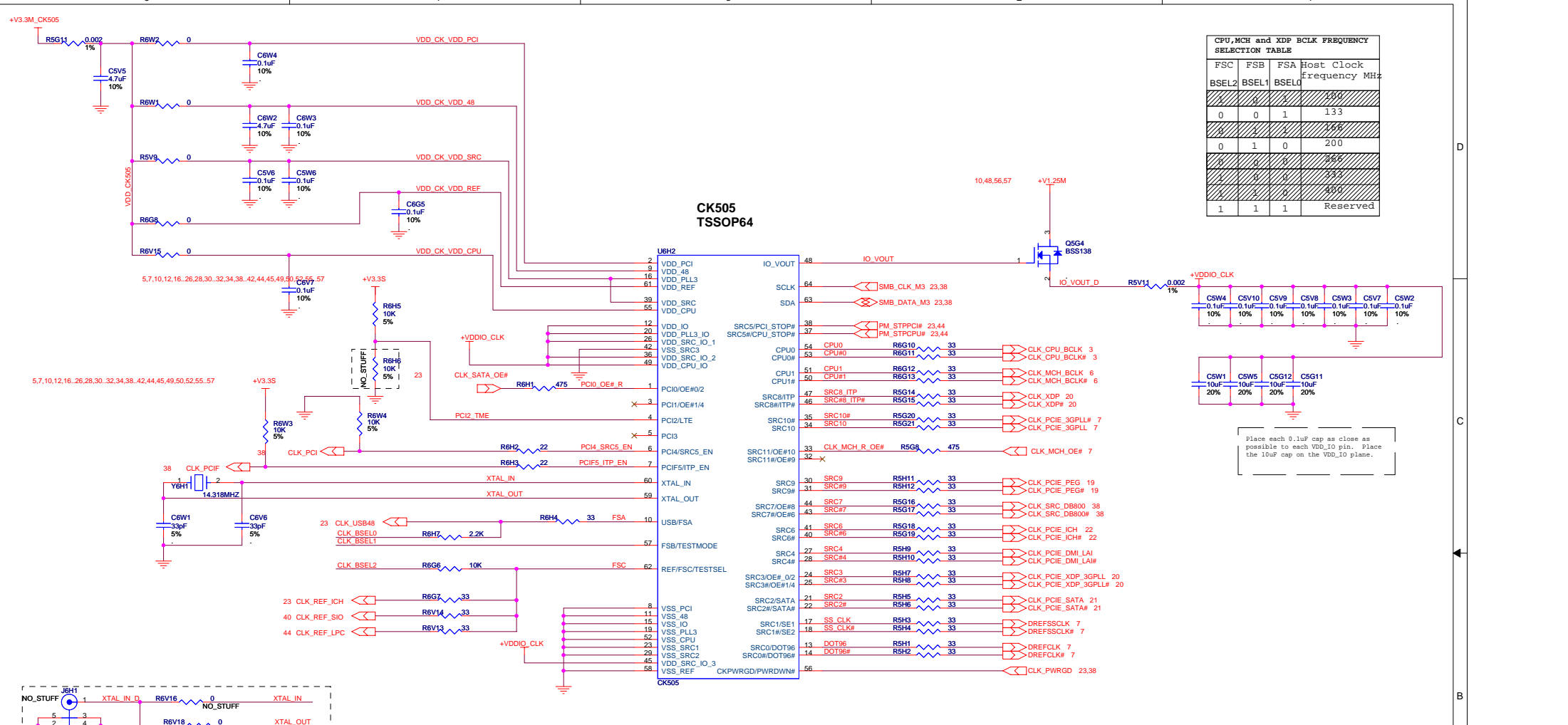
<b>Matanzas</b>		Intel Confidential
Title IDE		
Size	Document Number NDA	Rev 1.5
Date:	Tuesday, December 05, 2006	Sheet 32 of 58



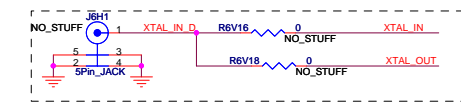




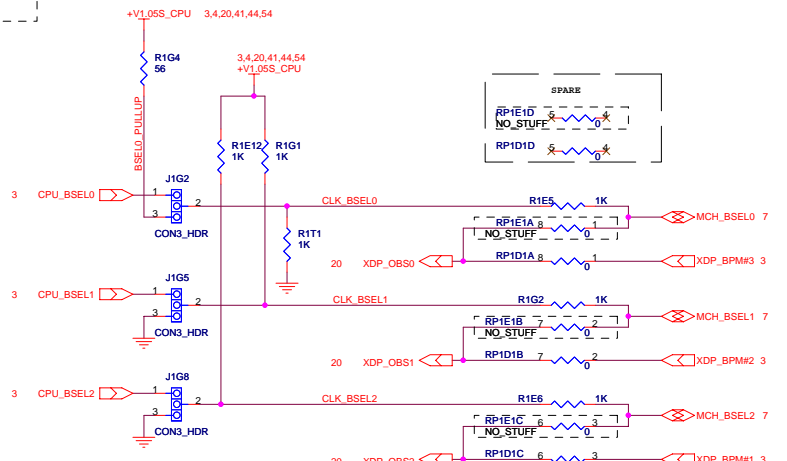




FSC	FSB	FSA	Host Clock frequency MHz
BSEL2	BSEL1	BSEL0	
0	0	1	100
0	0	1	133
0	1	1	166
0	1	0	200
1	0	0	266
1	0	1	333
1	1	0	400
1	1	1	Reserved

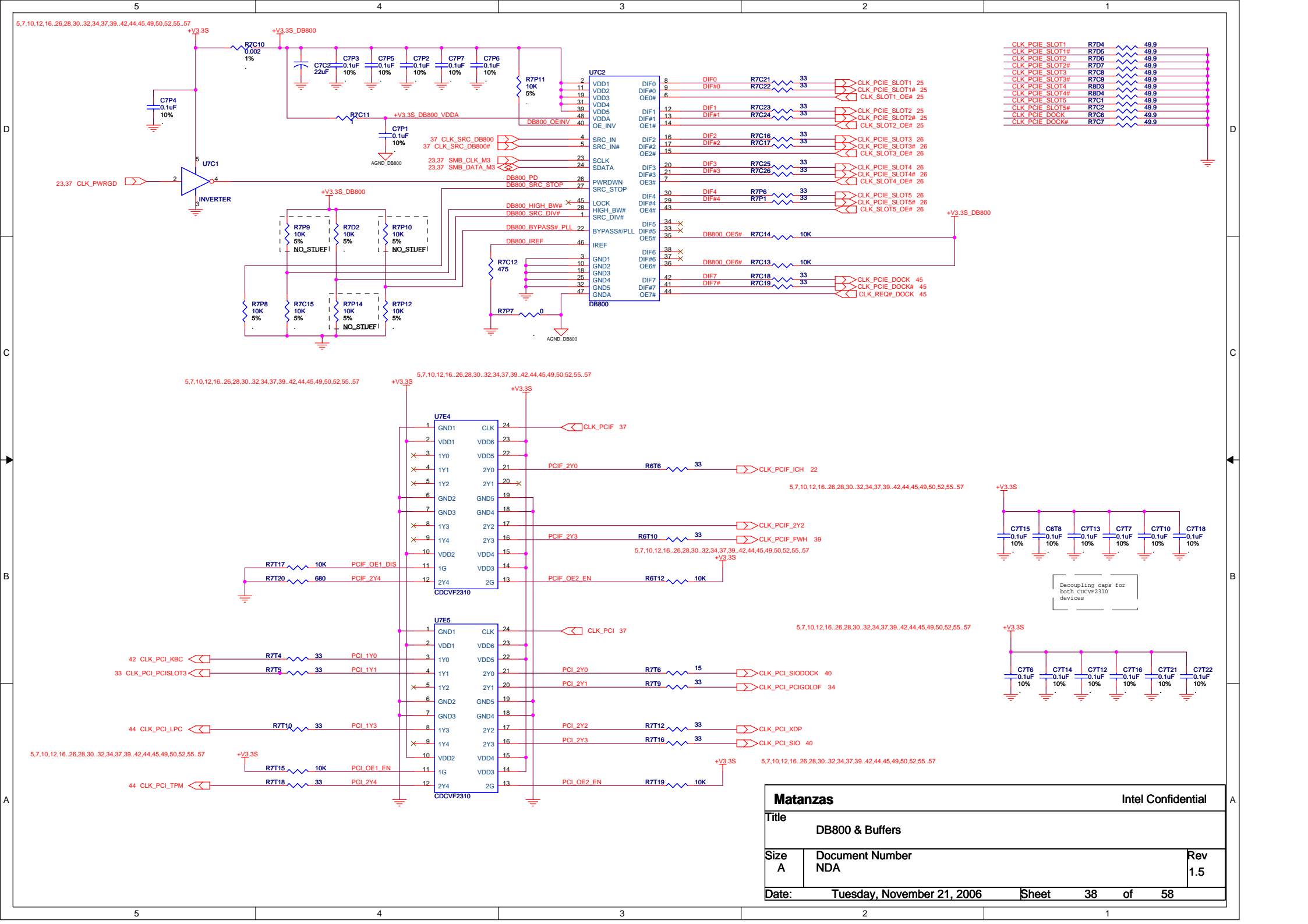


FSB Freq (MHz)	CPU Driven	J102	J105	J108	Default Settings
533	1	-	2	-	
	2	-	3	-	
	3	-	-	2	
800	Open	J102	-	-	
	Open	J105	-	-	
	2-3	-	-	J108	

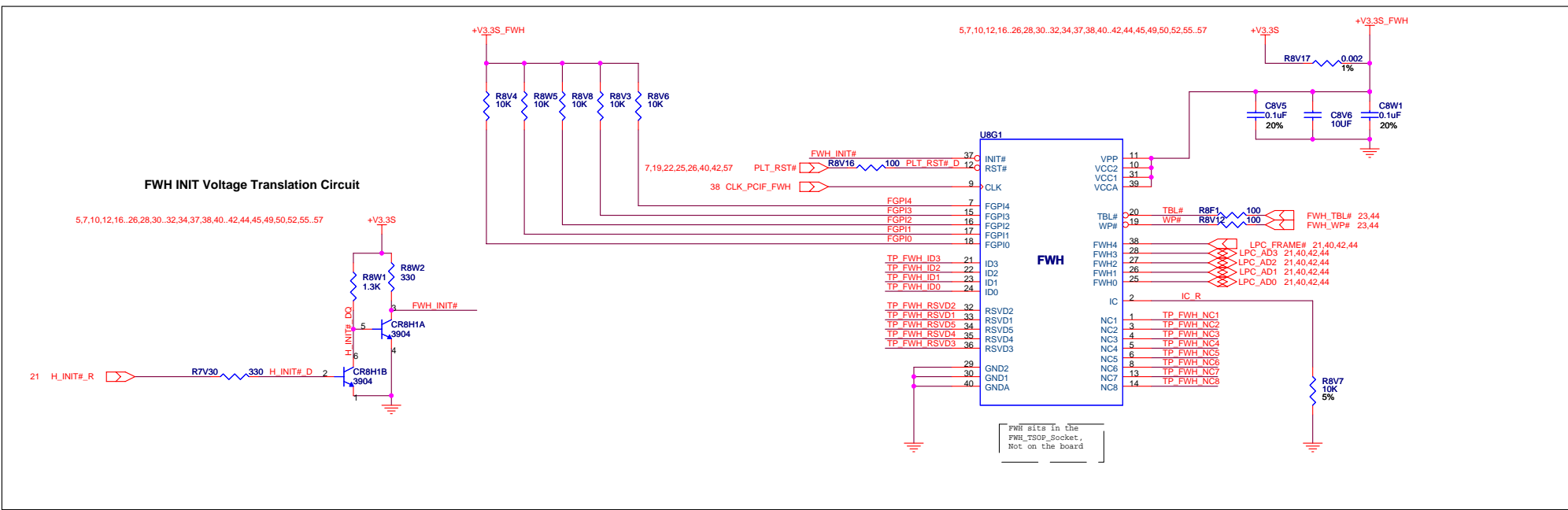


<b>Matanzas</b>		Intel Confidential
Title <b>CK505</b>		
Size Custom	Document Number NDA	Rev 1.5
Date:	Tuesday, November 21, 2006	Sheet 37 of 58



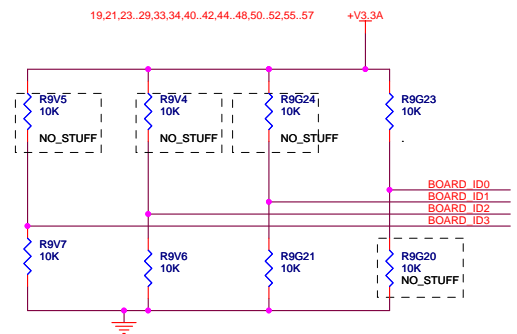


<b>Matanzas</b>		<b>Intel Confidential</b>	
<b>Title</b>			
DB800 & Buffers			
<b>Size</b>	<b>Document Number</b>		<b>Rev</b>
A	NDA		1.5
<b>Date:</b>	Tuesday, November 21, 2006	<b>Sheet</b>	38 of 58

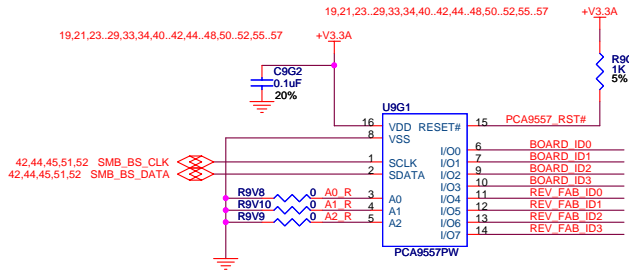
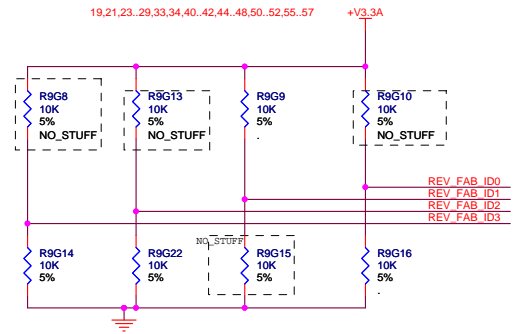


**FWH INIT Voltage Translation Circuit**

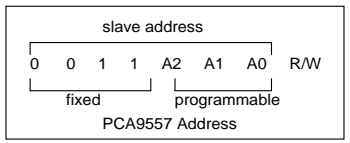
**BOARD REVISION**



**FAB REVISION**



**8-bit I/O Port Expander**



**FAB ID Strapping Table**

FAB_REV				BOARD FAB
3	2	1	0	
0	0	0	0	1
0	0	0	1	2
0	0	1	0	3
0	0	1	1	4
0	1	0	0	5
0	1	0	1	6
0	1	1	0	7
0	1	1	1	8
1	0	0	0	9
1	0	0	1	10
1	0	1	0	11
1	0	1	1	12
1	1	0	0	13
1	1	0	1	14
1	1	1	0	15
1	1	1	1	16

**BOARD REVISION Strapping Table**

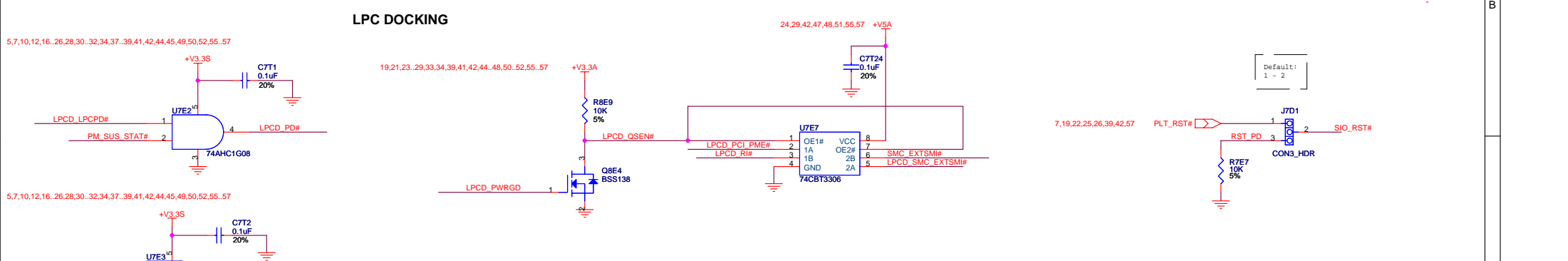
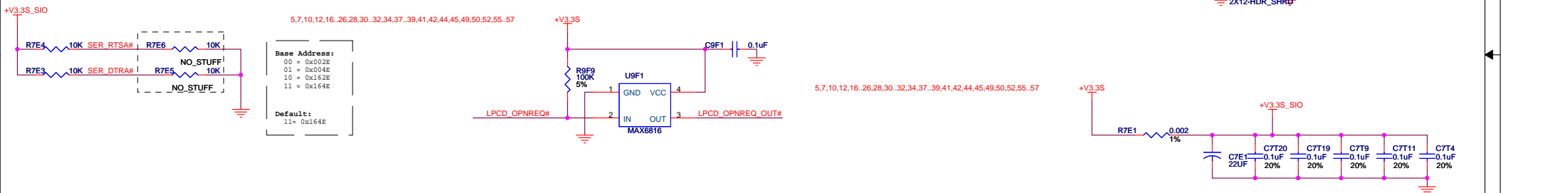
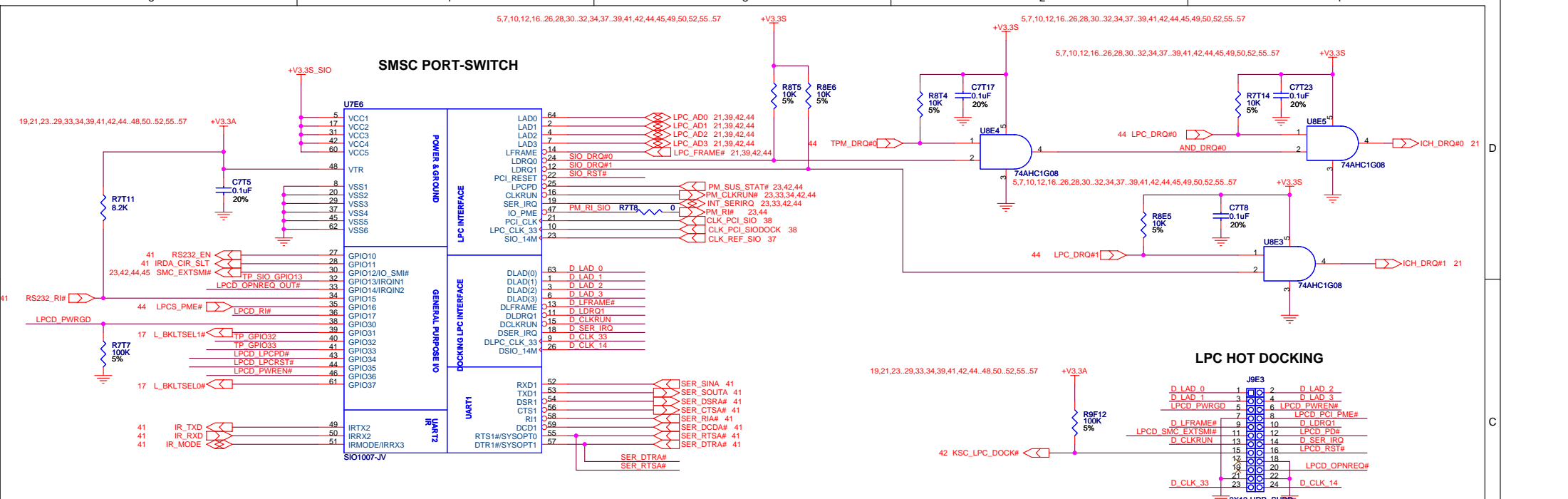
BOARD REVISION				BOARD ID
3	2	1	0	
0	0	0	1	Matanzas

**Matanzas**

**Intel Confidential**

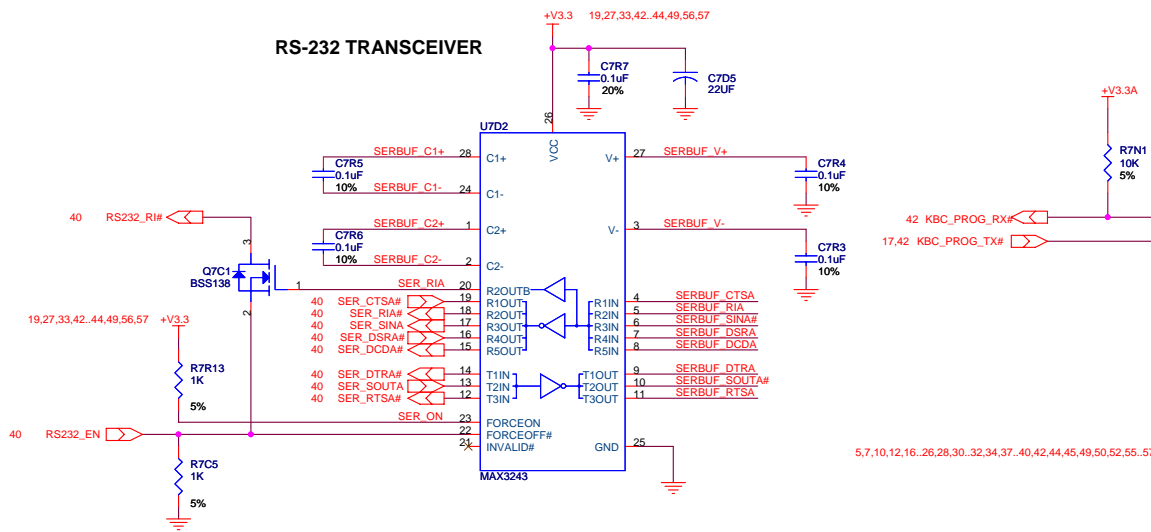
Title  
**FWH and I/O Port Expander**

Size <b>A</b>	Document Number <b>NDA</b>	Rev <b>1.5</b>
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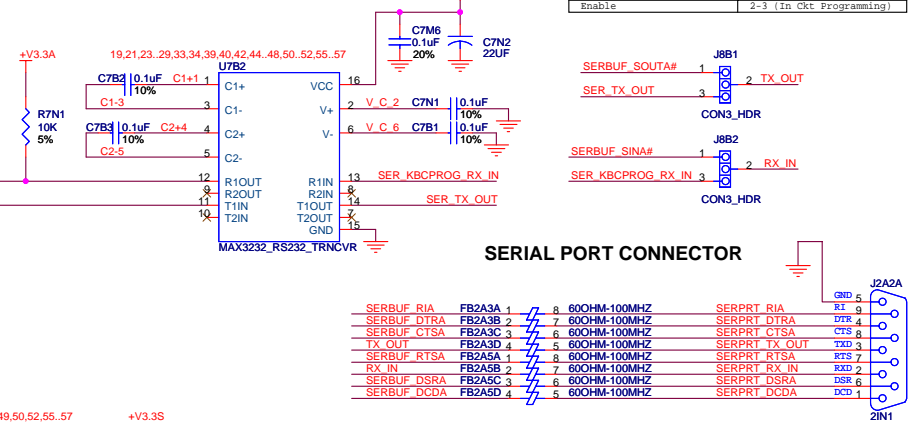


<b>Matanzas</b>		<b>Intel Confidential</b>	
Title SIO			
Size A	Document Number NDA		Rev 1.5
Date:	Tuesday, December 05, 2006	Sheet 40	of 58

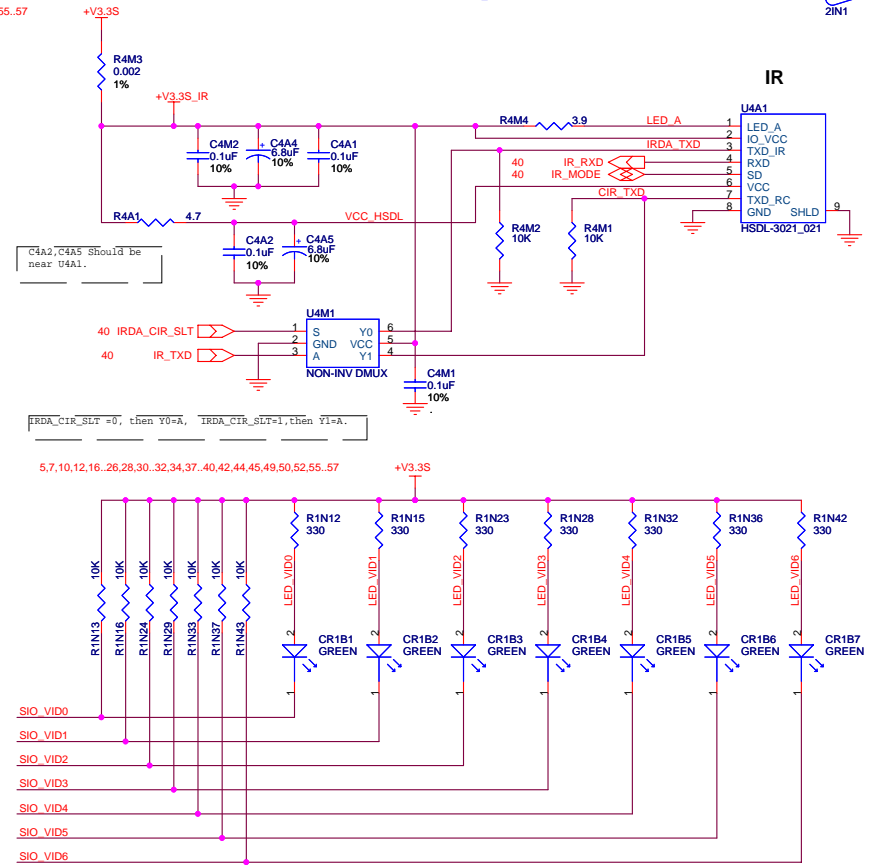
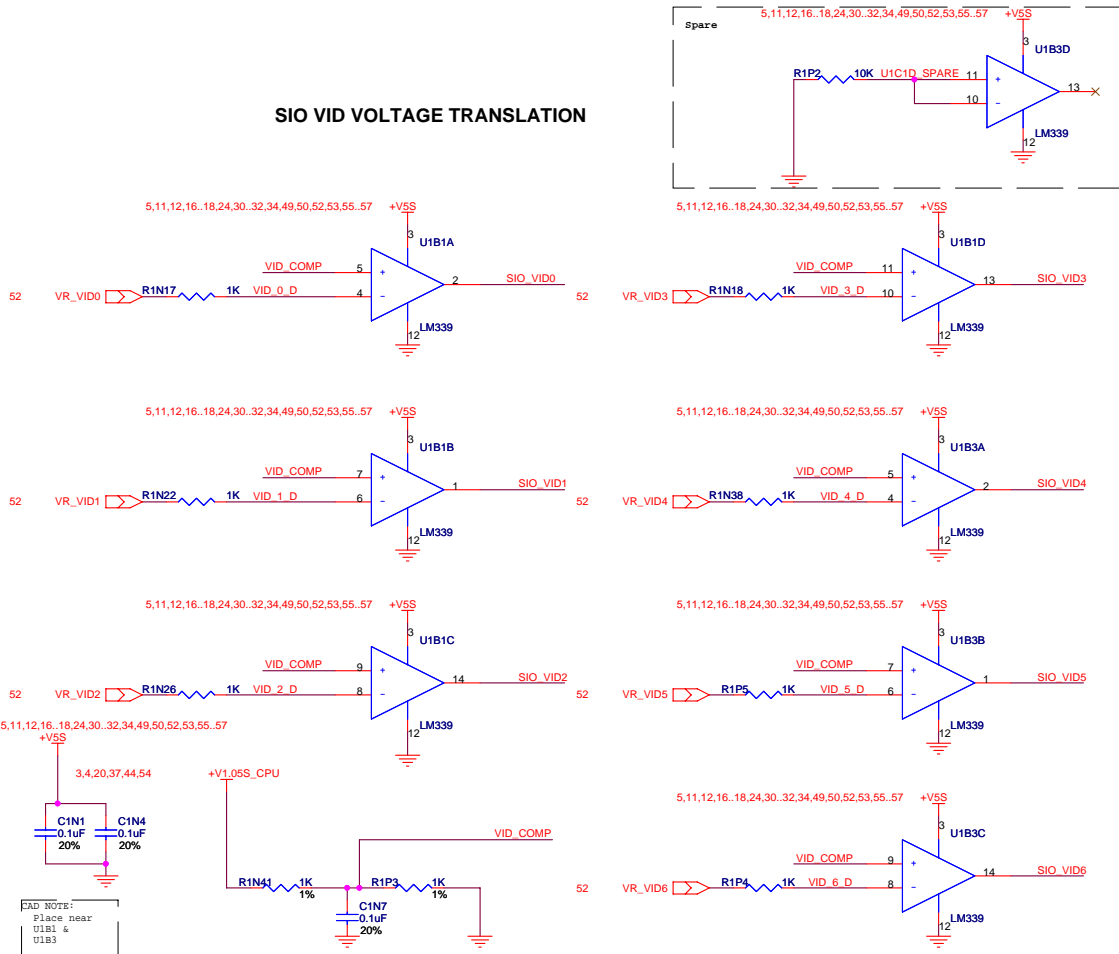
### RS-232 TRANSCEIVER



### SERIAL PORT CONNECTOR



### SIO VID VOLTAGE TRANSLATION



<b>Matanzas</b>		<b>Intel Confidential</b>	
Title: Legacy Support			
Size: A	Document Number: NDA		Rev: 1.5
Date: Tuesday, December 05, 2006	Sheet: 41	of 58	

CAD NOTE: Place C8H2 and C9V3 close to ADC AVCC pin (pin76). Route must go from power rail to caps, and then to the AVCC pin. Place C9V3 closest to the pin.

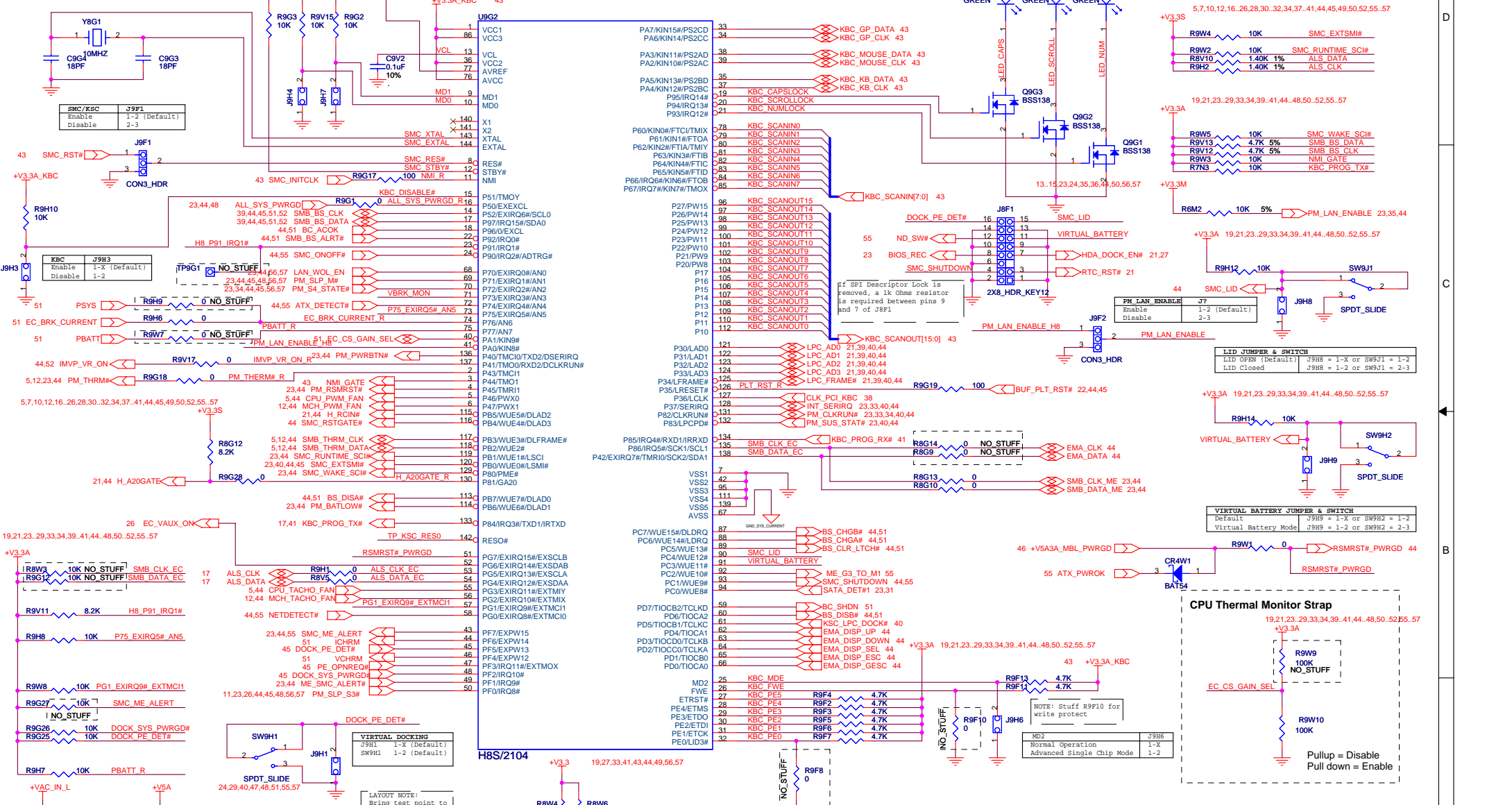
Shunt both J9H4 and J9H7 as default and as external programming

NOTE: Place C9V2 decoupling cap close to VCL pin 13

Boot Mode Programming Straps

J99-J92 needs to be at VCC for boot mode programming. They are already pulled up in the design. MD0, MD1 needs to be at Vcc. System needs to supply +V3.3A to flash connector.

Mode Type	MD0	MD1	MD2	NMI	(page 43)	(page 43)
Run Mode	0	0	1	0	X	STUFFED
Program Boot Block	0	0	1	1	STUFFED	OPEN
Program Flash	0	0	1	1	STUFFED	X



5.7,10,12,16,26,28,30,32,34,37,41,44,45,49,50,52,55,57

+V3.3S

R9W4 10K SMC\_EXTSMI#

R9W2 10K SMC\_RUNTIME\_SCI#

R9V10 1.40K 1% ALS\_DATA

R9H2 1.40K 1% ALS\_CLK

+V3.3A

R9W5 10K SMC\_WAKE\_SCI#

R9V13 4.7K 5% SMB\_BS\_DATA

R9V12 4.7K 5% SMB\_BS\_CLK

R9W3 10K NMI\_GATE

R7N3 10K KBC\_PROG\_TX#

+V3.3M

R9M2 10K 5% PM\_LAN\_ENABLE 23,35,44

+V3.3A 19,21,23,29,33,34,39,41,44,48,50,52,55,57

R9H12 10K SW9S1

SPDT\_SLIDE

PM LAN ENABLE

Enable 1-2 (Default)

Disable 2-3

+V3.3A 19,21,23,29,33,34,39,41,44,48,50,52,55,57

R9H14 10K SW9H2

VIRTUAL\_BATTERY

SPDT\_SLIDE

Virtual Battery Mode

Default J9H9 = 1-X or SW9H2 = 1-2

Virtual Battery Mode J9H9 = 1-2 or SW9H2 = 2-3

+V3.3A 19,21,23,29,33,34,39,41,44,48,50,52,55,57

R9H14 10K SW9H2

VIRTUAL\_BATTERY

SPDT\_SLIDE

Virtual Battery Mode

Default J9H9 = 1-X or SW9H2 = 1-2

Virtual Battery Mode J9H9 = 1-2 or SW9H2 = 2-3

+V3.3A 19,21,23,29,33,34,39,41,44,48,50,52,55,57

R9W9 100K NO\_STUFF

EC\_CS\_GAIN\_SEL

R9W10 100K

Pullup = Disable

Pull down = Enable

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**Title** H8 2104 KBC

**Size** A

**Document Number** NDA

**Rev** 1.5

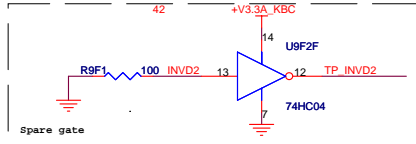
**Date:** Tuesday, December 05, 2006 **Sheet** 42 **of** 58

Circuitry provides an interrupt to the SMC every 1s while in suspend (this allows the SMC to complete housekeeping functions while suspended)

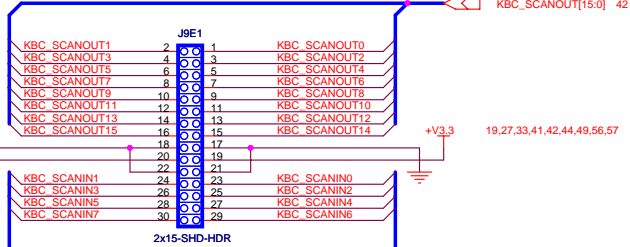
Boot Block Programming	
+V32	
Normal Program	Shunt (Default)
Program	No Shunt

1Hz Clock		J9H2
Disable	Shunt	
Enable	No Shunt (Default)	

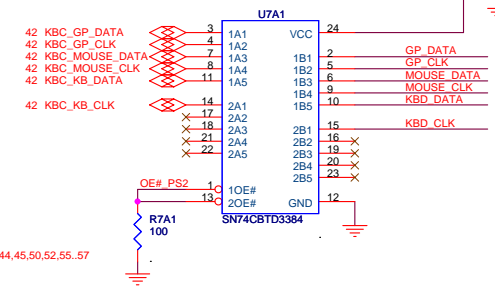
NMI Jumper  
NOTE: Shunt J9H2 for SMC Programming



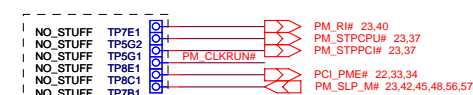
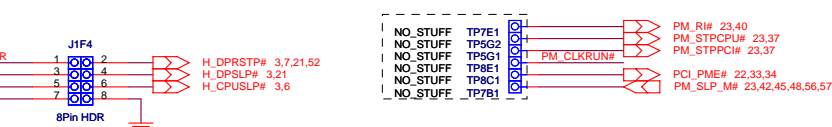
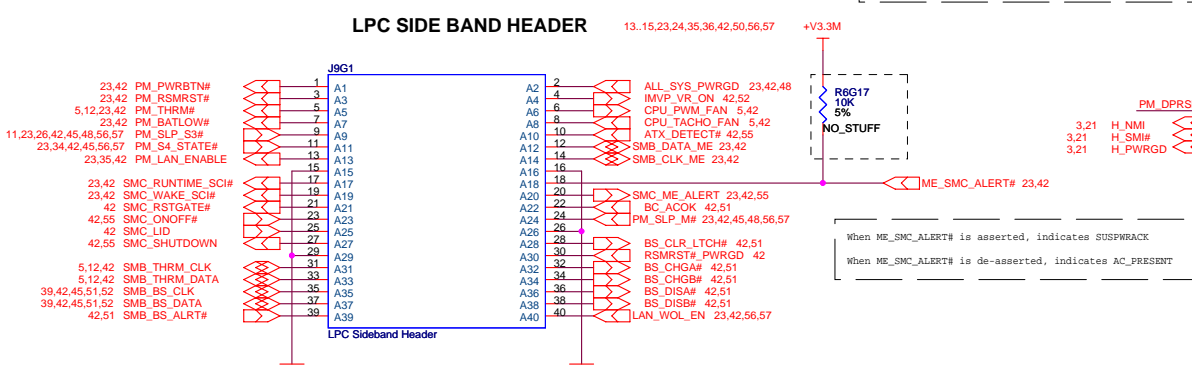
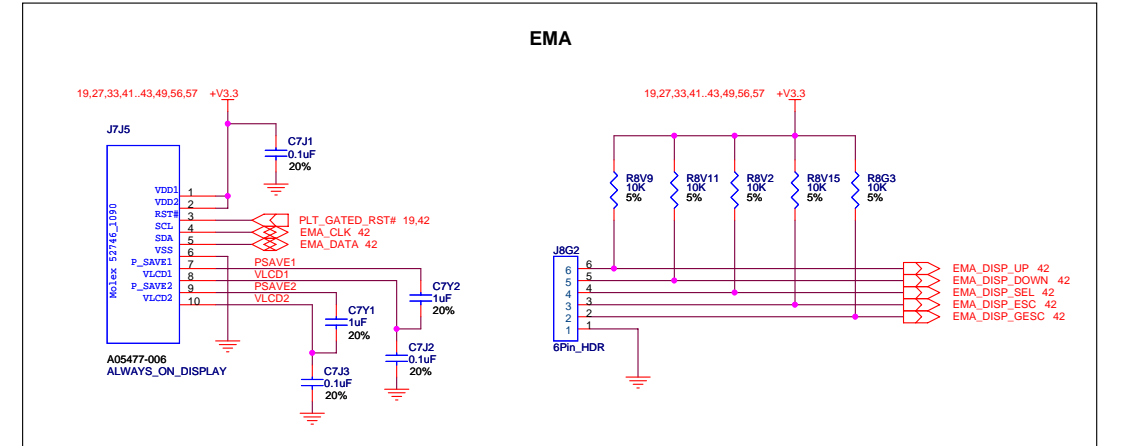
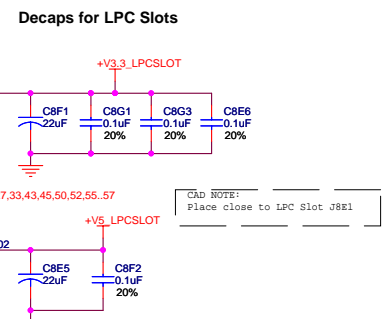
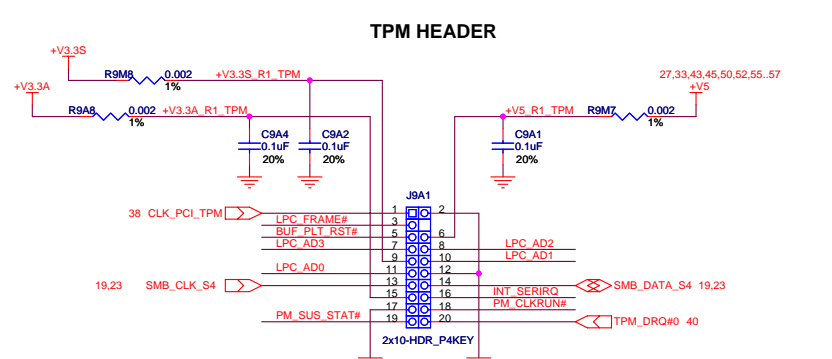
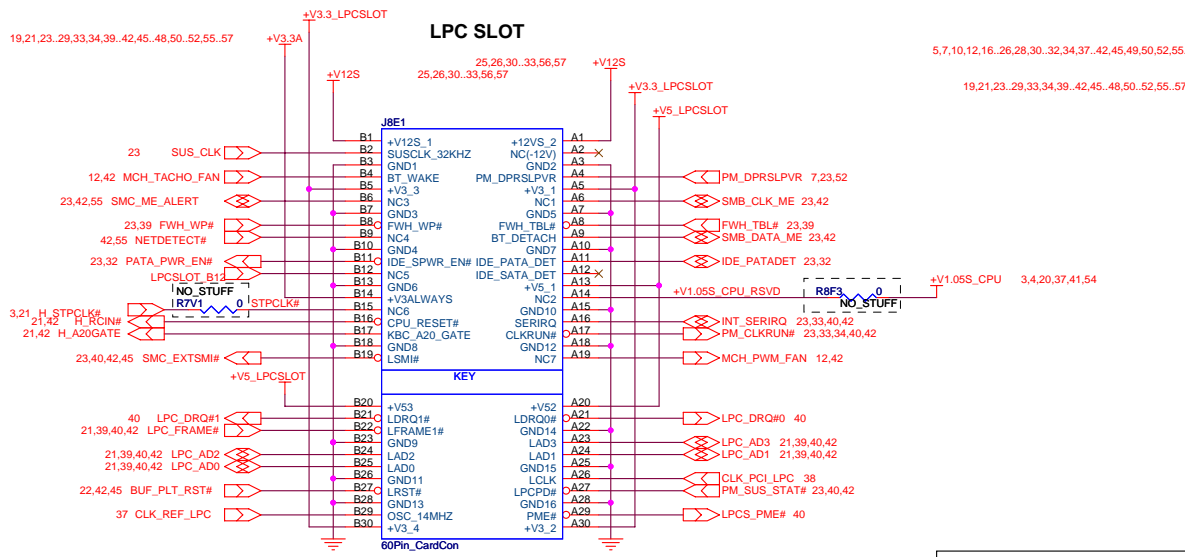
### Scan Matrix Key Board



CBTD has integrated diode for 5V to 3.3V voltage translation

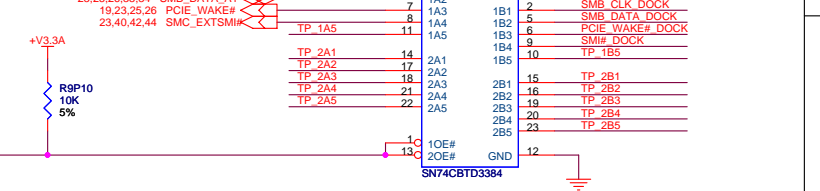
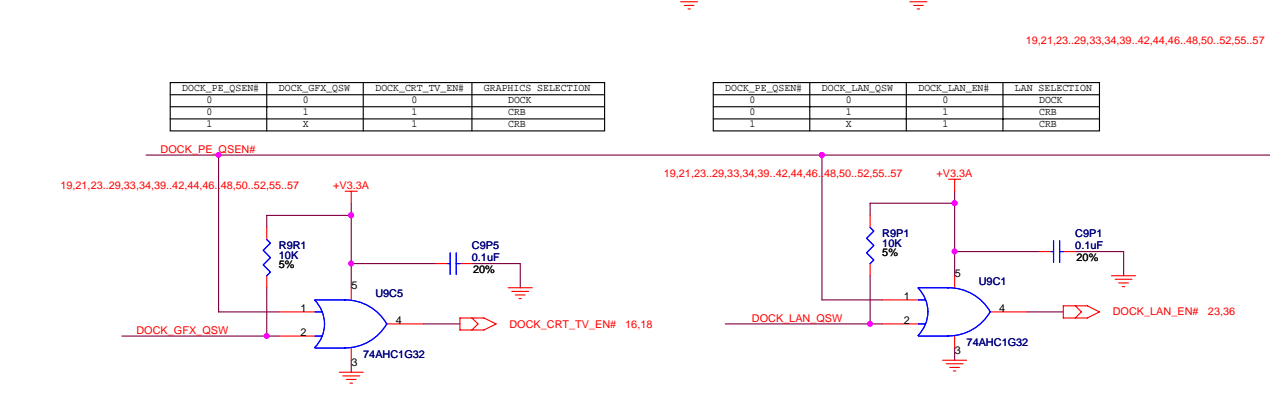
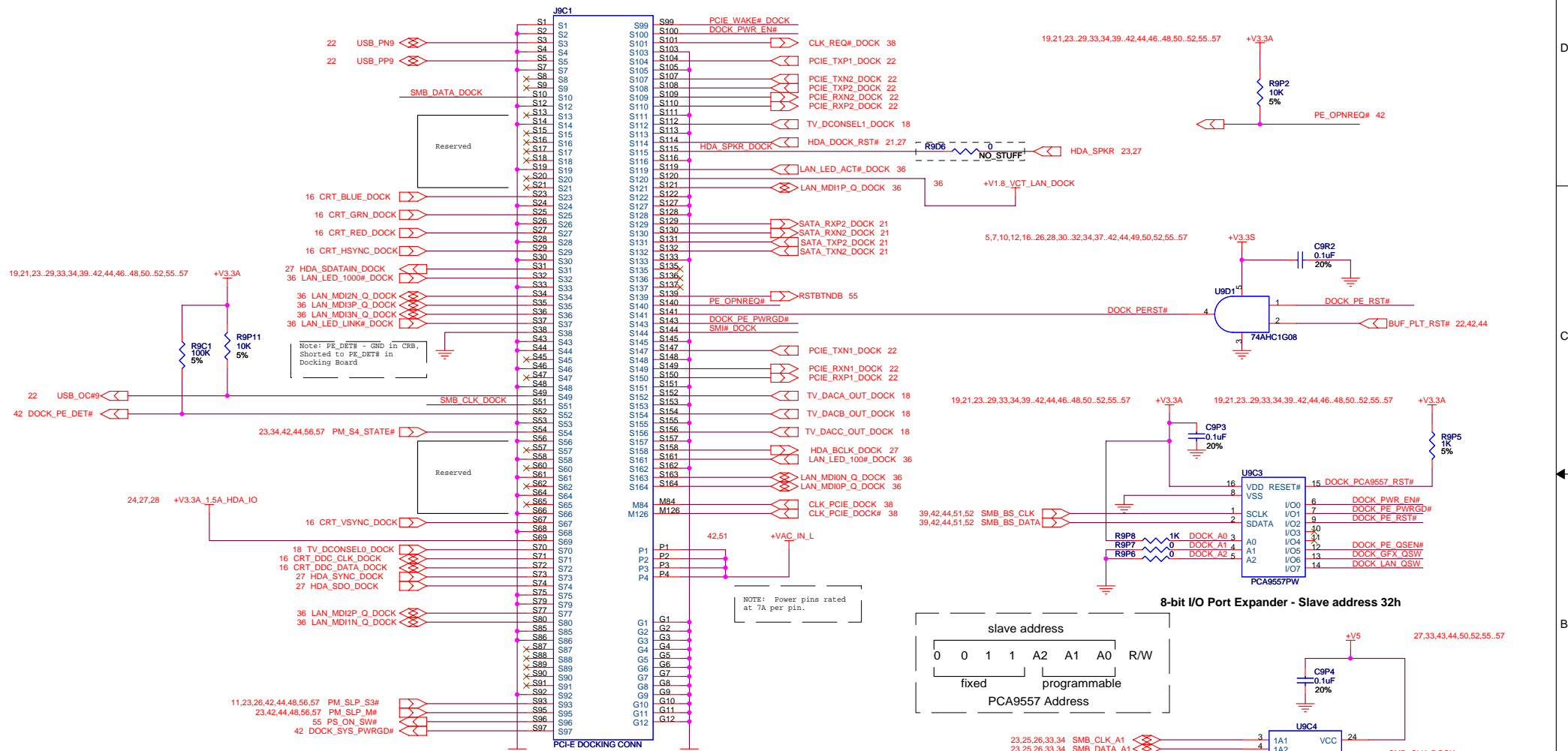


<b>Matanzas</b>		<b>Intel Confidential</b>	
Title PS2			
Size A	Document Number NDA		Rev 1.5
Date:	Tuesday, December 05, 2006	Sheet	43 of 58



<b>Matanzas</b>		<b>Intel Confidential</b>	
Title LPC Slot, TPM Header, and EMA			
Size A	Document Number NDA		Rev 1.5
Date:	Thursday, November 30, 2006	Sheet	44 of 58

# PCI-Express Docking Interface

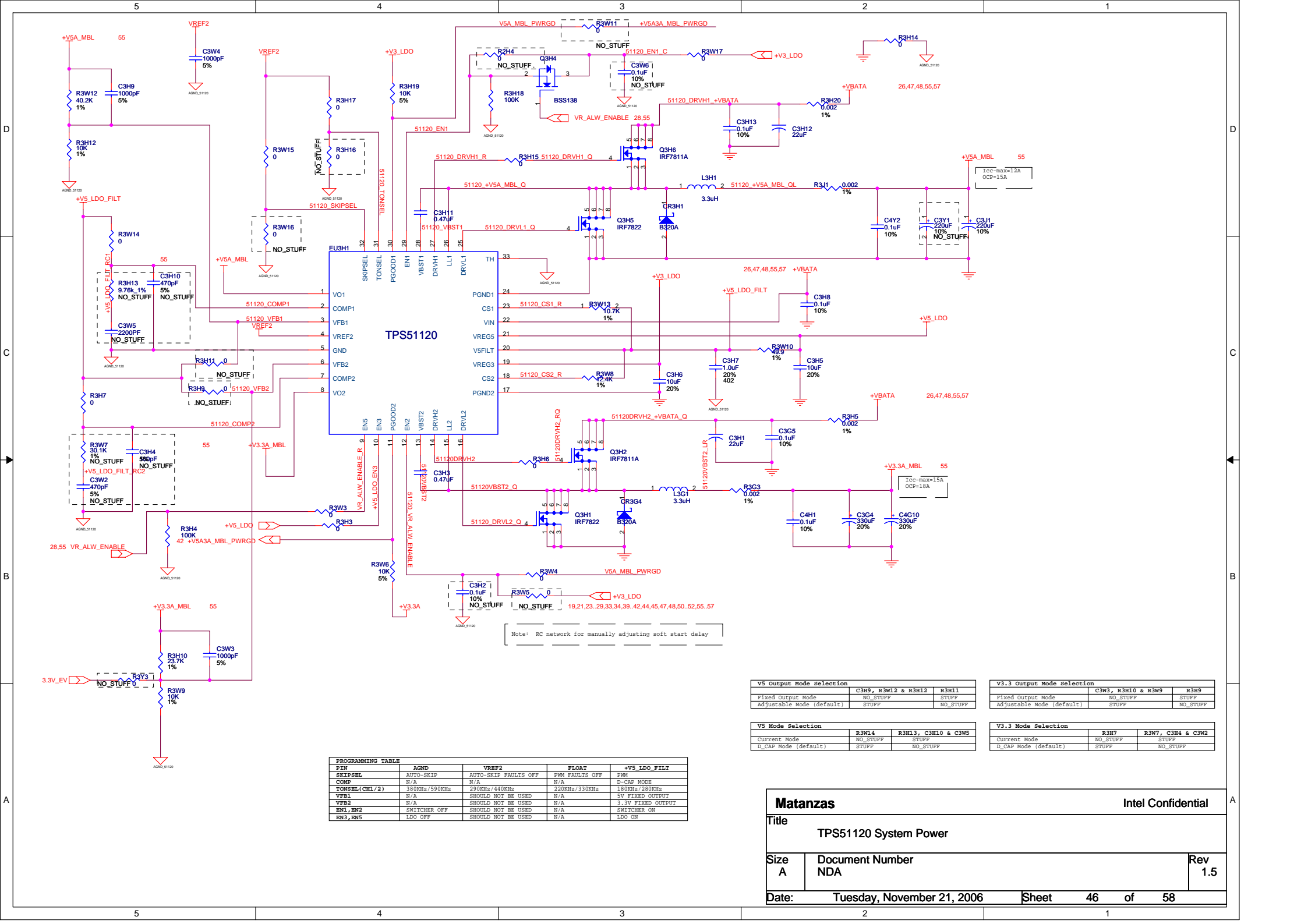


DOCK_PE_QSEN#	DOCK GFX_QSW	DOCK CRT_TV_EN#	GRAPHICS SELECTION
0	0	0	DOCK
0	1	1	CRB
1	X	1	CRB

DOCK_PE_QSEN#	DOCK_LAN_QSW	DOCK_LAN_EN#	LAN SELECTION
0	0	0	DOCK
0	1	1	CRB
1	X	1	CRB

<b>Matanzas</b>		<b>Intel Confidential</b>	
Title: <b>Docking</b>			
Size: <b>A</b>	Document Number: <b>NDA</b>		Rev: <b>1.5</b>
Date: <b>Tuesday, December 05, 2006</b>		Sheet: <b>45</b>	of <b>58</b>





PROGRAMMING TABLE	AGND	VREF2	PGOOD1	PGOOD2	PGND1	PGND2
FIN	AUTO-SKIP	AUTO-SKIP	FAULTS OFF	FAULTS OFF	PNM	PNM
SKIPSEL	N/A	N/A	N/A	N/A	D-CAP MODE	D-CAP MODE
COMP	380KHz/590KHz	290KHz/440KHz	220KHz/330KHz	180KHz/280KHz		
TONSEL(CH1/2)	N/A	SHOULD NOT BE USED	N/A	5V FIXED OUTPUT		
VFB1	N/A	SHOULD NOT BE USED	N/A	3.3V FIXED OUTPUT		
VFB2	N/A	SHOULD NOT BE USED	N/A	SWITCHER ON		
EN1, EN2	SWITCHER OFF	SHOULD NOT BE USED	N/A	SWITCHER ON		
EN3, EN5	LDO OFF	SHOULD NOT BE USED	N/A	LDO ON		

V5 Output Mode Selection			
Fixed Output Mode	C3H9, R3W12 & R3H12	R3H11	
Adjustable Mode (default)	STUFF	NO_STUFF	

V3.3 Output Mode Selection			
Fixed Output Mode	C3W3, R3H10 & R3W9	R3H9	
Adjustable Mode (default)	STUFF	NO_STUFF	

V5 Mode Selection			
Current Mode	R3W14	R3H13, C3H10 & C3W5	
D_CAP Mode (default)	NO_STUFF	STUFF	

V3.3 Mode Selection			
Current Mode	R3H7	R3W7, C3H4 & C3W2	
D_CAP Mode (default)	NO_STUFF	STUFF	

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Title: **TPS51120 System Power**

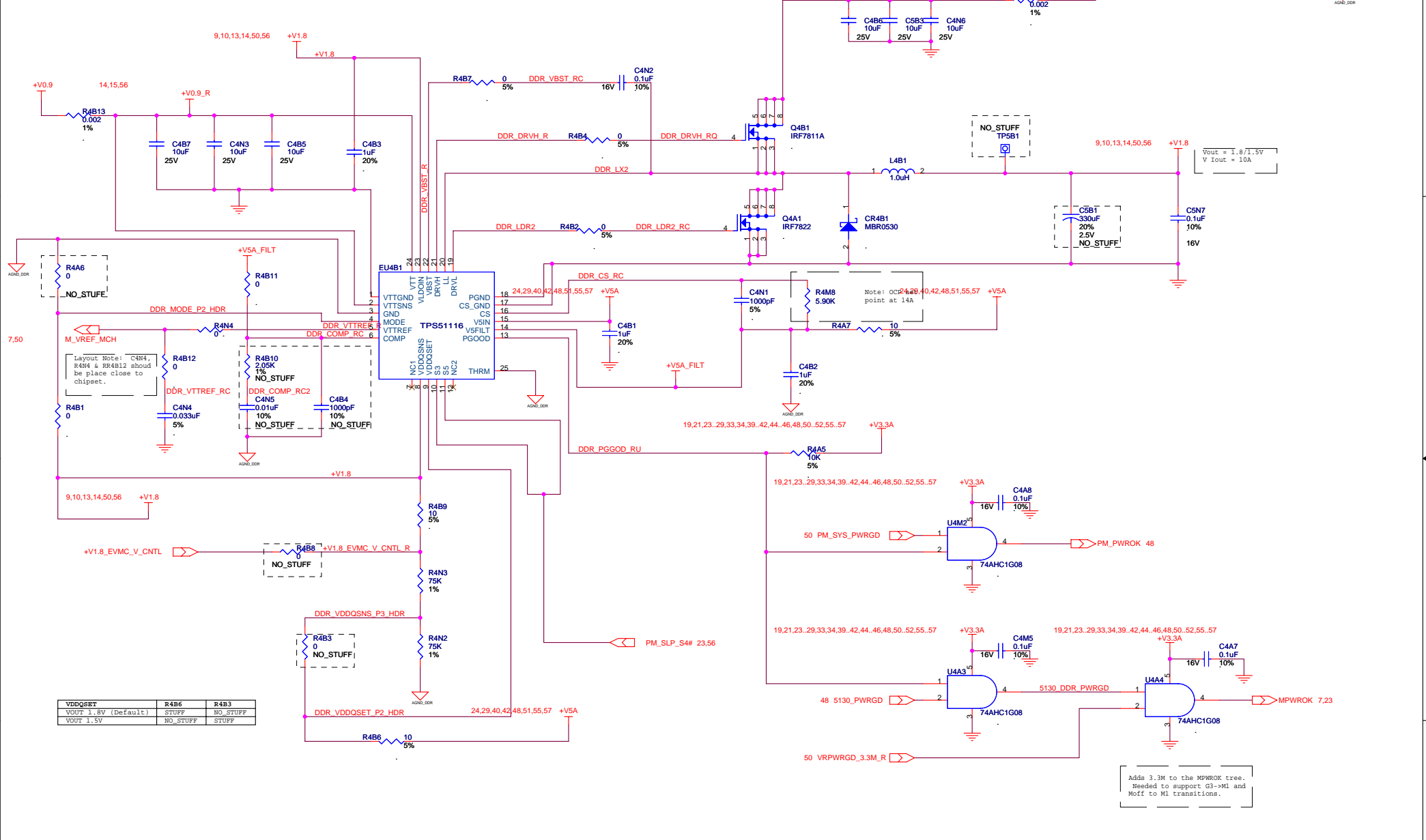
Size A	Document Number NDA	Rev 1.5
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Date: **Tuesday, November 21, 2006** Sheet **46** of **58**

Discharge Selection		
	R4B1	R4A6
Tracking Discharge (Default)	STUFF	NO_STUFF
Non-tracking Discharge	NO_STUFF	STUFF

Mode Selection		
	R4B11	R4B10, C4N5 & C4B4
Current Mode	NO_STUFF	STUFF
D_CAP Mode (default)	STUFF	NO_STUFF

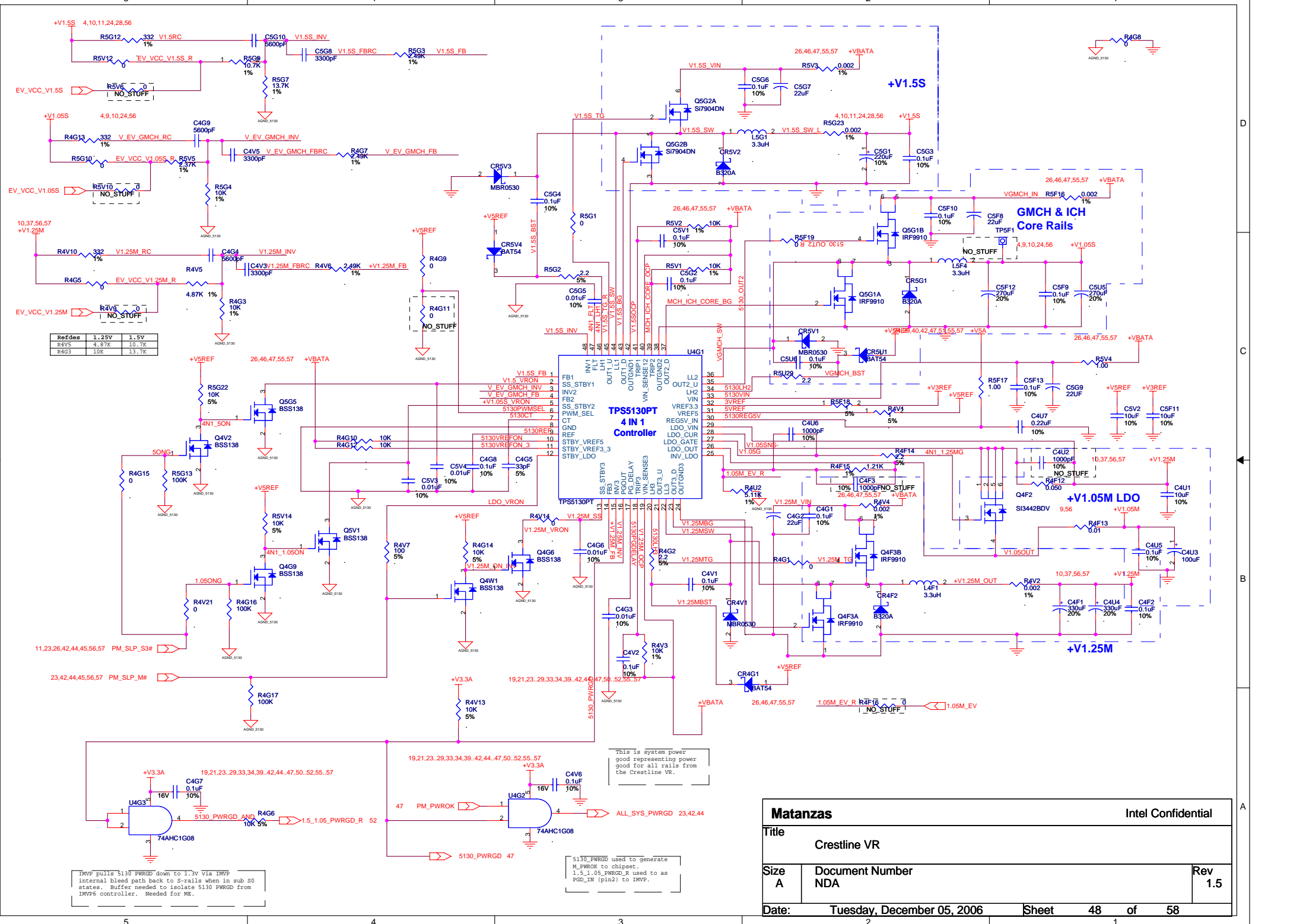
### DDR2 VREG



VDDQSET	R4B6	R4B3
VOUT 1.8V (Default)	STUFF	NO_STUFF
VOUT 1.5V	NO_STUFF	STUFF

Add 3.3M to the MPWRK tree. Needed to support G3->M1 and M0ff to M1 transitions.

<b>Matanzas</b>		<b>Intel Confidential</b>	
Title DDR2 VR			
Size A	Document Number NDA		Rev 1.5
Date:	Tuesday, December 05, 2006	Sheet	47 of 58



Refdes	1.25V	1.5V
R4V5	4.87K	10.7K
R4G3	10K	13.7K

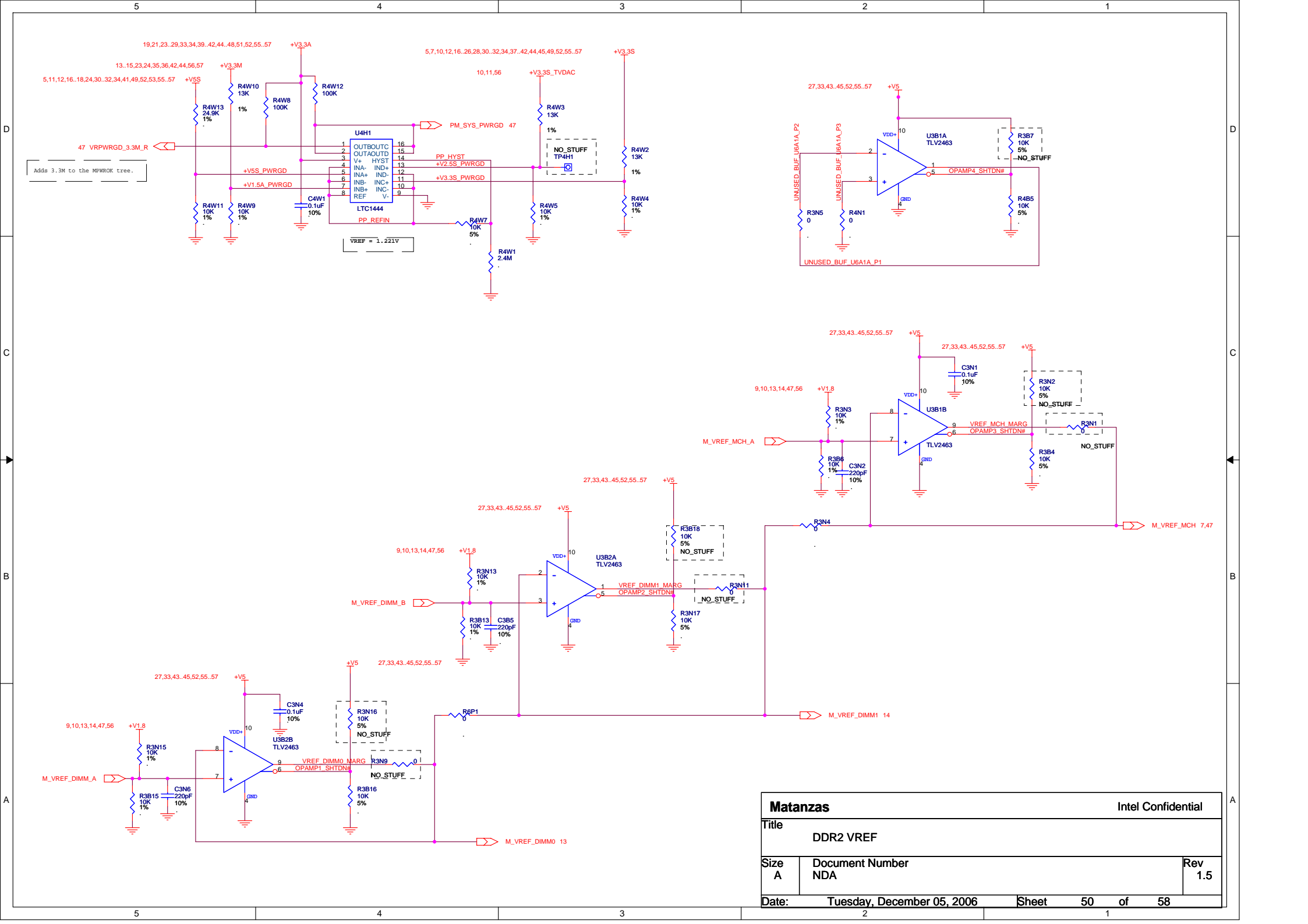
This is system power good representing power good for all rails from the Crestline VR.

IMVP pulls 5130 PWRGD down to 1.3V Via IMVP internal bleed path back to S-rails when in sub S0 states. Buffer needed to isolate 5130 PWRGD from IMVP6 controller. Needed for MB.

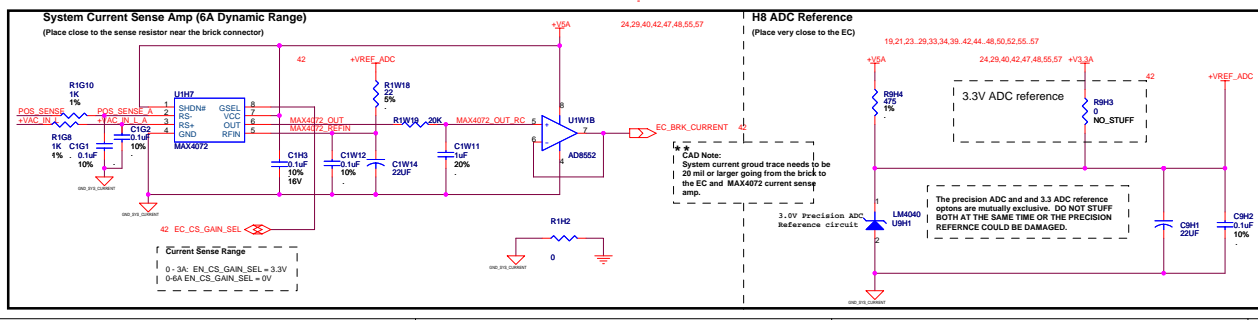
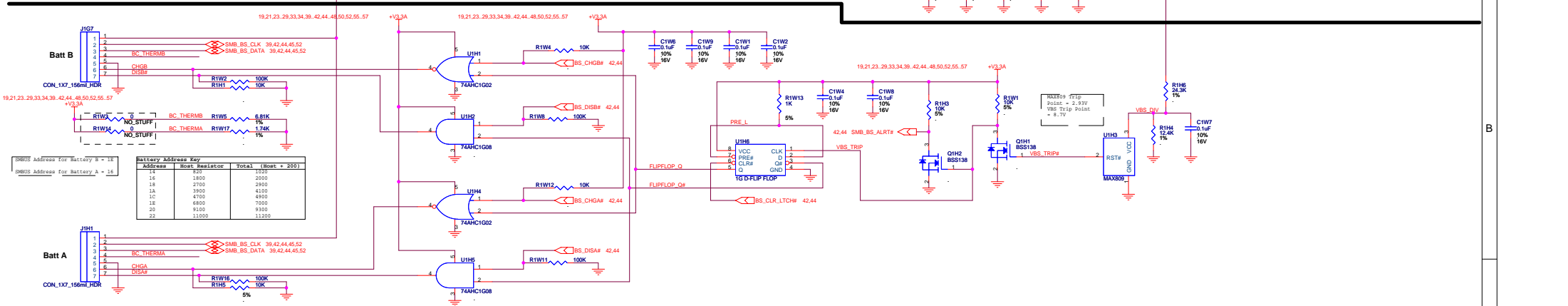
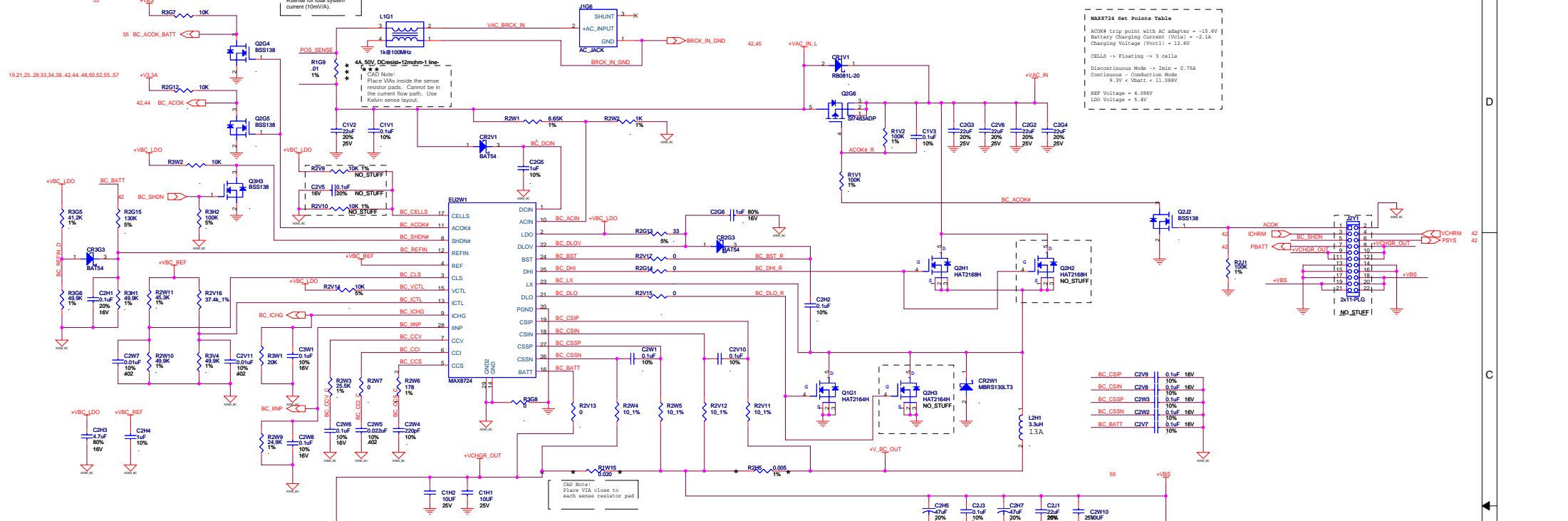
5130\_PWRGD used to generate M\_PWRGD to chipset. 1.5\_1.05\_PWRGD used as PGD\_IN (pin2) to IMVP.

<b>Matanzas</b>		<b>Intel Confidential</b>	
Title Crestline VR			
Size A	Document Number NDA	Rev 1.5	
Date:	Tuesday, December 05, 2006	Sheet	48 of 58





<b>Matanzas</b>		<b>Intel Confidential</b>	
Title DDR2 VREF			
Size A	Document Number NDA		Rev 1.5
Date:	Tuesday, December 05, 2006	Sheet	50 of 58



**Matanzas**

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Title: Crestline VR

Size A

Document Number: NDA

Rev: 1.5

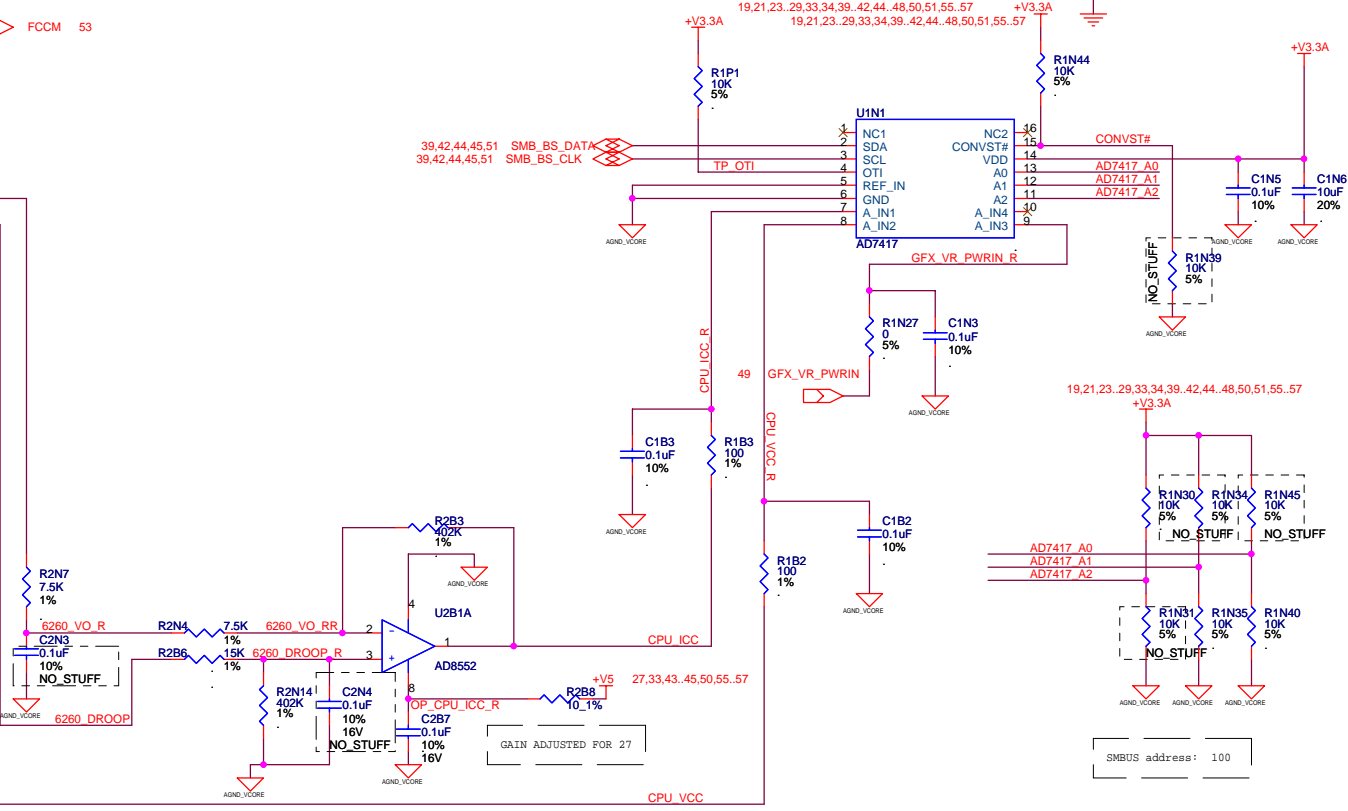
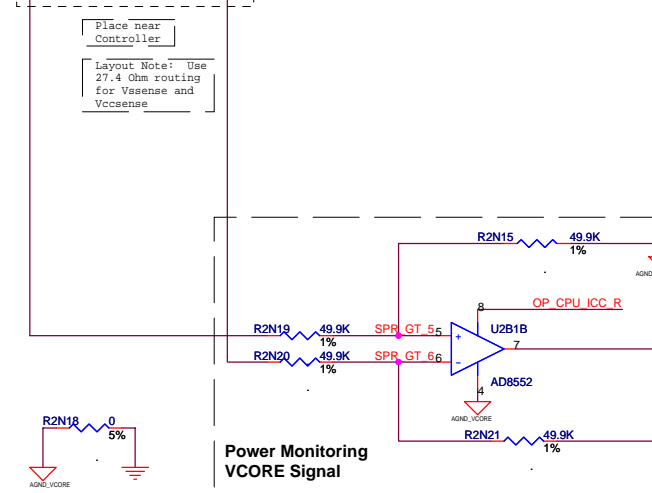
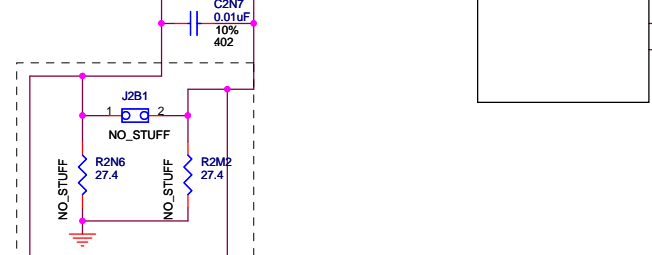
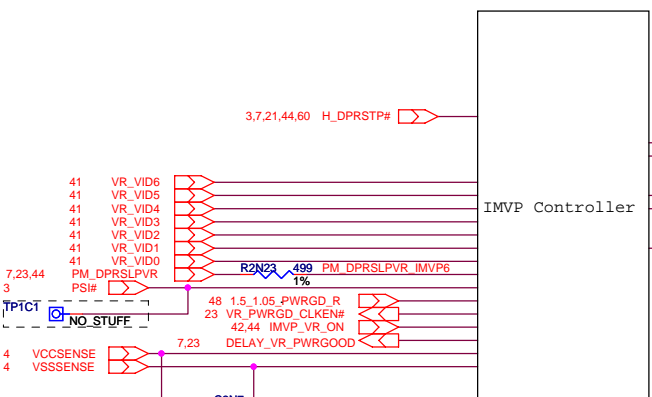
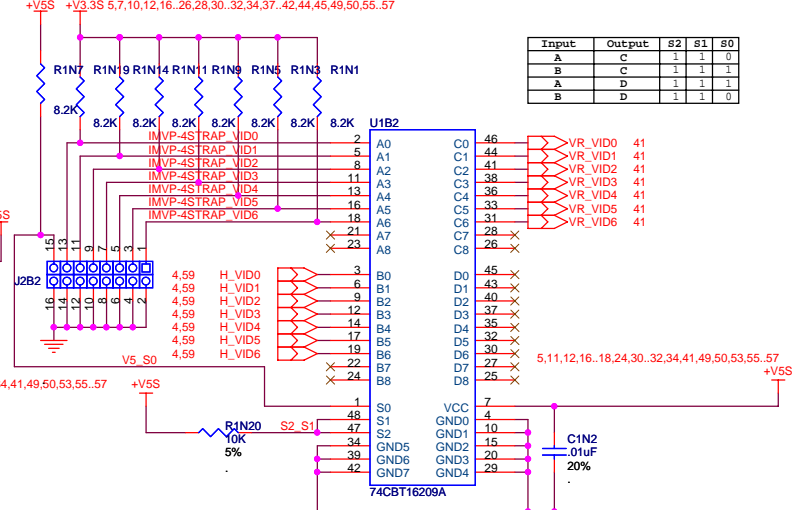
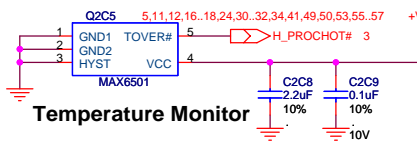
Date: Tuesday, December 05, 2006

Sheet 51 of 58

# CPU VCC\_Core VR and MUX Buffer

Input	Output	S2	S1	S0
A	C	1	1	0
B	C	1	1	1
A	D	1	1	1
B	D	1	1	0

LAYOUT NOTE:  
PLACE Q2C5 AS CLOSE TO  
Q2C4 AS POSSIBLE

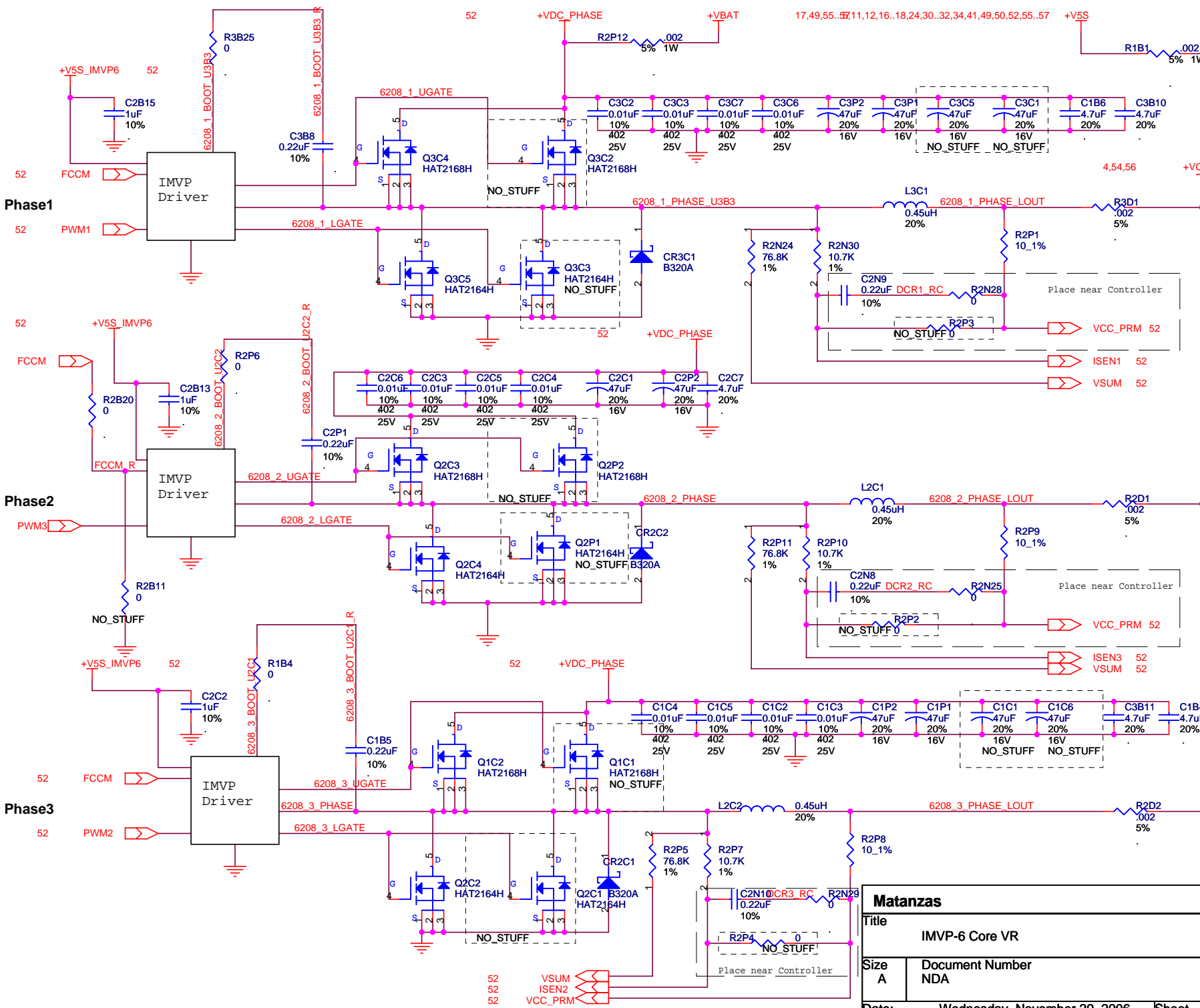


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Title: IMVP-6

Size A	Document Number NDA	Rev 1.5
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Date: Wednesday, November 29, 2006 Sheet 52 of 58



LAYOUT NOTES:

Place R2N24 & R2N30 right next to each other. Route a single trace from the input pad of the inductor and T at the resistors. --> Do not use plane flood. This applies for R2P11 & R2P10 and R2P5 & R2P7 as well.

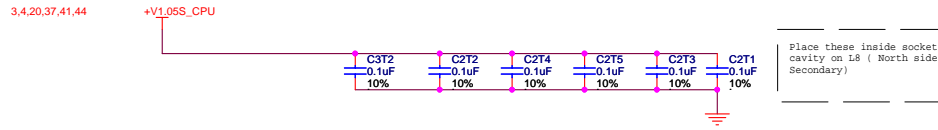
Place CR3C1 near Q3C4 and Q3C5. Route sharing the ground and switch nodes with low side FETs. This applies for CR2C1 and CR2C2 as well.

Place the 0402 caps near the drain of the high side FETs for each phase.

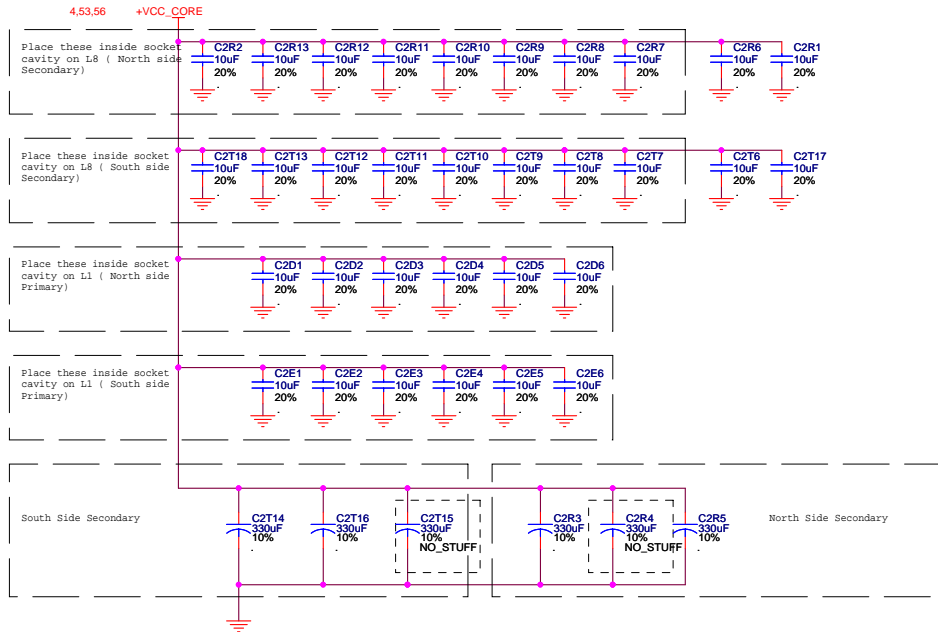
<b>Matanzas</b>		Intel Confidential	
Title IMVP-6 Core VR			
Size A	Document Number NDA		Rev 1.5
Date: Wednesday, November 29, 2006		Sheet 53	of 58

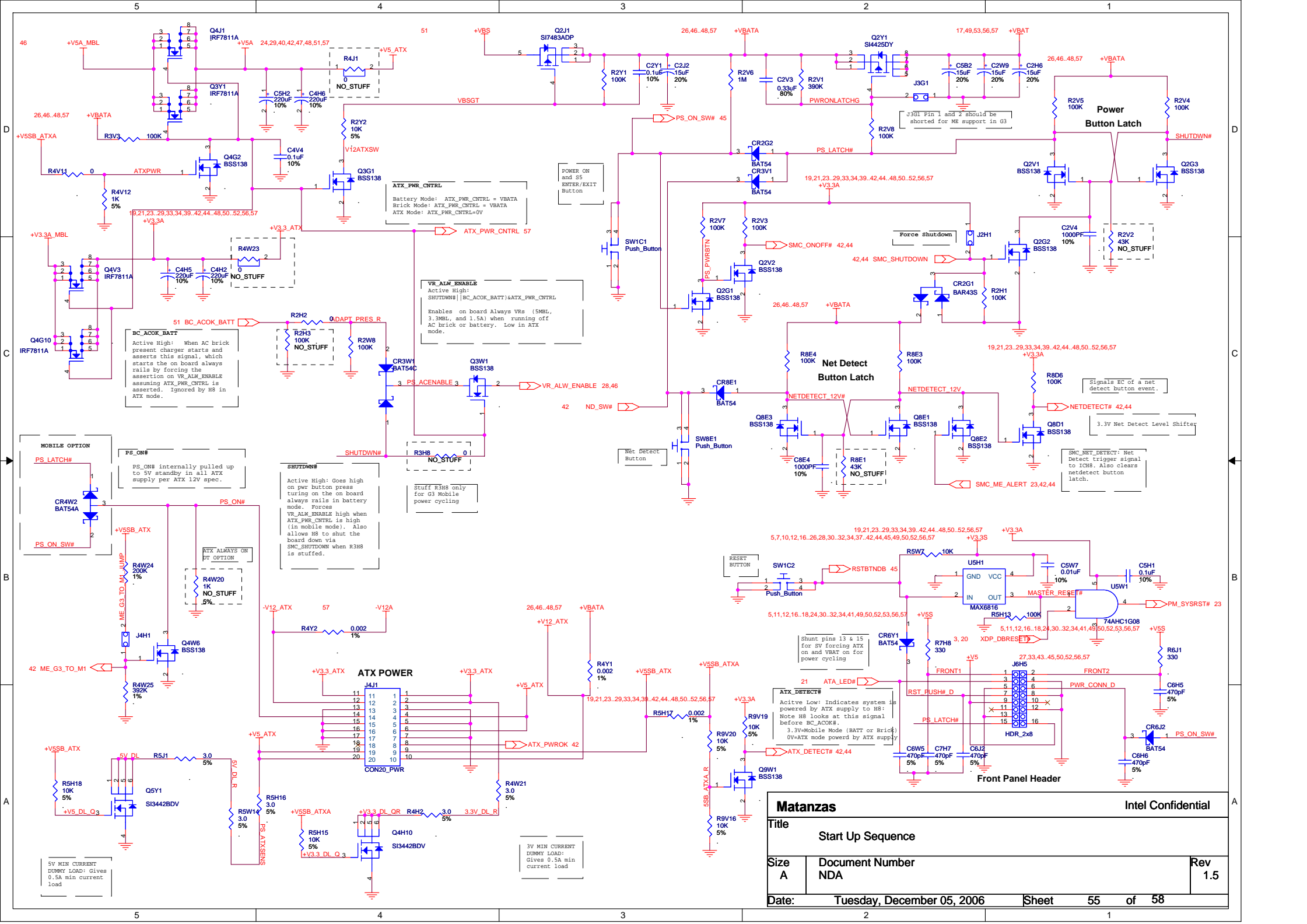


### Vccp Core Decoupling



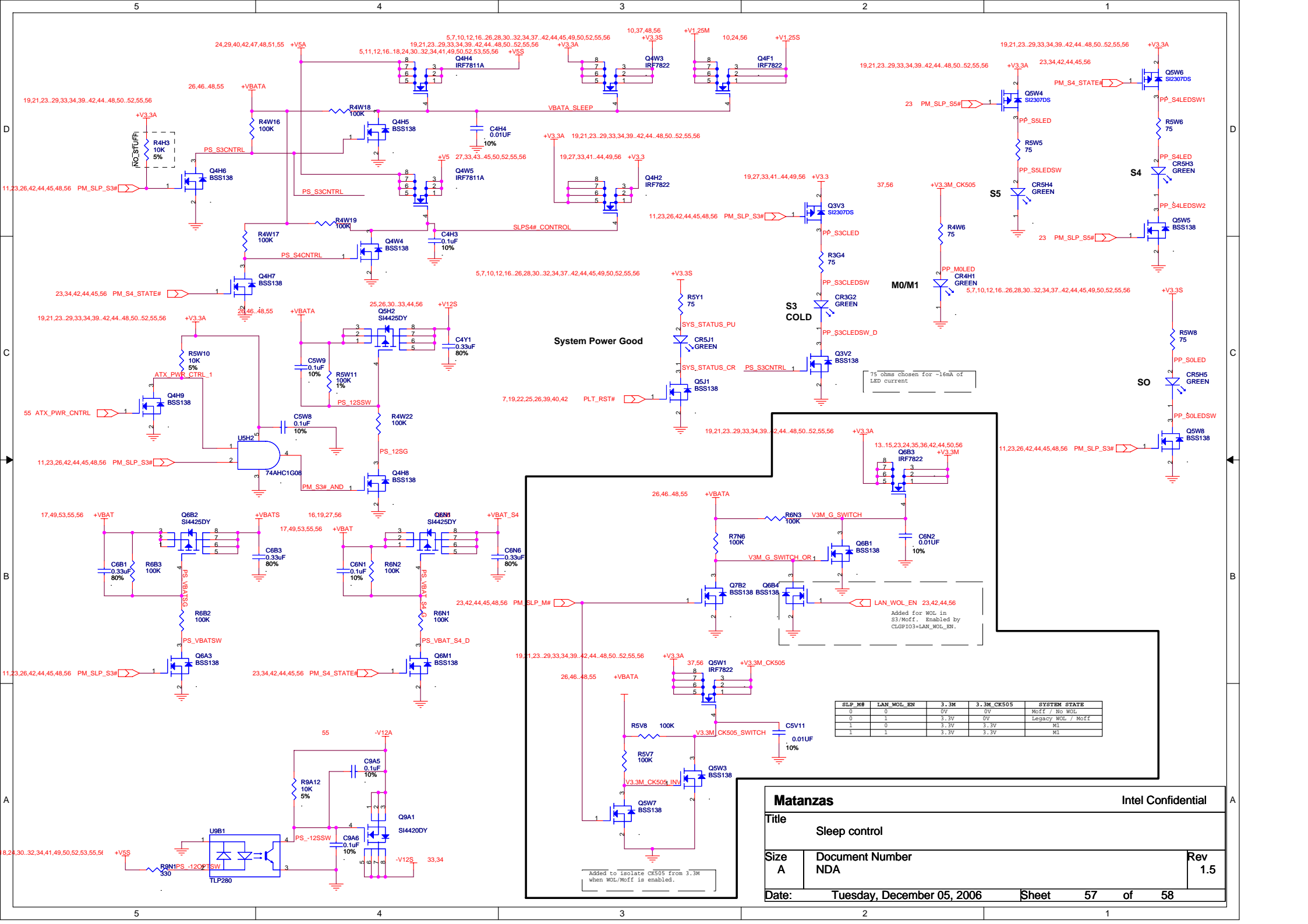
### Vcc Core Decoupling





<b>Matanzas</b>		Intel Confidential	
Title: Start Up Sequence			
Size: A	Document Number: NDA		Rev: 1.5
Date: Tuesday, December 05, 2006	Sheet: 55	of 58	





**System Power Good**

75 ohms chosen for -16mA of LED current

SLP_M#	LAN_WOL_EN	3_3M	3_3M_CK505	SYSTEM STATE
0	0	0V	0V	MoIF / No_WoL
1	1	3.3V	0V	Legacy_WoL / MoIF
1	0	3.3V	3.3V	M1
1	1	3.3V	3.3V	M1

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Title: Sleep control

Size A | Document Number: NDA | Rev 1.5

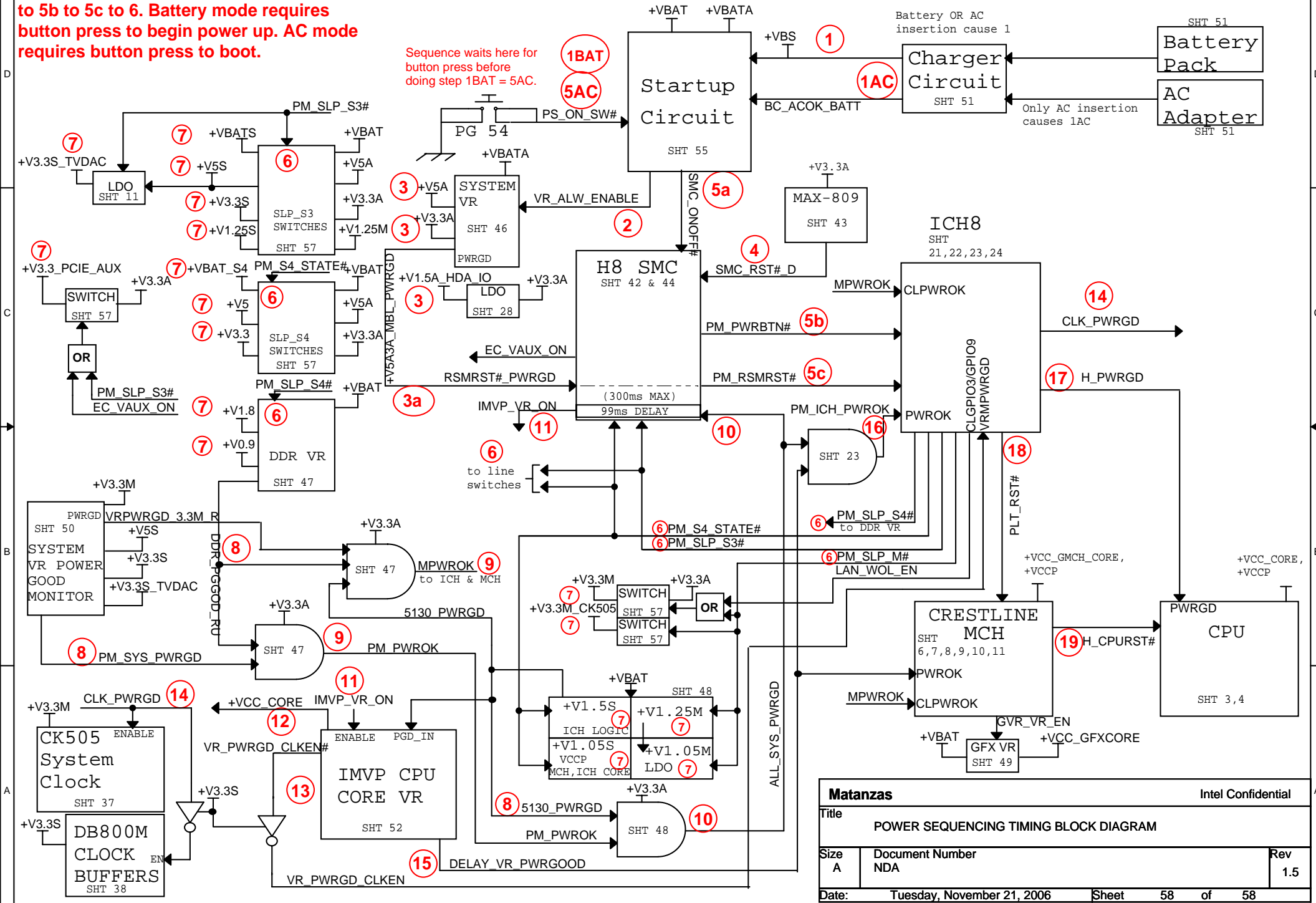
Date: Tuesday, December 05, 2006 | Sheet 57 of 58

Added to isolate CK505 from 3.3M when WoL/MoIF is enabled.

# MATANZAS Mobile Power On Sequence

Steps 1 leads to either 1BAT for battery only mode or 1AC for AC mode. 5AC leads to 5a to 5b to 5c to 6. Battery mode requires button press to begin power up. AC mode requires button press to boot.

Sequence waits here for button press before doing step 1BAT = 5AC.



<b>Matanzas</b>		Intel Confidential
Title POWER SEQUENCING TIMING BLOCK DIAGRAM		
Size A	Document Number NDA	Rev 1.5
Date: Tuesday, November 21, 2006	Sheet 58	of 58